

Strongbow_KL
Schematics Document

DY : None Installed
UMA: UMA only installed
DIS: DISCRTE OPTIMUS installed

<Core Design>

緯創資通

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Title

Cover Page

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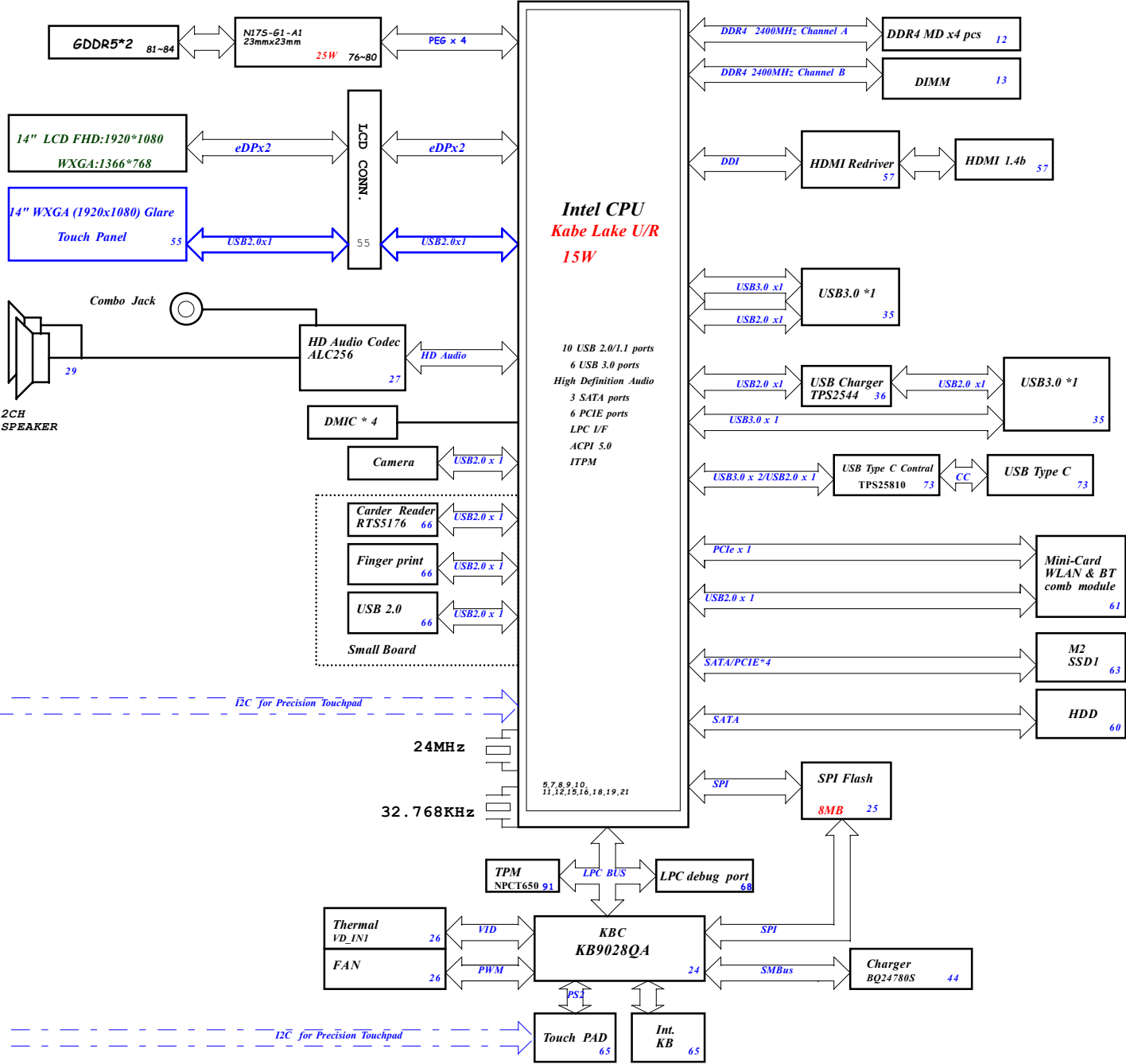
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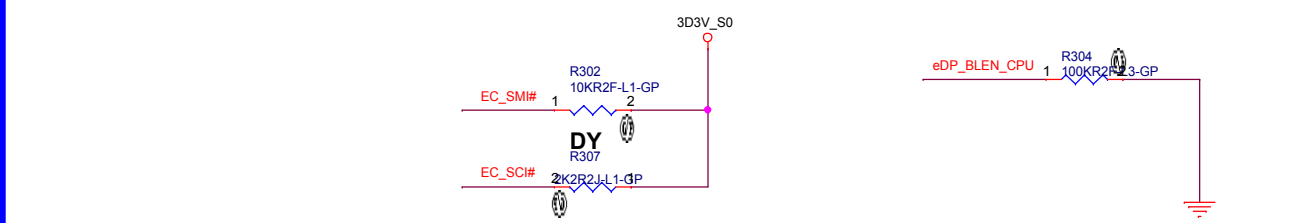
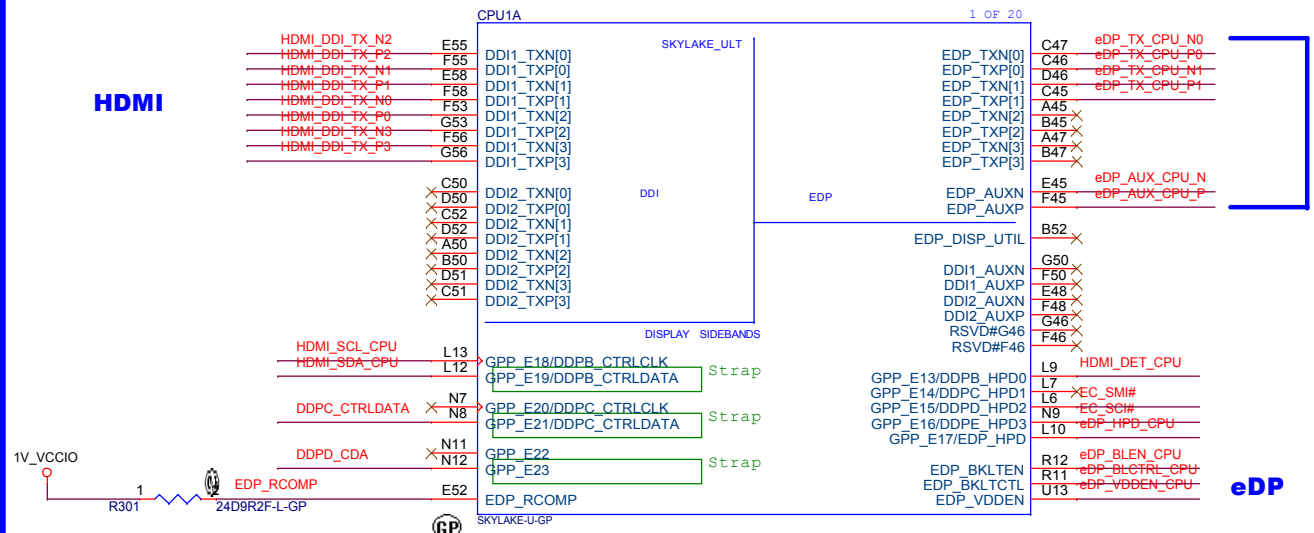
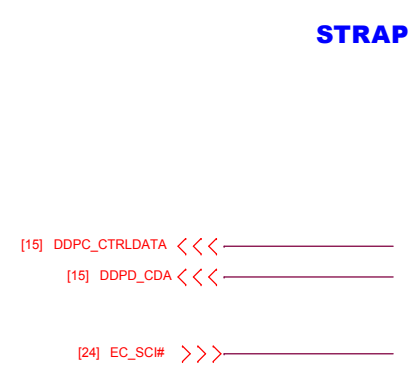
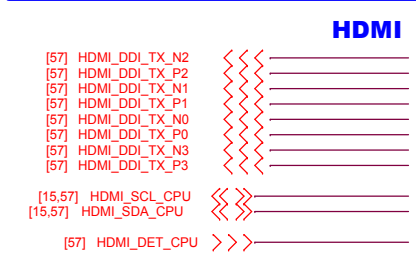
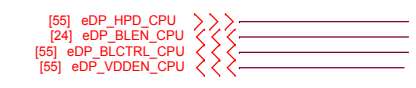
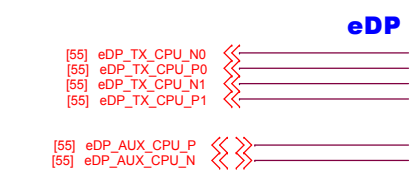
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Strongbow_KBL Block Diagram



GPU DC/DC		CHARGER	
RT8813D6QW-GP	85	BQ24780S	44
INPUTS	OUTPUTS	INPUTS	OUTPUTS
5V_S0	1V_VGACORE_S0	AD* BT*	19V_DCBATOUT
GPU DC/DC		SYSTEM DC/DC	
RT8816A6QW-GP	86	RT6258C6QUF-GP	45
INPUTS	OUTPUTS	INPUTS	OUTPUTS
5V_S5	1D35V_V6A_S0	19V_DCBATOUT	3D3V_AUX_S5 5V_S5
GPU DC/DC		SYSTEM DC/DC	
SY8003ADFC-GP	86	RT6256B6QUF-GP	45
INPUTS	OUTPUTS	INPUTS	OUTPUTS
3D3V_S5	1D8V_AON_S0	19V_DCBATOUT	3D3V_S5
GPU DC/DC		CPU DC/DC	
APE8939GN3-GP	86	RT3602	46-47
INPUTS	OUTPUTS	INPUTS	OUTPUTS
1D8V_AON_S0	1D8V_V6A_S0	19V_DCBATOUT	1V_CPU_CORE
GPU DC/DC		CPU DC/DC	
APE8939GN3-GP	86	AOZ5049	48
INPUTS	OUTPUTS	INPUTS	OUTPUTS
1D0V_S5	1V_1D05V_V6A_S0	19V_DCBATOUT	1V_VCCGT
		CPU DC/DC	
		RT9610B	50
		INPUTS	OUTPUTS
		5V_S5	1V_VCCSA
		CPU DC/DC	
		G5388K11U-GP	51
		INPUTS	OUTPUTS
		5V_S5	PWR_VDDQ
		CPU DC/DC	
		APL5930KAI	51
		INPUTS	OUTPUTS
		5V_S5	2D5V_S3
		SYSTEM DC/DC	
		G5388K11U-GP	52
		INPUTS	OUTPUTS
		5V_S5	1D0V_S5
		SYSTEM DC/DC	
		G9661-25ADJ	53
		INPUTS	OUTPUTS
		3D3V_S5	1D8V_S5
		SYSTEM Load switch	
		TPS22976	40
		INPUTS	OUTPUTS
		3D3V_S5	1D5V_S0
		5V_S5	5V_S0
		1D0V_S5	1V_VCCST
		1D8V_S5	1D8V_S0
		SYSTEM Load switch	
		APE8939	40
		INPUTS	OUTPUTS
		1D0V_S5	1V_VCCIO

Main Func = CPU



(#543016) eDP_RCOMP Guideline

Signal	Trace Width	Isolation Spacing	Resistor Value	Length
eDP_RCOMP	20 mils	25 mils	24.9 Ω ± 1%	Max = 100 mils

Design Guideline:
Skylake processor signal eDP_RCOMP should be connected to the VCCIO rail via a single 24.9 ± 1% Ω resistor

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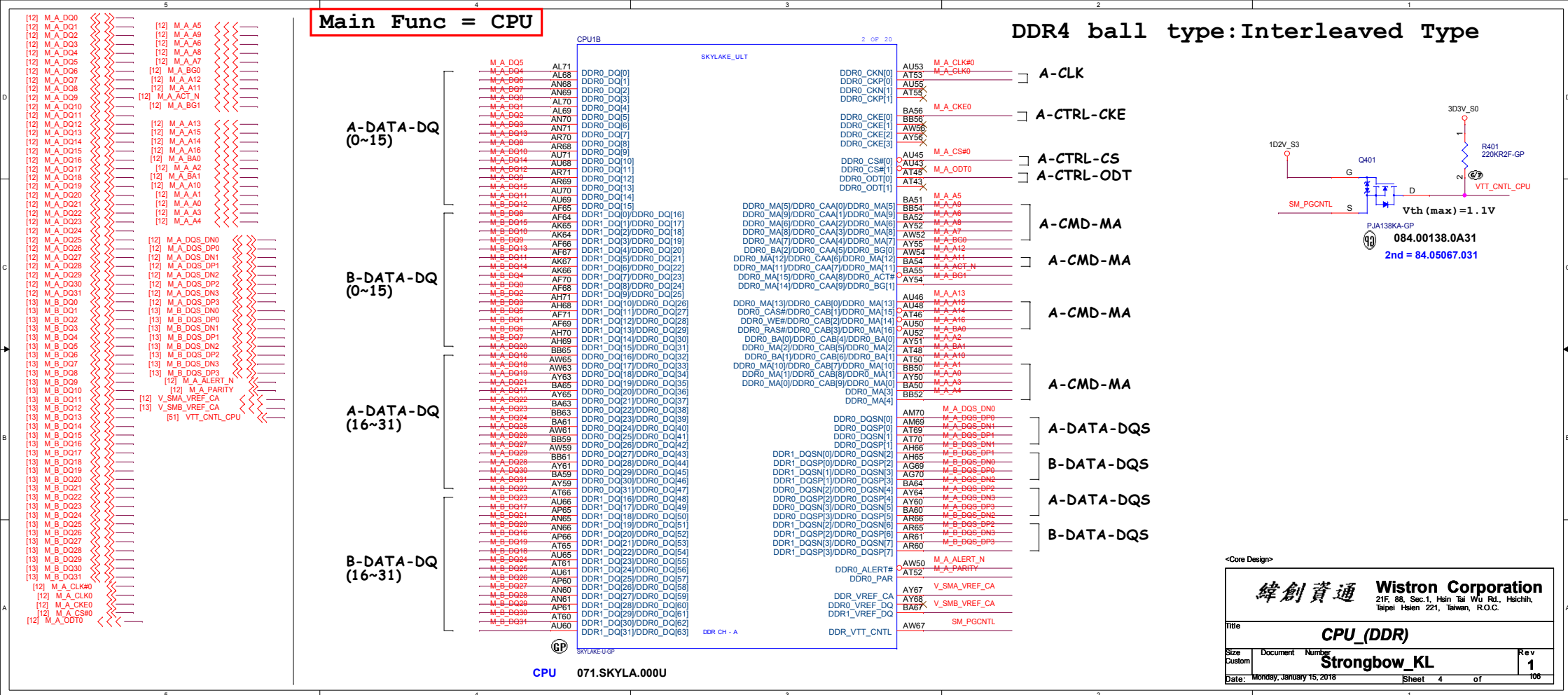
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Title: **CPU_(DISPLAY)**

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	Strongbow_KL	1
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Main Func = CPU



Main Func = CPU

DDR4 ball type:Interleaved Type

[13] M_B_DQ32	[13] M_B_A5
[13] M_B_DQ33	[13] M_B_A9
[13] M_B_DQ34	[13] M_B_A6
[13] M_B_DQ35	[13] M_B_A8
[13] M_B_DQ36	[13] M_B_A7
[13] M_B_DQ37	[13] M_B_BG0
[13] M_B_DQ38	[13] M_B_A12
[13] M_B_DQ39	[13] M_B_A11
[13] M_B_DQ40	[13] M_B_ACT_N
[13] M_B_DQ41	[13] M_B_BG1
[13] M_B_DQ42	[13] M_B_A13
[13] M_B_DQ43	[13] M_B_A15
[13] M_B_DQ44	[13] M_B_A14
[13] M_B_DQ45	[13] M_B_A16
[13] M_B_DQ46	[13] M_B_BA0
[13] M_B_DQ47	[13] M_B_A2
[13] M_B_DQ48	[13] M_B_BA1
[13] M_B_DQ49	[13] M_B_A10
[13] M_B_DQ50	[13] M_B_A1
[13] M_B_DQ51	[13] M_B_A0
[13] M_B_DQ52	[13] M_B_A3
[13] M_B_DQ53	[13] M_B_A4
[13] M_B_DQ54	[13] M_B_CLK#0
[13] M_B_DQ55	[13] M_B_CLK0
[13] M_B_DQ56	[13] M_B_CKE0
[13] M_B_DQ57	[13] M_B_CS#0
[13] M_B_DQ58	[13] M_B_ODT0
[13] M_B_DQ59	[13] M_B_DQS_DN4
[13] M_B_DQ60	[13] M_B_DQS_DN5
[13] M_B_DQ61	[13] M_B_DQS_DN6
[13] M_B_DQ62	[13] M_B_DQS_DN7
[13] M_B_DQ63	[13] M_B_DQS_DN8
[12] M_A_DQ32	[12] M_A_DQS_DN6
[12] M_A_DQ33	[12] M_A_DQS_DN7
[12] M_A_DQ34	[12] M_A_DQS_DN7
[12] M_A_DQ35	[12] M_A_DQS_DN7
[12] M_A_DQ36	[12] M_B_DQS_DP4
[12] M_A_DQ37	[13] M_B_DQS_DN5
[12] M_A_DQ38	[13] M_B_DQS_DP5
[12] M_A_DQ39	[13] M_B_DQS_DN6
[12] M_A_DQ40	[13] M_B_DQS_DP6
[12] M_A_DQ41	[13] M_B_DQS_DN7
[12] M_A_DQ42	[13] M_B_DQS_DP7
[12] M_A_DQ43	[13] M_B_DQS_DN8
[12] M_A_DQ44	[13] M_B_ALERT_N
[12] M_A_DQ45	[13] M_B_PARITY
[12] M_A_DQ46	[12,13] SM_DRAMRST#
[12] M_A_DQ47	[13] M_B_ODT1
[12] M_A_DQ48	[13] M_B_CS#1
[12] M_A_DQ49	[13] M_B_CLK#1
[12] M_A_DQ50	[13] M_B_CLK1
[12] M_A_DQ51	[13] M_B_CKE1
[12] M_A_DQ52	[13] M_B_CLK1
[12] M_A_DQ53	[13] M_B_CKE1
[12] M_A_DQ54	[13] M_B_CKE1
[12] M_A_DQ55	[13] M_B_CKE1
[12] M_A_DQ56	[13] M_B_CKE1
[12] M_A_DQ57	[13] M_B_CKE1
[12] M_A_DQ58	[13] M_B_CKE1
[12] M_A_DQ59	[13] M_B_CKE1
[12] M_A_DQ60	[13] M_B_CKE1
[12] M_A_DQ61	[13] M_B_CKE1
[12] M_A_DQ62	[13] M_B_CKE1
[12] M_A_DQ63	[13] M_B_CKE1

A-DATA-DQ (32~47)

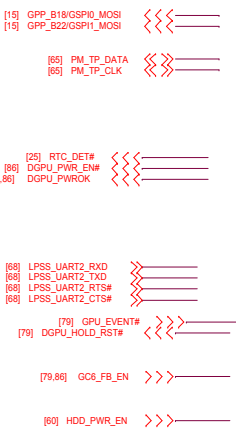
B-DATA-DQ (32~47)

A-DATA-DQ (48~63)

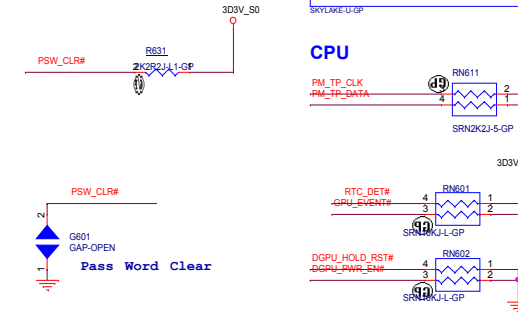
B-DATA-DQ (48~63)

M_A_DQ32	AY39	
M_A_DQ36	AW39	DDR0_DQ32/DDR1_DQ0
M_A_DQ34	AY37	DDR0_DQ33/DDR1_DQ1
M_A_DQ38	AW37	DDR0_DQ34/DDR1_DQ2
M_A_DQ35	BB39	DDR0_DQ35/DDR1_DQ3
M_A_DQ37	BA39	DDR0_DQ36/DDR1_DQ4
M_A_DQ36	BA37	DDR0_DQ37/DDR1_DQ5
M_A_DQ38	BB37	DDR0_DQ38/DDR1_DQ6
M_A_DQ40	AY39	DDR0_DQ39/DDR1_DQ7
M_A_DQ41	AW35	DDR0_DQ40/DDR1_DQ8
M_A_DQ43	AY33	DDR0_DQ41/DDR1_DQ9
M_A_DQ44	BB35	DDR0_DQ42/DDR1_DQ10
M_A_DQ44	AW33	DDR0_DQ43/DDR1_DQ11
M_A_DQ40	BA35	DDR0_DQ44/DDR1_DQ12
M_A_DQ46	BA33	DDR0_DQ45/DDR1_DQ13
M_A_DQ42	BB33	DDR0_DQ46/DDR1_DQ14
M_B_DQ36	AU40	DDR1_DQ47/DDR1_DQ15
M_B_DQ33	AT40	DDR1_DQ32/DDR1_DQ16
M_B_DQ37	AT37	DDR1_DQ33/DDR1_DQ17
M_B_DQ38	AU37	DDR1_DQ34/DDR1_DQ18
M_B_DQ37	AR40	DDR1_DQ35/DDR1_DQ19
M_B_DQ32	AP40	DDR1_DQ36/DDR1_DQ20
M_B_DQ35	AP37	DDR1_DQ37/DDR1_DQ21
M_B_DQ39	AR37	DDR1_DQ38/DDR1_DQ22
M_B_DQ41	AT33	DDR1_DQ39/DDR1_DQ23
M_B_DQ40	AU33	DDR1_DQ40/DDR1_DQ24
M_B_DQ46	AU30	DDR1_DQ41/DDR1_DQ25
M_B_DQ42	AT30	DDR1_DQ42/DDR1_DQ26
M_B_DQ44	AR33	DDR1_DQ43/DDR1_DQ27
M_B_DQ43	AP33	DDR1_DQ44/DDR1_DQ28
M_B_DQ47	AR30	DDR1_DQ45/DDR1_DQ29
M_B_DQ44	AP30	DDR1_DQ46/DDR1_DQ30
M_B_DQ49	AY31	DDR1_DQ47/DDR1_DQ31
M_A_DQ62	AY31	DDR1_DQ48/DDR1_DQ32
M_A_DQ64	AY29	DDR1_DQ49/DDR1_DQ33
M_A_DQ63	AW29	DDR1_DQ50/DDR1_DQ34
M_A_DQ68	BB31	DDR1_DQ51/DDR1_DQ35
M_A_DQ66	BA31	DDR1_DQ52/DDR1_DQ36
M_A_DQ61	BA29	DDR1_DQ53/DDR1_DQ37
M_A_DQ66	BB29	DDR1_DQ54/DDR1_DQ38
M_A_DQ67	AY27	DDR1_DQ55/DDR1_DQ39
M_A_DQ68	AW27	DDR1_DQ56/DDR1_DQ40
M_A_DQ69	AY25	DDR1_DQ57/DDR1_DQ41
M_A_DQ69	BB27	DDR1_DQ58/DDR1_DQ42
M_A_DQ61	BA25	DDR1_DQ59/DDR1_DQ43
M_A_DQ62	BB25	DDR1_DQ60/DDR1_DQ44
M_A_DQ62	BA25	DDR1_DQ61/DDR1_DQ45
M_B_DQ33	BB25	DDR1_DQ62/DDR1_DQ46
M_B_DQ48	AT27	DDR1_DQ63/DDR1_DQ47
M_B_DQ44	AU27	DDR1_DQ48
M_B_DQ45	AW27	DDR1_DQ50
M_B_DQ62	AU25	DDR1_DQ52
M_B_DQ49	AN27	DDR1_DQ53
M_B_DQ69	AN25	DDR1_DQ54
M_B_DQ67	AP25	DDR1_DQ55
M_B_DQ66	AU22	DDR1_DQ56
M_B_DQ60	AT22	DDR1_DQ57
M_B_DQ62	AN22	DDR1_DQ59
M_B_DQ68	AT21	DDR1_DQ60
M_B_DQ61	AP22	DDR1_DQ61
M_B_DQ60	AN21	DDR1_DQ62
M_B_DQ60	AP21	DDR1_DQ63

Main Func = PCH



Touch Pad



GPIO Group Summary

GPIO Group	Power Pins	Voltage
Primary Well Group A (GPP_A)	VCCPGPPA	1.8V or 3.3V
Primary Well Group B (GPP_B)	VCCPGPPB	1.8V or 3.3V
Primary Well Group C (GPP_C)	VCCPGPPC	1.8V or 3.3V
Primary Well Group D (GPP_D)	VCCPGPPD	1.8V or 3.3V
Primary Well Group E (GPP_E)	VCCPGPPE	1.8V or 3.3V
Primary Well Group F (GPP_F)	VCCPGPPF	1.8V
Primary Well Group G (GPP_G)	VCCPGPPG	1.8V or 3.3V
Deep Sleep Well Group (GPD)	VCCPDSW_3p3	3.3V

Vendor	NFIG4 (GPP_A1)	NFIG3 (GPP_A1)	NFIG2 (GPP_A2)	NFIG1 (GPP_A)	Mfr. PN	DDP/SDP	Wistron . P/N	Capacity	Stage
HYNIX	0	0	0	0	H5AN8G6NAFR-UHC	SDP	KN.8GB0G.049	8Gb	
Micron	0	0	0	1	MT40A512M16LY-075	SDP	KN.8GB04.027	8Gb	LAB
Micron	0	0	1	0	MT40A1G16KNR-075	DDP	KN.01604.003	16Gb	LAB
HYNIX	0	0	1	1	H5ANAG6NAMR-UHC	DDP	KN.0160G.010	16Gb	

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Title

CPU_(LPSS/ISH)

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Main Func = CPU

SVID

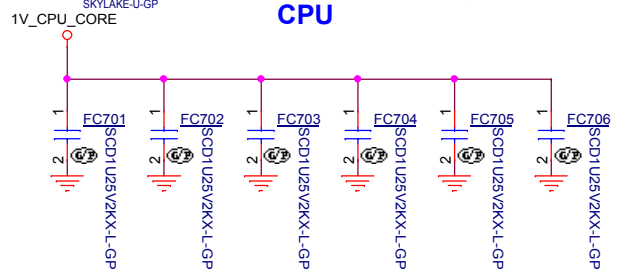
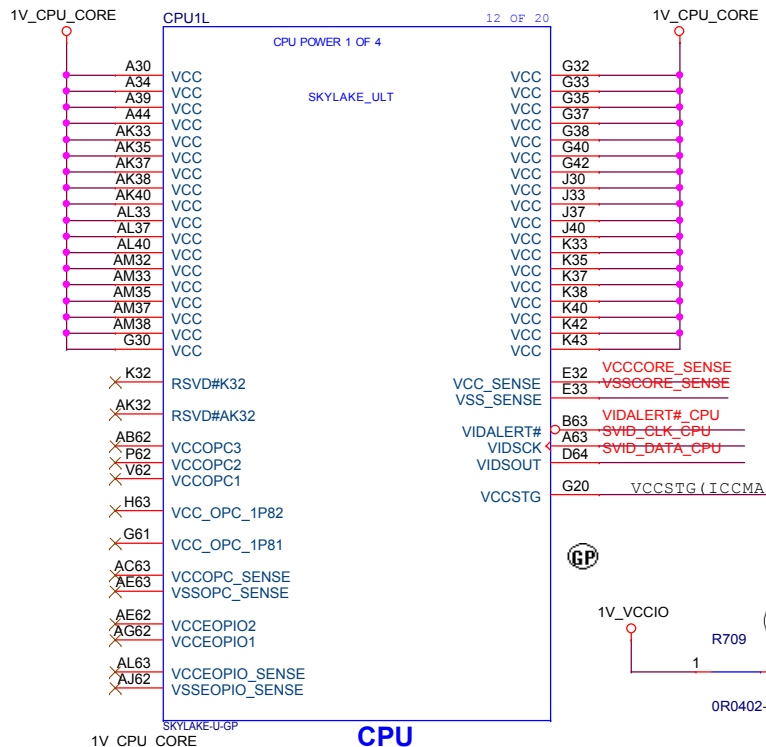
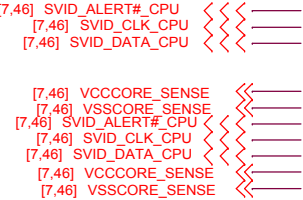
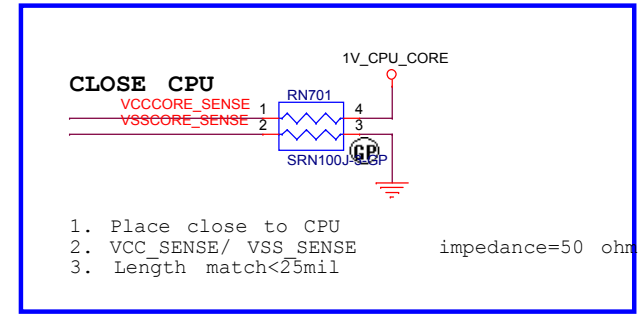
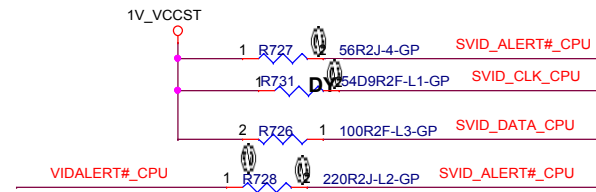


Table 10-10.SVID Bus Routing Guidelines

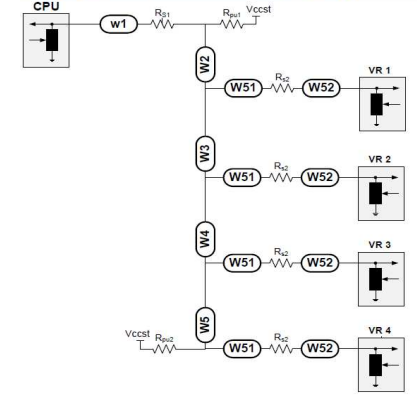
Signal	W1 [inches]	W2 [inches]	W3/4/5 [inches]	W2+W3+W4+W5 [inches]	W51 [inches]	W52 [inches]	R _{PU1} [Ω]	R _{PU2} [Ω]	R _{S1} [Ω]	R _{S2} [Ω]	VCC _{ST} [v]
VIDSOUT	0.5-3	1-15	0.5-4	3-17	<0.1	<0.1	100	100	0	10	1.0
VIDSCK							Empty	45	0	50	
VIDALERT #							56	Empty	220	0	



Layout Note:

1. Place close to CPU
2. VCC_SENSE/ VSS_SENSE impedance=50 ohm
3. Length match<25mil

Figure 10-7. Routing Illustration for SVID Topology

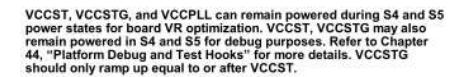


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[46] VSSSA_SENSE <<<< _____
 [46] VCCSA_SENSE <<<< _____

[46] VCCGT_SENSE <<<< _____
 [46] VSSGT_SENSE <<<< _____



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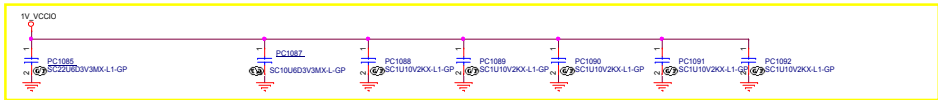
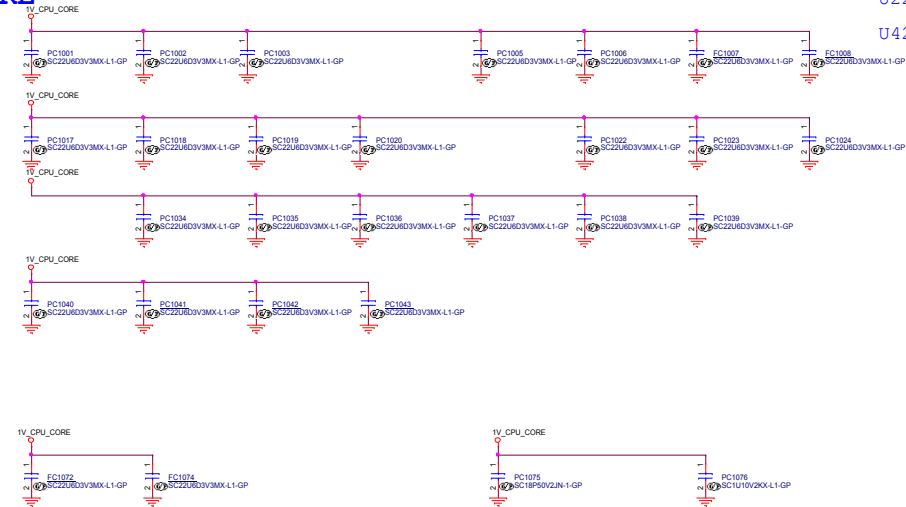
Main Func = CPU

VCORE

1V_CPU_CORE

U22 0603 22uF *25 , 0603 10uF*1

U42 0603 22uF *12



1V_VCCIO
22uF* 1 10uF * 1 1uF *4

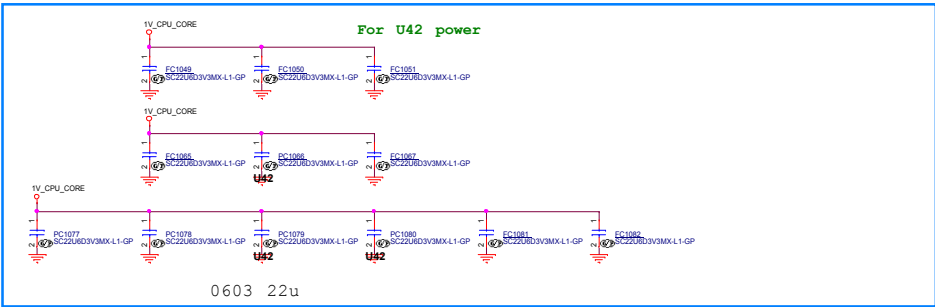
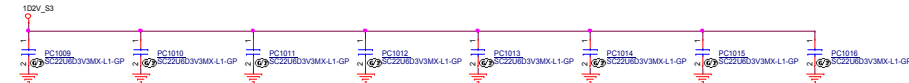


Table 48-4. Decoupling Requirements for KBL-R U 4+2 / KBL U 2+2 Processor (Sheet 2 of 3)

Domain	Backside cap	Primary side cap	Placement guideline
VCCSA	7x 10 uF 0402 7x 1 uF 0402 or 0201		Place on secondary side, underneath the package.
VCCDQ	6x 10 uF 0402		Place as close to the package as possible.
VCCDQ	4x 1 uF 0402		Place as close to the package as possible.
VCCDQ	4x 10 uF 0402		Place as close to the package as possible.
VCCDQ	3 x 22 uF 0603		Place as close to the package as possible.
VCCDQ	1 x 10 uF 0402		Preferred to place the 0402 10uF cap on the secondary under the package shadow near VDDQC pin and short to VDDQ rail under with a shape. Alternatively, if the 0402 cap cannot be placed on the backside, follow the example shown in Figure 48-3. The 0402 cap to VDDQC BGA routing should not exceed 48mohm (RdC). RVP design uses trace L=450mil, W=4mil between BGA and cap. Additional trace routing implemented in RVP design was not required.
VCCPL	1x 1 uF 0402		Place as close to the package as possible.
VCCPL_OC	1x 1 uF 0201		Do not route VCCPL, VCCPL_OC, VCCGT closest adjacent layer over any power net other than ground.
VCCGT	1x 1 uF 0402		For VccST, Refer to Figure 48-2 for additional routing details for VccST & VccSTG.

- Notes:
- The 6.3V voltage is for the higher capacitance retention; more 0805 components will be required for a lower voltage capacitor rating. Assumption: VR loop bandwidth ~ 250kHz e.g., 1MHz switching VR.
 - Component placement order: Package edge > 0402 caps > 0805 caps > Bulk caps > Power source.
 - Due to the difference between the package designs, KBL U 2+2 design requires more on-board decoupling in order to maintain the same loadline.
 - Diagram of placement for 0402 backside caps for CPU decoupling.

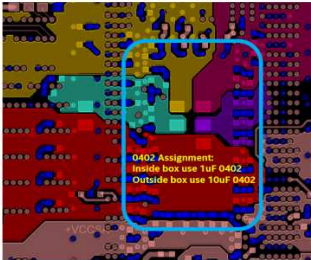


Table 48-4. Decoupling Requirements for KBL-R U 4+2 / KBL U 2+2 Processor (Sheet 1 of 3)

Domain	Backside cap	Primary side cap	Placement guideline
Vcc	7x 10 uF 0402		Place on secondary side, underneath the package
	31x 1 uF 0402 or 0201		Refer to diagram in Note 4 below for placement recommendation of 0402 caps
		9x 22 uF 0603	Place as close to the package as possible
		8x 47 uF 0805 (6.3V) ¹	
		8x 10 uF 0402	
Vcc/VccGT	5x 1 uF 0402 or 0201		Place as close to the package as possible
VccGT	12x 10 uF 0402		Place on secondary side, underneath the package
	14x 1 uF 0402 or 0201		
		7x 22 uF 0603	Place as close to the package as possible
		3x 47 uF 0805 (6.3V) ¹	

Power Layout



48.1.3 Kaby Lake U Compatible Design Recommendation

48.1.3.1 KBL-R U 4+2 / KBL U 2+2 Design Recommendation

Table 48-3. Bulk Decoupling Example (KBL-R U42/KBL U22)

Bulk Decoupling Locations	Example - U 4+2	Example - U 2+2	Notes
Vcc Power Plane at VR output	2x 220 uF (@4.5mO ESR)	1x 220 uF (@4.5mO ESR)	Placed at primary side near to VR output
	1x 220 uF (@4.5mO ESR)		Placed at backside side near to VR output
VCCGT Power Plane at VR output	2x 220 uF (@4.5mO ESR)		Placed at primary side near to VR output
VDDQ Power Plane at VR output	2x 47 uF 0805		Placed at primary side near to VR output
VCCDQ Power Plane at VR output	2x 47 uF 0805		Placed at primary side near to VR output
VCCSA Power Plane at VR output	2x 47 uF 0805		Placed at primary side near to VR output
VCCPL Power Plane at VDDQA VR output	1x 0.1uF 0402		Placed at primary side near to VR output

Notes:

- These examples are based on 1MHz switching frequency VR with bandwidth of up to 250kHz.
- Bulk decoupling is not a "requirement" but recommendation only. It is an example of VR design/VR bandwidth. Customer should work with respective vendor to validate their VR & bulk decoupling designs to ensure the electrical requirements are met.

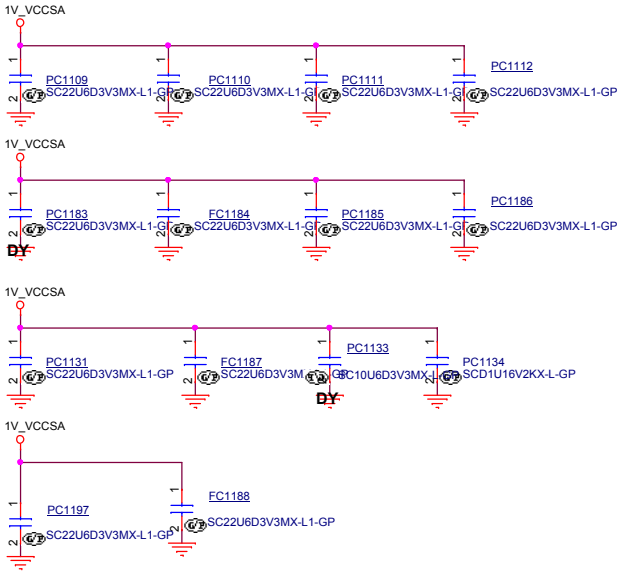
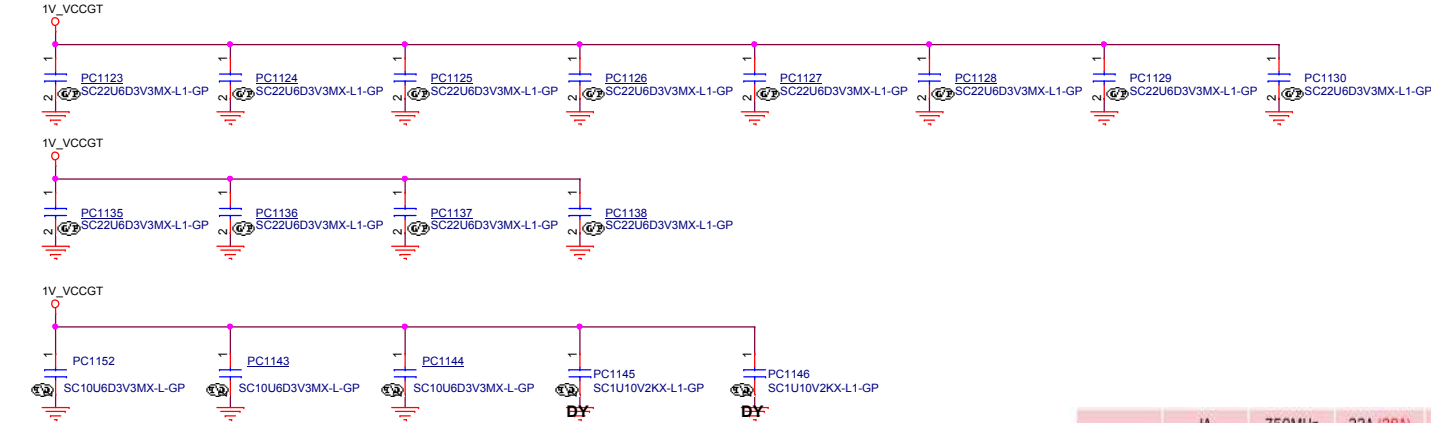
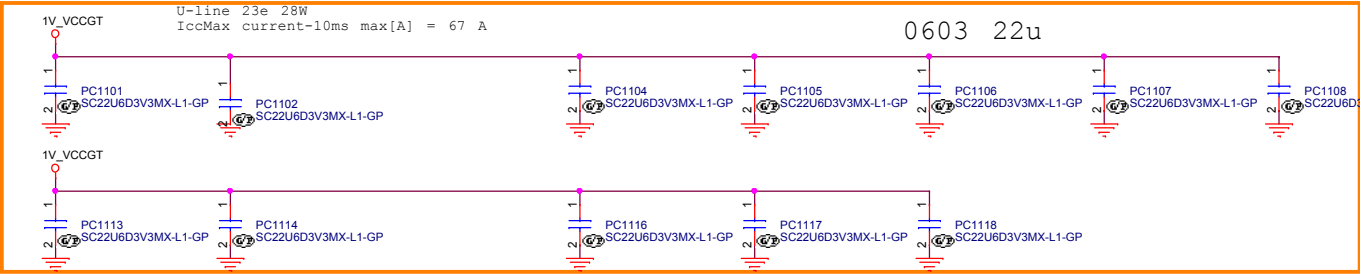
Core Design

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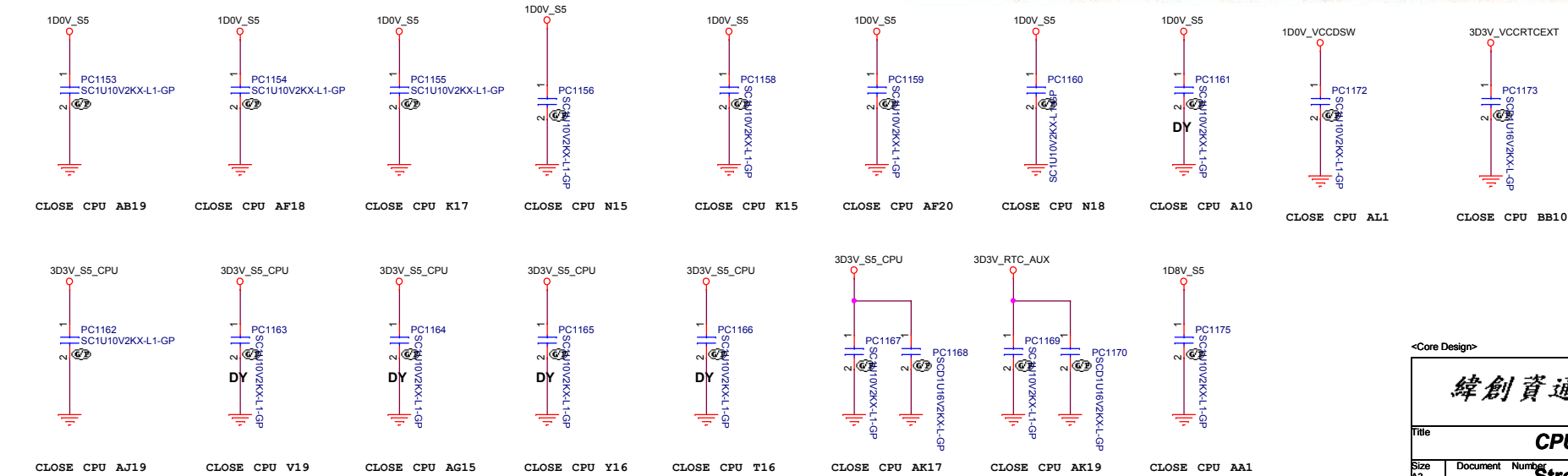
File	CPU_POWER1	
Doc Number	Strongbow_KL	
Date	Thursday, January 11, 2016	Sheet 10 of 106

Main Func = CPU

SLICED GT



U22 15W	IA	750MHz	33A (28A)	23A (21A)	2.1mΩ (2.35mΩ)	30A (TBD)	200mv/30us	1X0.15uH	2X330uF/9mW	30X22uF
								Or	1x330uF/9mW	36x22uF
	GT	750KHz	40A (31A)	18A (18A)	3.1mΩ	38A (TBD)	70mv/10us	1X0.15uH	2X330uF/9mW	24X22uF
								Or	1x330uF/9mW	36x22uF
	SA	750KHz	6A (5A)	6A (4A)	10.3mΩ	4A (TBD)	200mv/30us	1X0.42uH	None	5X22uF



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Title CPU_(Power CAP2)

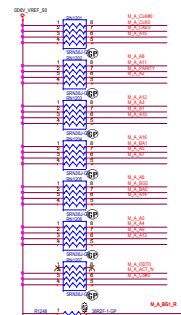
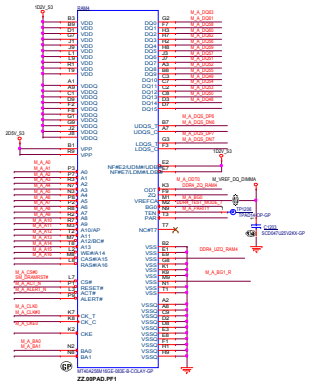
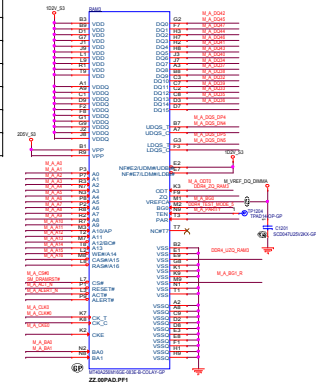
Size A3 Document Number Strongbow_KL Rev 1

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SS1D = DDR4 CHA

DQ80	DQ0-DQ7
DQ81	DQ8-DQ15
DQ82	DQ16-DQ23
DQ83	DQ24-DQ31
DQ84	DQ32-DQ39
DQ85	DQ40-DQ47
DQ86	DQ48-DQ55
DQ87	DQ56-DQ63

please notice that signal B01 (pin:80) and DQ0 (pin:59) are required



4.14.3 KBL-R DDR4 Memory Down Decoupling

This recommendation assumes a 2Ch memory down implementation.

Memory Configuration	Power Domain	Decoupling Location	Qty x μF (size)	Note
DDR4 Memory Down x16 - 4 Devices per Channel	VDDQ/VDD (shorted)	4 as near each x16 DRAM device as possible	32x 1 μF (0402) (All stuffed)	
		Distributed around the DRAM devices	10x 10 μF (0603) (All stuffed)	
	VPP	2 as near each x16 DRAM device as possible	16x 1 μF (0402)	
		Distributed around the DRAM devices	5x 10 μF (0603)	
	VTT	2 as near each x16 DRAM device as possible	16x 1 μF (0402)	
		Distributed around the DRAM devices	4x 10 μF (0603)	

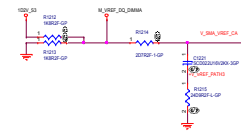
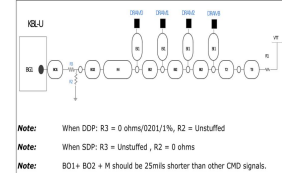
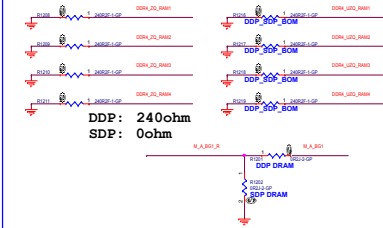


Figure 3-29. SKL/KBL U DDR4 x16 Memory Down SDP and DDP common board B01 Signal Topology



SDP & DDP SETTING



DDP x16 and SDP x16 Compatible Layout

Alternate two layout, risk of VSS offset increases a little

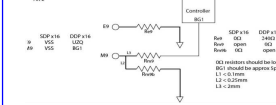
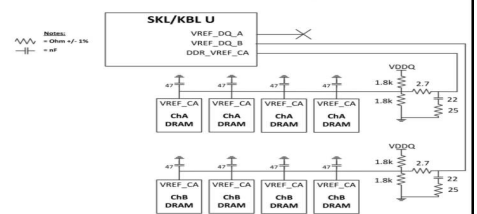
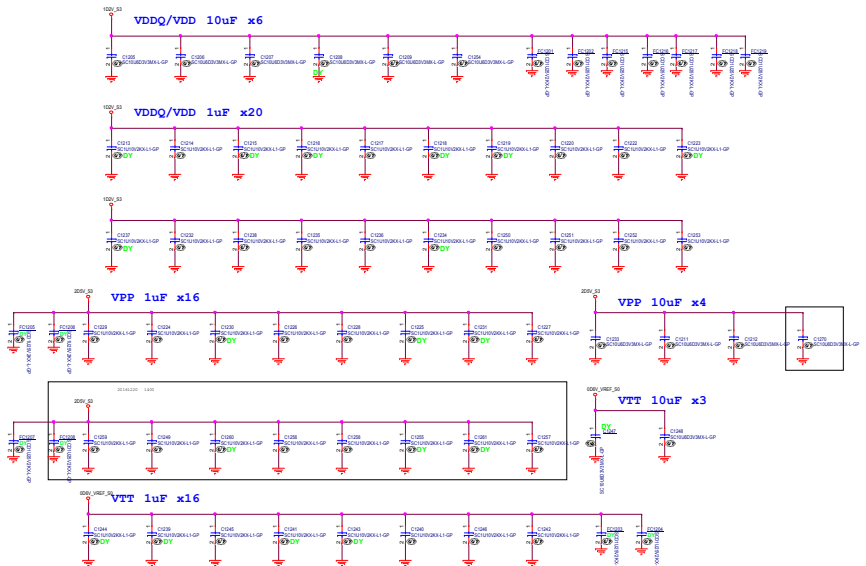


Figure 4-3. SKL/KBL U DDR4 Memory Down VREF-DQ and VREF-CA Overview



DDR4 On Board RAM Power Decouple Cap



For OD1M1, OD1M2, OD1M3, OD1M4

5	4	3	2	1
D				D
C				C
B				B
A				A
5	4	3	2	1

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Title			
CPU_POWER3			
Size Custom	Document Number	Rev	
	Strongbow_KL	1	
Date:	Thursday, January 11, 2018	Sheet 14 of	106

SSID = STRAP

Description	Display Port B Detected	Display Port C Detected	Reserved	No reboot	Boot BIOS strap bit BBS	Flash descriptor security override	Display Port D Detected
GPIO	GPP_E19	GPP_E21	SPI0_MISO	GPP_B18	GPP_B22	HDA_SDO	GPP_E23
Schematic							
High	Detected	Detected	Detected	Enable	LPC	Disable	Detected
Low	Not Detected	Not Detected	Not Detected	Disable	SPI	Enable	Not Detected
	internal pull-down	internal pull-down	internal pull-up	internal pull-down	internal pull-down	internal pull-down	internal pull-down

Description	Top Swap Override	Reserved	Reserved	Reserved	TLS Confidentiality	eSPI or LPC	Reserved
GPIO	GPP_B14	SPI0_MOSI	SPI0_IO2	SPI0_IO3	GPP_C2	GPP_C5	GPP_B23
Schematic							
High	Enable				Enable	eSPI	
Low	Disable				Disable	LPC	
	internal pull-down	internal pull-up	internal pull-up	internal pull-up	internal pull-down	internal pull-down	internal pull-down

STRAP RESISTORS SHOULD BE PLACED CLOSE TO SOC SHOULD BE PLACED OUTSIDE KIC AREA

Name	Internal Pull-up / Pull-Down (Note 1)	De-Glitch (Note 2)	Multiplexed With	Default	NMI or SMI Capable	Note
GPP_B22	20K PD (see note)	No	No	GPI0_MOSI	GPO	None
GPP_B23	20K PD (see note)	Yes	No	SMI0_ALERT# / PCHIOF#	GPO	NMI SMI

Signal Name	Power Plane	During Reset	Immediately after Reset	S3/S4/S5	Deep Sx
HDA_AUDIO_INTERFACE	Primary	Driven Low	Driven Low	Driven Low	OFF
HDA_RST#	Primary	Internal Pull-down	Driven Low	Driven Low	OFF
HDA_BLK	Primary	Driven Low	Driven Low	Driven Low	OFF
HDA_SDO	Primary	Internal Pull-down	Driven Low	Driven Low	OFF
HDA_SDI[1:0]	Primary	Internal Pull-down	Internal Pull-down		OFF

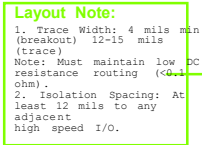
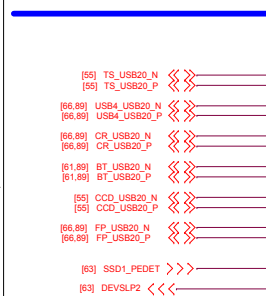
I/O Signal Planes and States

Signal Name	Power Plane	During Reset	Immediately after Reset	S3/S4/S5	Deep Sx
SPI0_CLK	Primary	Driven Low (See Note 1)	Driven Low	Driven Low	Off
SPI0_MOSI	Primary	Internal Pull-up / Pull-down (See Note 1 & 2)	Driven Low	Driven Low	Off
SPI0_MISO	Primary	Internal Pull-up	Internal Pull-up	Internal Pull-up	Off
SPI0_CS0#	Primary	Driven High (See Note 1)	Driven High	Driven High	Off
SPI0_CS1#	Primary	Internal Pull-up (See Note 1)	Driven High	Driven High	Off
SPI0_CS2#	Primary	Driven High (See Note 1)	Driven High	Driven High	Off
SPI0_IO[2:3]	Primary	Internal Pull-up (See Note 1)	Internal Pull-up	Internal Pull-up	Off
SPI1_CLK	Primary	Undriven	Undriven	Undriven	Off
SPI1_MOSI	Primary	Undriven	Undriven	Undriven	Off
SPI1_MISO	Primary	Undriven	Undriven	Undriven	Off
SPI1_CS#	Primary	Undriven	Undriven	Undriven	Off
SPI1_IO[2:3]	Primary	Undriven	Undriven	Undriven	Off

Notes:
1. Pins are tri-stated (with weak internal pull-up) prior to RSMRST# de-assertion.
2. Weak internal pull-up resistor is enabled when RSMRST# is asserted and is switched to a weak internal pull-down when RSMRST# is de-asserted.

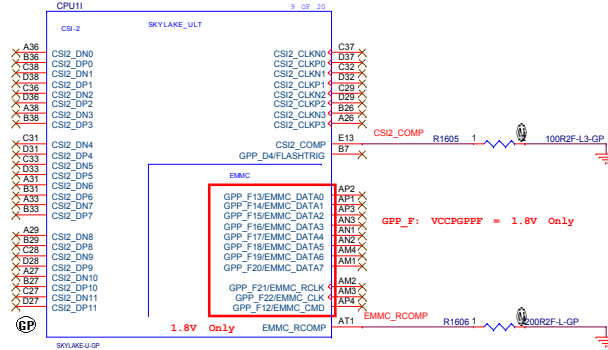
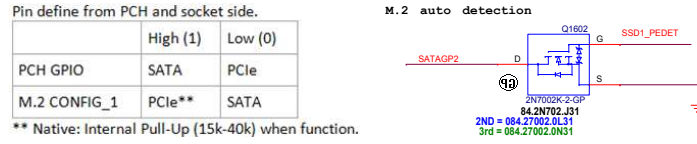
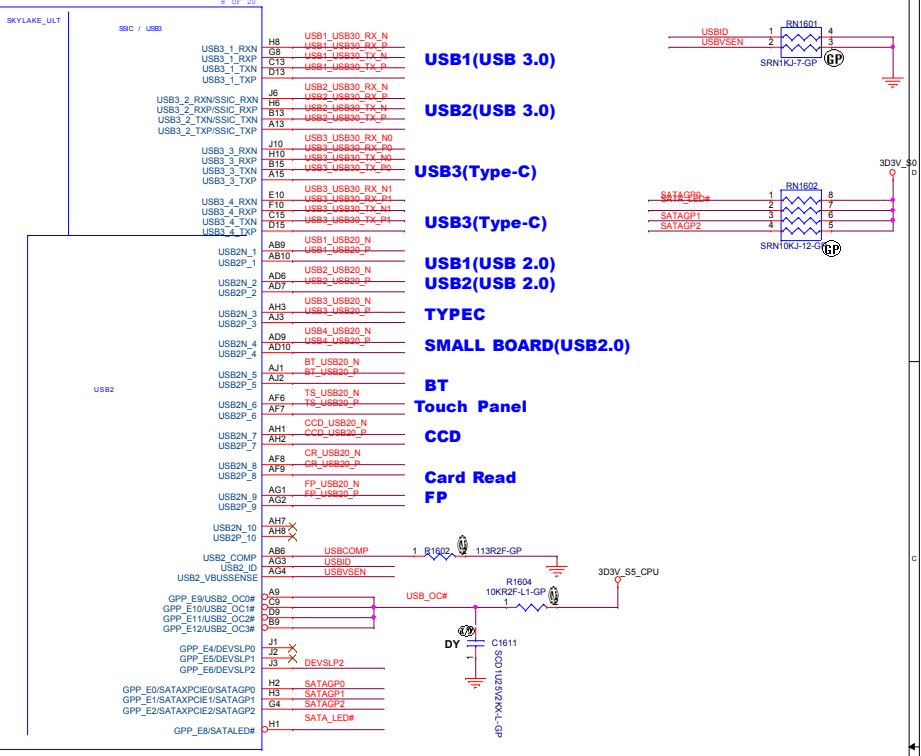
DDPB_CTRLDATA / GPP_E19	Display Port B Detected	Rising edge of PCH_PWROK	This signal has a weak internal pull-down. 0 = Port B is not detected. 1 = Port B is detected. Notes: 1. The internal pull-down is disabled after PLTRST# de-asserts. 2. This signal is in the primary well.
DDPC_CTRLDATA / GPP_E21	Display Port C Detected	Rising edge of PCH_PWROK	This signal has a weak internal pull-down. 0 = Port C is not detected. 1 = Port C is detected. Notes: 1. The internal pull-down is disabled after PLTRST# de-asserts. 2. This signal is in the primary well.
GSPI0_MOSI / GPP_B18	No Reboot	Rising edge of PCH_PWROK	The signal has a weak internal pull-down. 0 = Disable "No Reboot" mode. 1 = Enable "No Reboot" mode (PCH will disable the TCO Timer system reboot feature). This function is useful when running ITP/XDP. Notes: 1. The internal pull-down is disabled after PLTRST# de-asserts. 2. The status of this strap is readable using the NO REBOOT bit (Chipset Configuration Registers: RCBA + Offset 3410h:Bit 5). 3. This signal is in the primary well.
GSPI1_MOSI / GPP_B22	Boot BIOS Strap Bit BBS	Rising edge of PCH_PWROK	This Signal has a weak internal pull-down. This field determines the destination of accesses to the BIOS memory range 0x00000000-0x0000000F. This strap is used in conjunction with Boot BIOS Destination Selection 0 strap. 0 = Boot BIOS Destination 1 = LPC Notes: 1. The internal pull-down is disabled after PLTRST# de-asserts. 2. If option 1 (LPC) is selected, BIOS may still be placed on LPC, but all platforms are required to have SPI flash connected to the PCIE's SPI bus with a valid descriptor in order to boot. 3. Boot BIOS Destination Select to LPC by functional strap or using Boot BIOS Destination bit will not affect SPI accesses initiated by Intel ME or Integrated GBE LAN. 4. This signal is in the primary well.
Signal	Usage	When Sampled	Comment
DDPD_CTRLDATA / GPP_E23	Display Port D Detected	Rising edge of PCH_PWROK	This signal has a weak internal pull-down. 0 = Port D is not detected. 1 = Port D is detected. Notes: 1. The internal pull-down is disabled after PLTRST# de-asserts. 2. This signal is in the primary well.
SPKR / GPP_B14	Top Swap Override	Rising edge of PCH_PWROK	The signal has a weak internal pull-down. 0 = Disable "Top Swap" mode. (Default) 1 = Enable "Top Swap" mode. This inverts an address on access to SPI and firmware hub, so the processor believes it fetches the alternate boot block instead of the original boot-block. PCH will invert A16 (default) for cycles going to the upper two 64KB blocks in the flash or the appropriate address lines (A16, A17, or A18) as selected in Top Swap Block size soft strap (changed through FITC). Notes: 1. The internal pull-down is disabled after PLTRST# de-asserts. 2. Software will not be able to clear the Top Swap bit until the system is rebooted. 3. The status of this strap is readable using the Top Swap bit (Bus0, Device31, Function0, Offset Dch, D14). 4. This signal is in the primary well.
SMALERT# / GPP_C2	TLS Confidentiality	Rising edge of RSMRST#	This signal has a weak internal pull-down. 0 = Disable Intel ME Crypto Transport Layer Security (TLS) cipher suite (no confidentiality). 1 = Enable Intel ME Crypto Transport Layer Security (TLS) cipher suite (with confidentiality). Must be pulled up to support Intel AMT with TLS and Intel SBA (Small Business Advantage) with TLS. Notes: 1. The internal pull-down is disabled after RSMRST# de-asserts. 2. This signal is in the primary well.
SMIOALERT# / GPP_C5	eSPI or LPC	Rising edge of RSMRST#	This signal has a weak internal pull-down. 0 = LPC is selected for EC. 1 = eSPI is selected for EC. Notes: 1. The internal pull-down is disabled after RSMRST# de-asserts. 2. This signal is in the primary well.

GPU



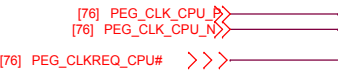
Rate #	Module Configuration Decodes				Module Type and Main Host Interface ¹	Port Configuration ²
	CONFIG_0 (Pin 21)	CONFIG_1 (Pin 69)	CONFIG_2 (Pin 75)	CONFIG_3 (Pin 1)		
0	GND	GND	GND	GND	SSD – SATA	N/A
1	GND	N/C	GND	GND	SSD – PCIe	N/A

KBL Premium/U		Acer 2015		2017 R15(Premium)		2017 R15(base)	
Lane1	USB3 Port1	USB 3 (i/O)		USB 3 (i/O)		USB 3 (i/O)	
Lane2	USB3 Port2	USB 3 (i/O)		USB 3 (i/O)		USB 3 (i/O)	
Lane3	USB3 Port3	USB 3 (i/O)		USB 3 Type-C (i/O)		USB 3 Type-C (i/O)	
Lane4	USB3 Port4						
Lane5	USB3 Port5 (Premium)	PCIe Port1					
Lane6	USB3 Port6 (Premium)	PCIe Port2					
Lane7		dGPU		dGPU		dGPU	
Lane8		PCIe Port3					
Lane9		PCIe Port4					
Lane9		PCIe Port5		LAN			
Lane10		PCIe Port6		WIFI		WIFI	
Lane11	SATA0 (Base/Premium)	PCIe Port7 (Premium)		HDD		HDD	
Lane12	SATA1 (Base/Premium)	PCIe Port8 (Premium)		ODD		ODD	
Lane13		PCIe Port9					
Lane14		PCIe Port10		NA		M.2 SSD (PCIe x4) * BIOS needs to set PCIe x4 lane reversal	
Lane15	SATA1 (Premium)	PCIe Port11				M.2 SSD (PCIe x4) * BIOS needs to set PCIe x4 lane reversal	
Lane16	SATA2 (Premium)	PCIe Port12		M.2 SSD (SATA x1)		M.2 SSD (SATA x1)	
	USB2 Port1	USB 3 (i/O)		USB 3 (i/O) (USB20)		USB 3 (i/O) (USB20)	
	USB2 Port2	USB 3 (i/O)		USB 3 (i/O) (USB20)		USB 3 (i/O) (USB20)	
	USB2 Port3	USB 3 (i/O)		USB 2 Type-C (i/O)		USB 2 Type-C (i/O)	
	USB2 Port4	USB 2 (i/O) / Sensor Hub		USB 2 (i/O)		USB 2 (i/O)	
	USB2 Port5	BT		BT		BT	
	USB2 Port6	FS		FS		FS	
	USB2 Port7	CCD		CCD		CCD	
	USB2 Port8	CR (USB) / FP		CR		CR	
	USB2 Port9	SG		FP		FP	
	USB2 Port10						



Main Func = PCH

DIS



WLAN



NGFF1



KBC

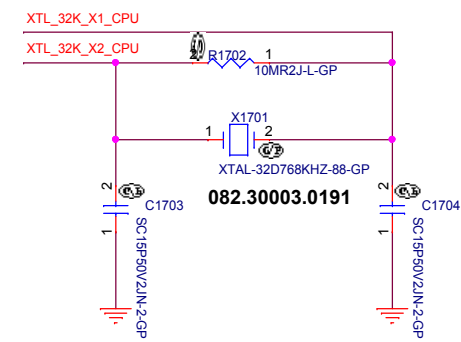
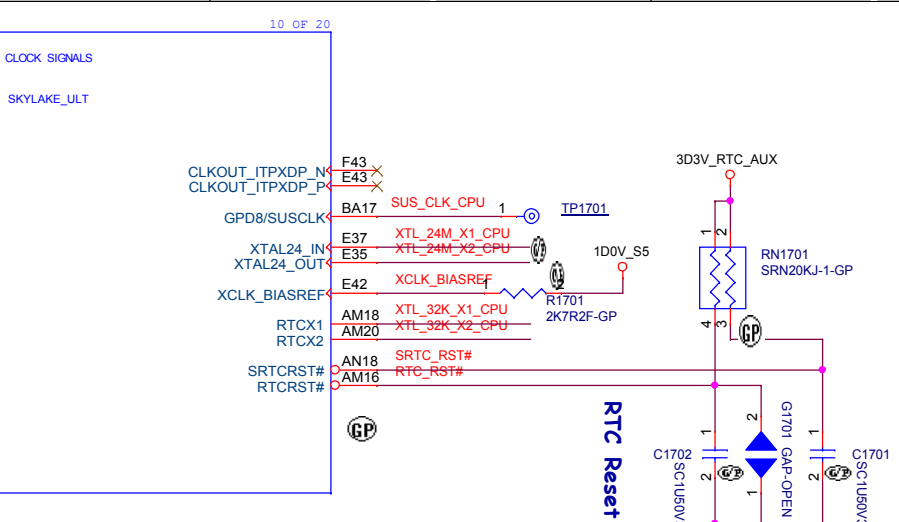
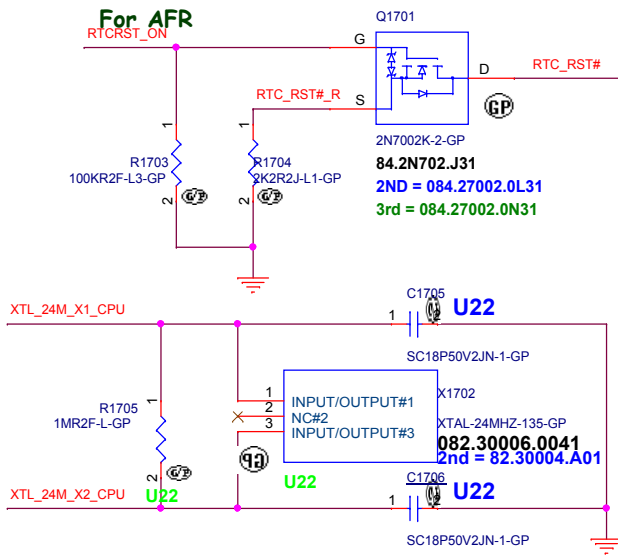


DIS

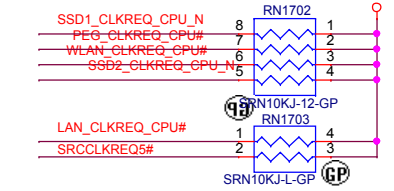
WLAN

NGFF1

CPU



close to CPU



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		21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih, Taipei Hsien 221, Taiwan, R.O.C.	
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MCP_CLOCK			
Size	Document	Number	Rev
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Date:	Monday, January 15, 2018		Sheet 17 of 106

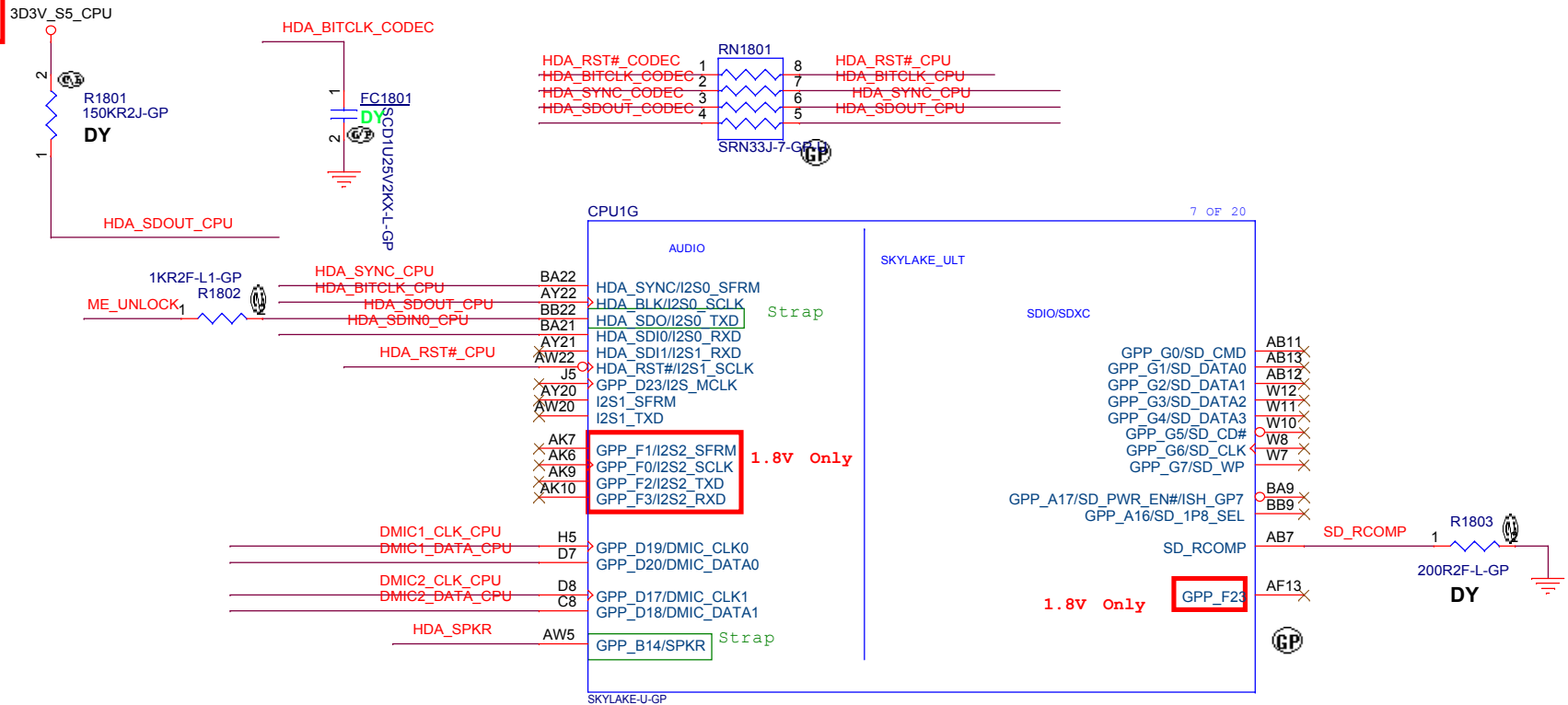
Main Func = PCH

Audio Code

[27] HDA_SDOUT_CODEEC <<<<—
[27] HDA_SDIN0_CPU <<<<—
[15,27] HDA_SPKR <<<<—
[27] HDA_RST#_CODEEC <<<<—

[24] ME_UNLOCK <<<<—
[27] HDA_SYNC_CODEEC <<<<—
[27] HDA_BITCLK_CODEEC <<<<—

[55] DMIC2_DATA_CPU <<<<—
[55] DMIC1_DATA_CPU <<<<—
[55] DMIC1_CLK_CPU <<<<—
[55] DMIC2_CLK_CPU <<<<—



18.3 Terminating Unused SDXC Signals

SDXC signals are multiplexed with GPIOs and default to GPIO functionality (as input). If SDXC interface is not used, the signals can be used as GPIOs instead. If the GPIO functionality is also not used, the signals can be left as no-connect.

Additionally, if SDXC interface is not used, the SD_RCOMP pin does not need to be connected to a RCOMP resistor.

<Core Design>

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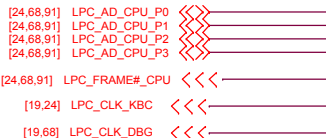
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Size Document Number **Strongbow_KL** Rev **1**

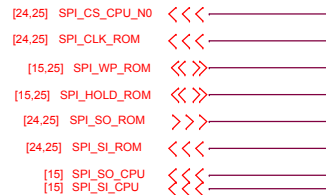
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Main Func = PCH

LPC



SPI



DM1&2 TPAD and XDP

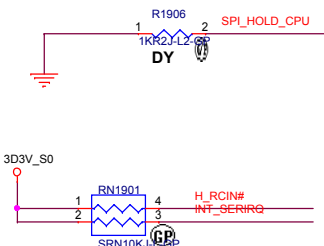
KBC



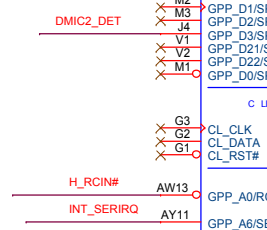
Memory

Audio Codec

KBC/GPU



CPU



Processor Interface	RCIN#	Keyboard Controller Reset Processor: The keyboard controller can generate INIT# to the processor. This saves the external OR gate with the processor other sources of INIT#. When the processor detects the assertion of this signal, INIT# is generated for 16 PCI clocks.

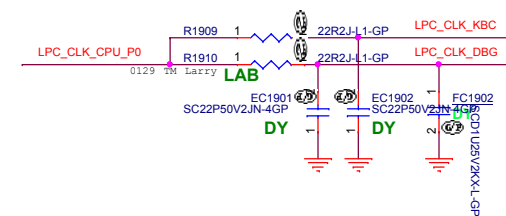
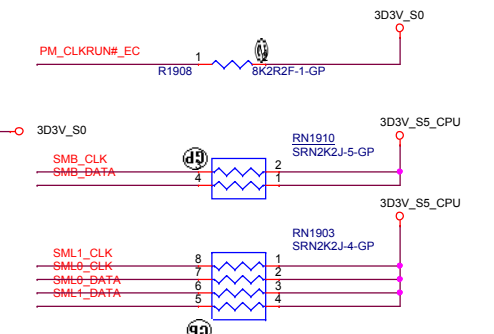
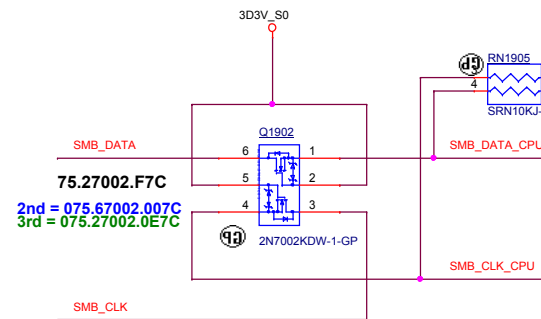
20.9 Serial Interrupt

The PCH supports a serial IRQ scheme. This allows a single signal to be used to report interrupt requests. The signal used to transmit this information is shared between the PCH and all participating peripherals. The signal line, SERIRQ, is synchronous to 24 MHz CLKOUT_LPC, and follows the sustained tri-state protocol that is used by all PCI signals. This means that if a device has driven SERIRQ low, it will first drive it high synchronous to PCI clock and release it the following PCI clock. The serial IRQ protocol defines this sustained tri-state signaling in the following fashion:

- S - Sample Phase**, Signal driven low
- R - Recovery Phase**, Signal driven high
- T - Turn-around Phase**, Signal released

The PCH supports a message for 21 serial interrupts. These represent the 15 ISA interrupts (IRQ0-1, 3-15), the four PCI interrupts, and the control signals SMI# and IOCHK#. The serial IRQ protocol does not support the additional APIC interrupts (20-23).

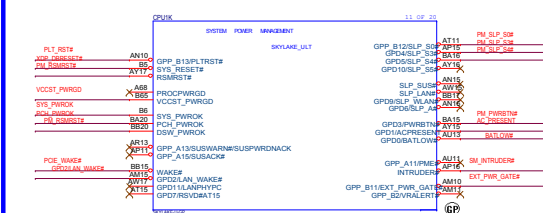
Note: IRQ14 and IRQ15 are special interrupts and maybe used by the GPIO controller when it is running GPIO driver mode. When the GPIO controller operates in GPIO driver mode, IRQ14 and IRQ15 shall not be utilized by the SERIRQ stream nor mapped to other interrupt sources, and instead come from the GPIO controller. If the GPIO controller is entirely in ACPI mode, these interrupts can be mapped to other devices accordingly.



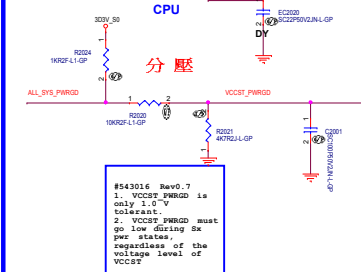
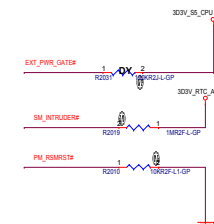
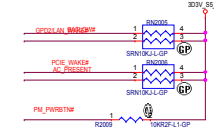
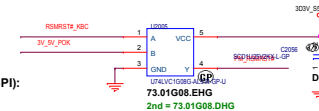
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Title LPC,SPI,SMBUS,CLINK	
Size Custom	Document Number Strongbow_KL
Date: Monday, January 15, 2018	Sheet 19 of 106

```
[p4] SYS_PWR0K >>>
[p4] PCH_PWR0K >>>
[161.63.00] PCH_PWR0K# >>>
[p4.05] ALL_SYS_PWR0K >>>
[p4.01.63.06.79.99.91] PLT_RST# <<<
[p4] RSMRST#_K1C >>>
[45.03] 3V_0V_P0K >>>
[p4.04.58] PM_SLP_S3# <<<
[p4.04.51] PM_SLP_S4# <<<
[p4] PM_PWRSTW# >>>
[p4] AC_PRESENT >>>
[p4.04.60.91] PM_SLP_S0W >>>
```



BATLOW#:
Pull-up required even if not implemented.



Name	Internal Pull-Up/ Pull-Down (Note 1)	De-Glitch (Note 2)		Multiplexed With	Default
		Input	Output		
GPP_A13	None	No	Yes	LPC mode: SUS_WARRN#/ SUSPWRRACK eSPI mode: None	SUS_WARRN#/ SUSPWRRACK (LPC mode) GPI (eSPI mode)
GPP_A14	None	No	Yes	LPC mode: SUS_STAT# eSPI mode: ESPI_RESET#	SUS_STAT# (LPC mode) ESPI_RESET# (eSPI mode)
GPP_A15	None	No	Yes	LPC mode: SUS_ACK# eSPI mode: None	SUS_ACK# (LPC mode) GPI (eSPI mode)

VR

M1

M2

M_{CSU}

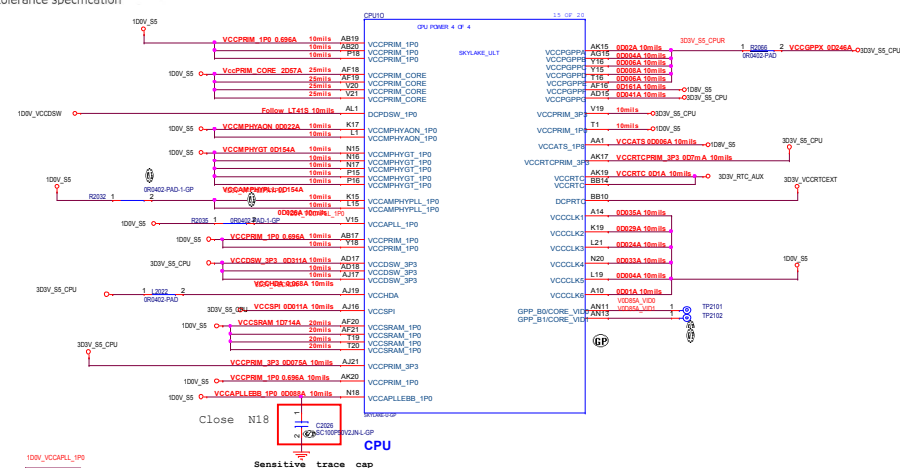
CPU

$R_F = 1Kohm$

$R_D = 60ohm$

VccST

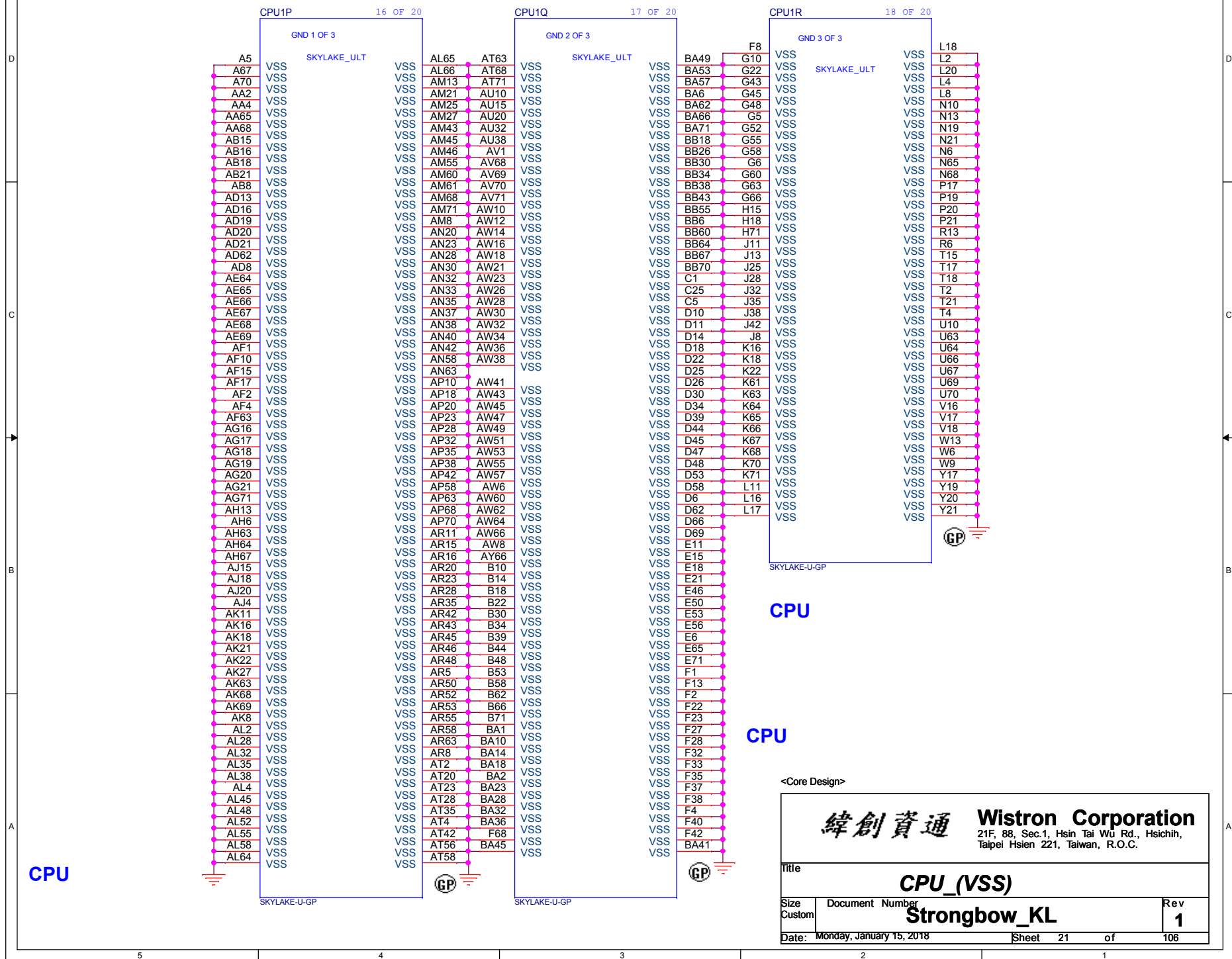
- **VCCST_PWRGOOD** is a signal on the processor that indicates both the **VCCST power supply** and **VDDQ power supply** are within voltage tolerance specification



SKL_PCH Pin Name	Direction	LPC Signal	eSPI Signal	Pin Description
GPP_A_0	in	RCINB	<GPIO>	
GPP_A_1	inout	LAD_0	ESPL_IO_[0]	LPC Cmd/Addr/Data or eSPI Data [0]
GPP_A_2	inout	LAD_1	ESPL_IO_[1]	LPC Cmd/Addr/Data or eSPI Data [1]
GPP_A_3	inout	LAD_2	ESPL_IO_[2]	LPC Cmd/Addr/Data or eSPI Data [2]
GPP_A_4	inout	LAD_3	ESPL_IO_[3]	LPC Cmd/Addr/Data or eSPI Data [3]
GPP_A_5	out	LFRAMEB	ESPL_C5B	LPC Frame or eSPI Chip Select
GPP_A_6	inout	SERIRQ	<GPIO>	
GPP_A_7	iod	PIRQAB	<GPIO>	
GPP_A_9	out	LPC_CLKOUT_0	ESPL_CLK	
GPP_A_14	out	SUS_STATB	ESPI_RESETB	
GPP_C5_SM LART5B	input	ESPL_EN Pin Strap		eSPI Enable Pin Strap; sampled at RMRST# deassertion 0: LPC; 1: eSPI
VCCPGPFA	-	3.3V	1.8V	Voltage for all GPIOs in GPP_A group

NOTE: All pin mappings are subject to change. Refer to the SKL-PCH EDS for final pin list

Main Func = PCH



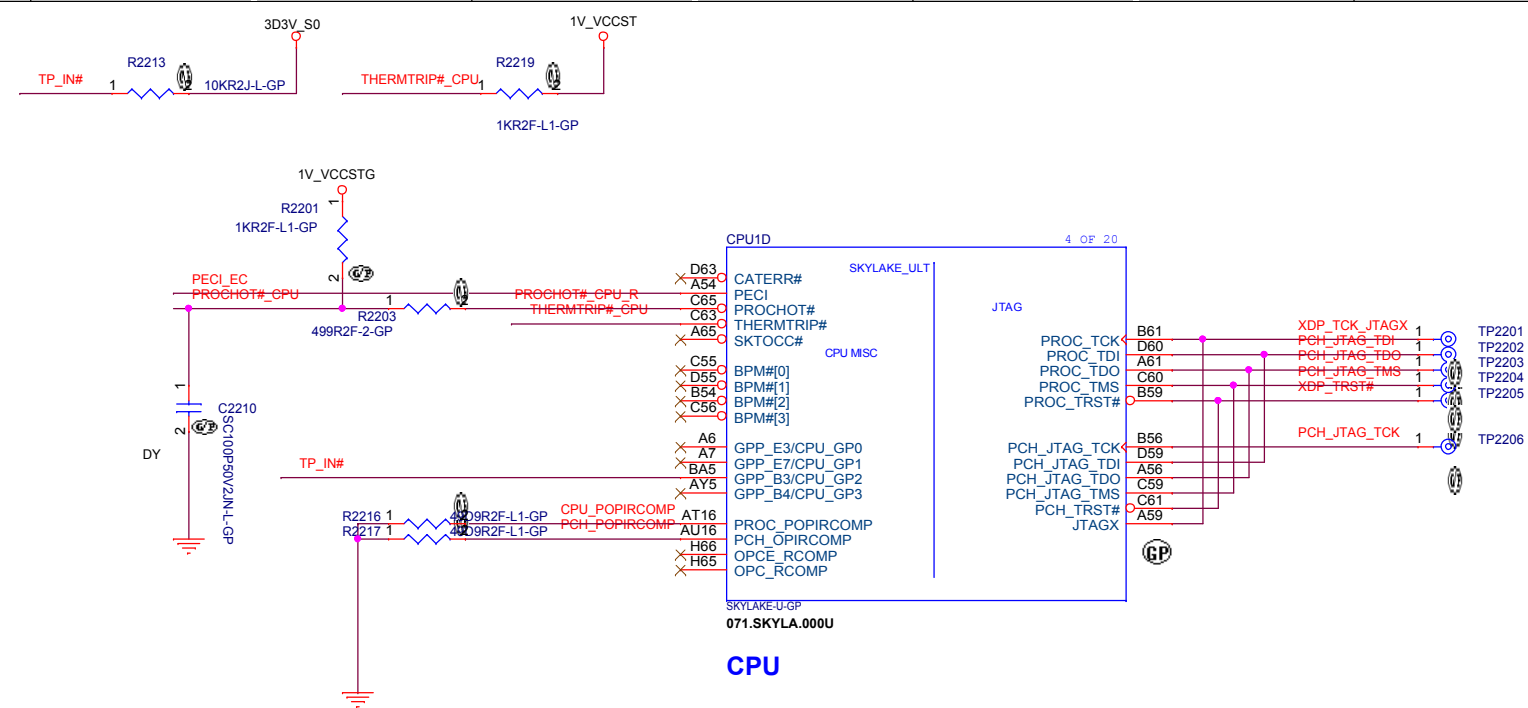
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Title CPU_(VSS)	
Size Custom	Document Number Strongbow_KL
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Sheet 21 of 106	

Main Func = CPU

[24] PECI_EC << >>—
[24,44,46] PROCHOT#_CPU << >>—

[65] TP_IN# >>> —



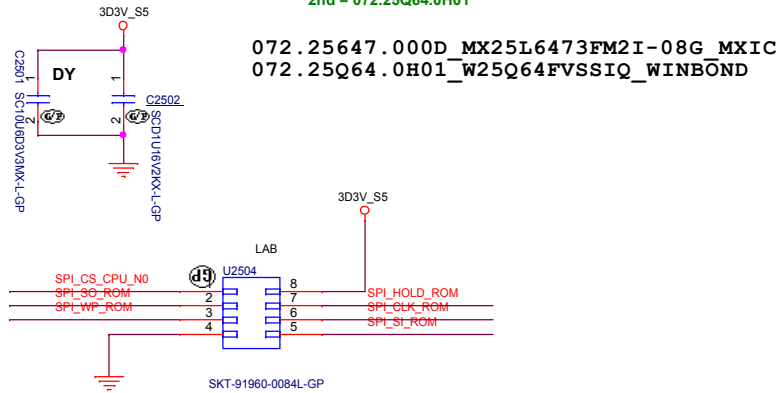
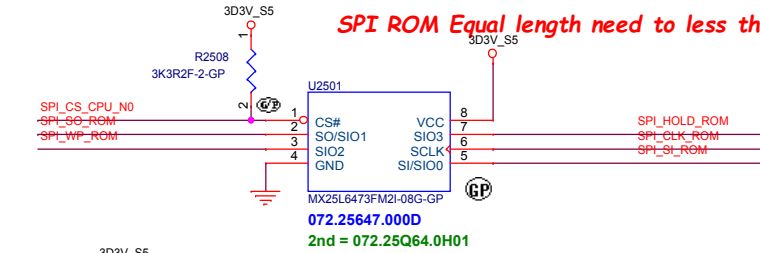
PROCHOT#	Processor Hot: PROCHOT# goes active when the processor temperature monitoring sensor(s) detects that the processor has reached its maximum safe operating temperature. This indicates that the processor Thermal Control Circuit (TCC) has been activated, if enabled. This signal can also be driven to the processor to activate the TCC.	I/O	GTL I OD 0	SE	All processor lines
THERMTRIP#	Thermal Trip: The processor protects itself from catastrophic overheating by use of an internal thermal sensor. This sensor is set well above the normal operating temperature to ensure that there are no false trips. The processor will stop all executions when the junction temperature exceeds approximately 130 °C. This is signaled to the system by the THERMTRIP# pin. Refer to the appropriate platform design guide for termination requirements.	0	OD	SE	All processor lines

<Core Design>

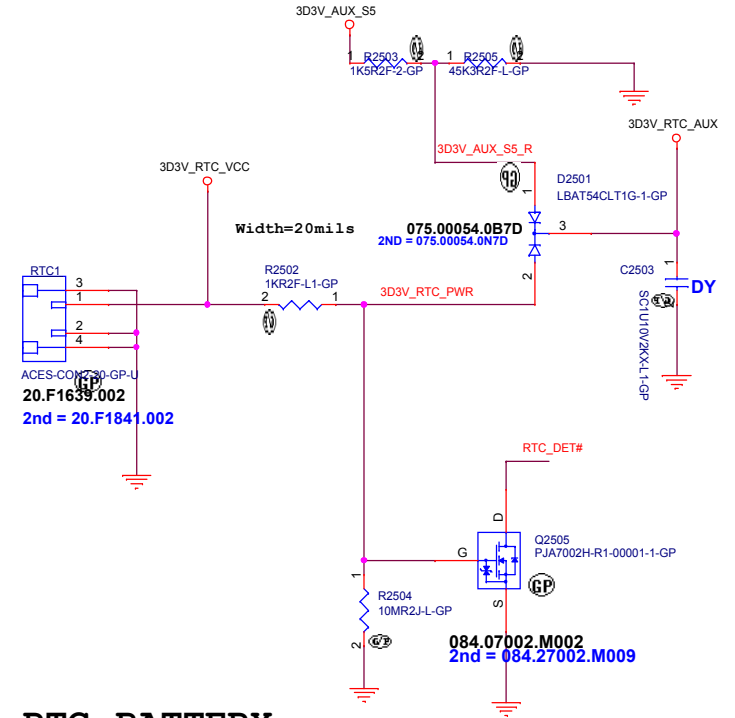
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Title CPU_(JTAG/CPU SIDE BAND)			
Size Custom	Document Number	Strongbow KL	Rev 1
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[19,24] SPI_CS_CPU_N0
[19,24] SPI_SO_ROM
[15,19] SPI_WP_ROM

[15,19] SPI_HOLD_ROM
[19,24] SPI_CLK_ROM
[19,24] SPI_SI_ROM
[6] RTC_DET#



Main Func = RTC



RTC BATTERY
1st= TBD
2nd= TBD

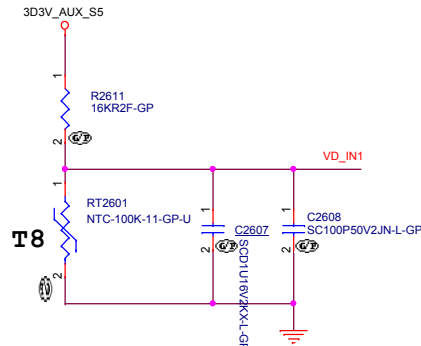
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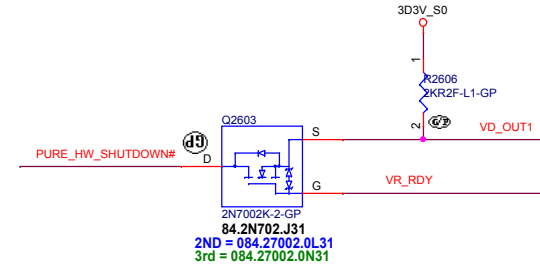
Title			Flash(KBC+PCH)/RTC	
Size	Document	Number	Rev	
Custom	Strongbow KL		1	
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SSID = Thermal

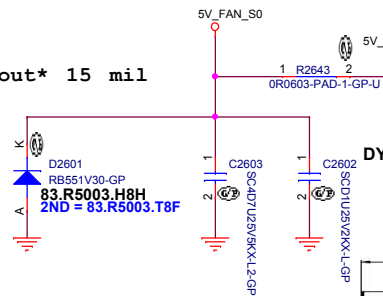
[24] VD_IN1 <<< _____
[24] FAN1_PWM >>> _____
[24] FAN_TACH1 <<< _____
[24] FAN_TACH1_C <<< _____
[24,40] PURE_HW_SHUTDOWN# <<< _____
[24] VD_OUT1 >>> _____
[40,46] VR_RDY >>> _____
[20,24,40,58] PM_SLP_S3# >>> _____



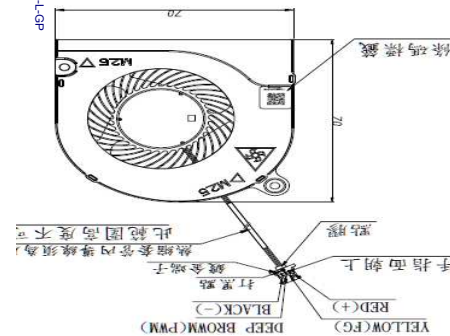
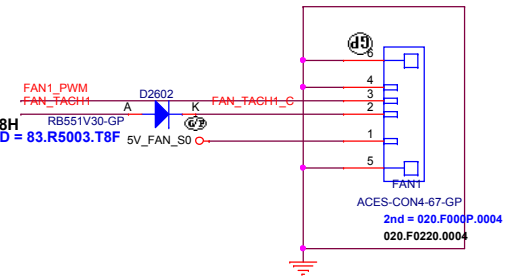
RT2601 close CPU and Vcore chock
VD_IN1 trace 10 mli



Layout 15 mil



83.R5003.H8H
2ND = 83.R5003.T8F



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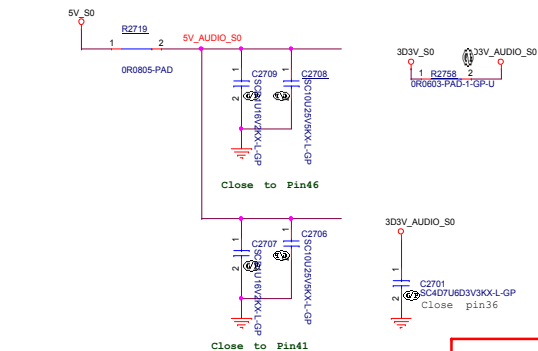
Title		Thermal 7718/Fan Controller P2793	
Size	Document	Number	Rev
Custom	Strongbow KL		1
Date:	Monday, January 15, 2018	Sheet	26 of 106

```

[18] HDA_BITCLK_CODEC _____
[18] HDA_SYNC_CODEC _____
[18] HDA_SDIN0_CPU _____
[18] HDA_SSDIN0_CODEC _____
[18] HDA_RST#_CODEC _____

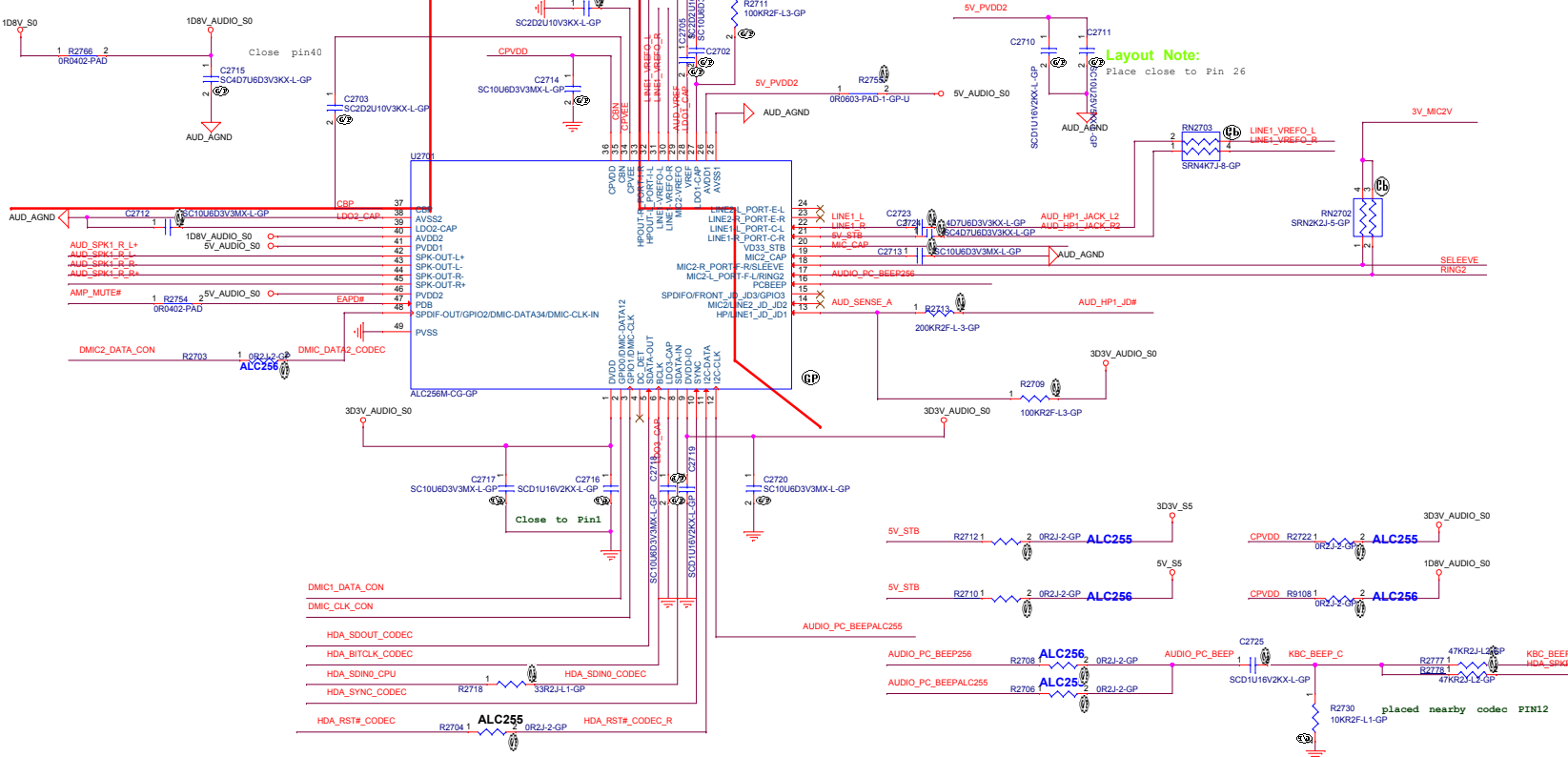
[24] AMP_MUTE# _____
[55] DMIC2_DATA_CON _____
[55] DMIC_CLK_CON _____
[55] DMIC2_DATA_CON _____
[29] AUD_HP1_JACK_L2 _____
[29] AUD_HP1_JACK_R2 _____
[29] AUD_HP1_JOM _____
[29] RING2 _____
[29] SELEEVE _____
[24] KBEC_BSP _____
[15,19] HDA_SPKR _____
(29,8) AUD_SPK1_R_L+ _____
(29,8) AUD_SPK1_R_L- _____
(29,8) AUD_SPK1_R_R+ _____
(29,8) AUD_SPK1_R_R- _____

```



Fix $V_{out}=1.5V$
 $I_{max}=300mA$
 $OCP = 400mA$

Layout Note:
Place close to Pin 26



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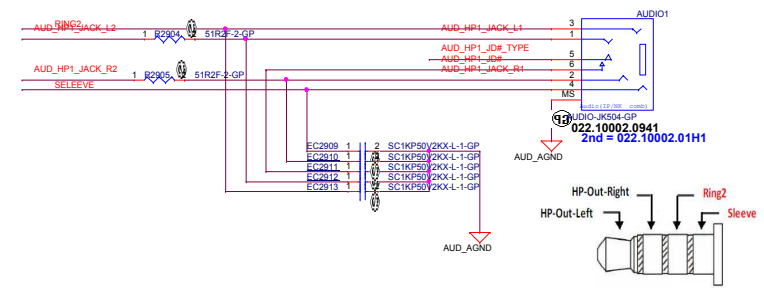
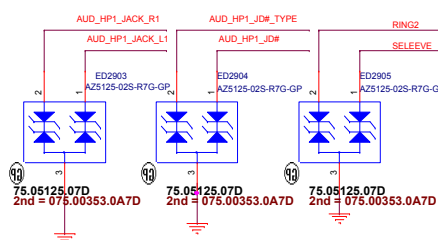
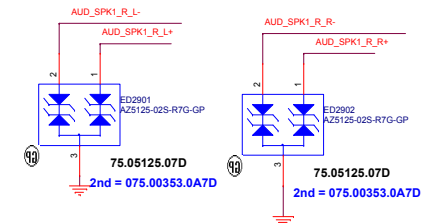
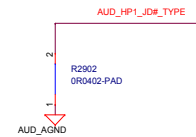
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Audio Codec ALC256			
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RTS5170(CARD READER)

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SSID = SDIO

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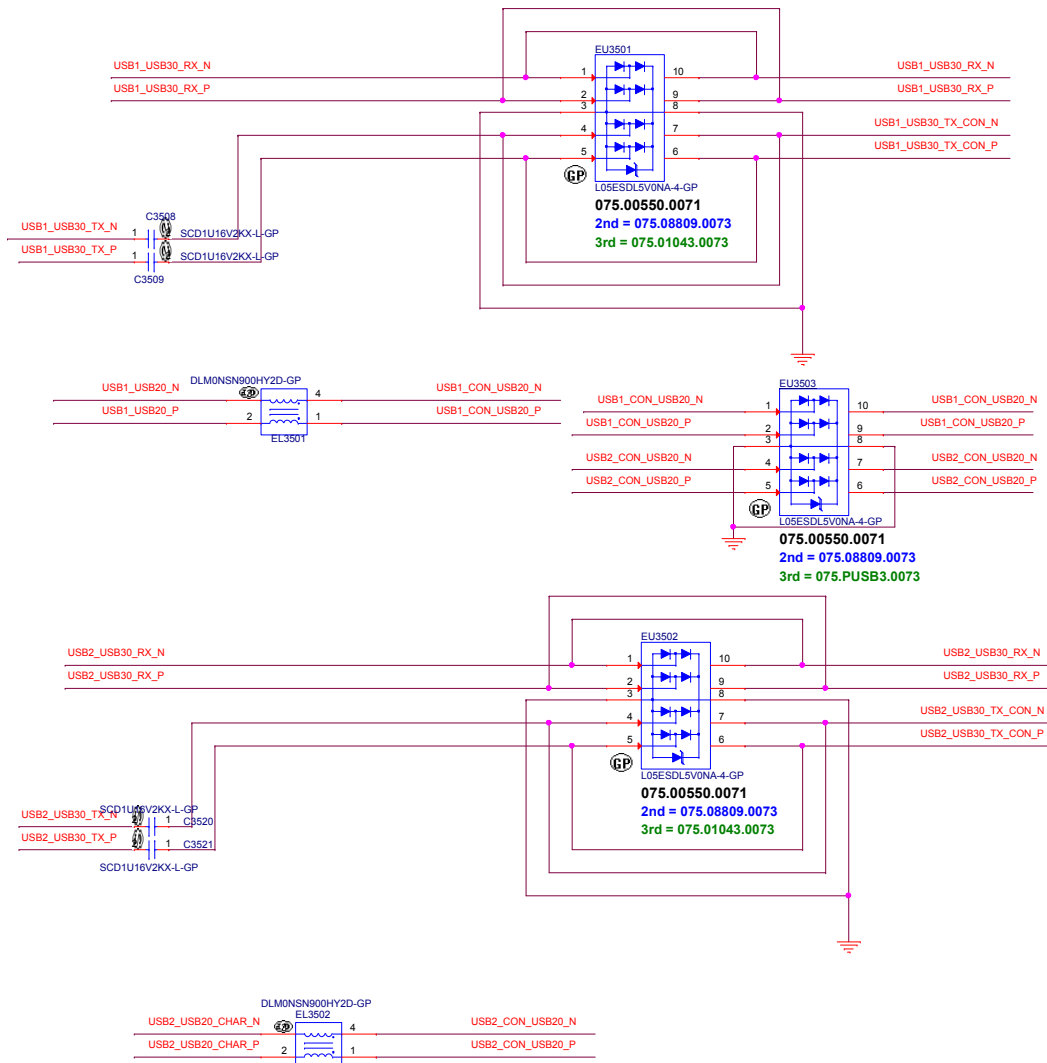
[16] USB1_USB20_N << >>
[16] USB1_USB20_P << >>
[24,66] USB_PWR_EN << >>
[16] USB1_USB30_RX_N << >>
[16] USB1_USB30_RX_P << >>
[16] USB1_USB30_TX_N << >>
[16] USB1_USB30_TX_P << >>

[89] USB1_CON_USB20_N << >>
[89] USB1_CON_USB20_P << >>

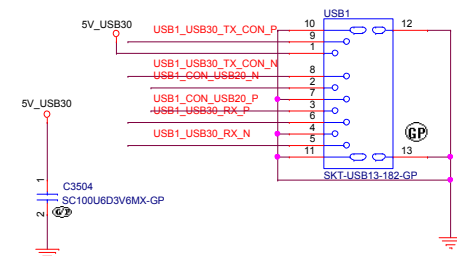
[36] USB2_USB20_CHAR_N << >>
[36] USB2_USB20_CHAR_P << >>

[16] USB2_USB30_RX_N << >>
[16] USB2_USB30_RX_P << >>
[16] USB2_USB30_TX_N << >>
[16] USB2_USB30_TX_P << >>

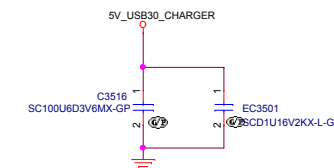
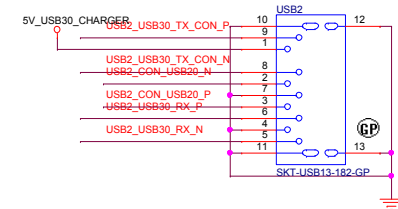
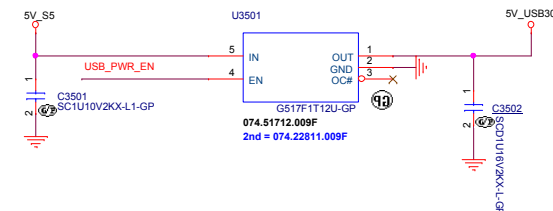
[89] USB2_CON_USB20_N << >>
[89] USB2_CON_USB20_P << >>



USB 3.0 Connector Pin definition	
1	POWER
2	USB 2.0 D-
3	USB 2.0 D+
4	GND
5	StdA_SSRX- SuperSpeed RX
6	StdA_SSRX+
7	GND
8	StdA_SSTX- SuperSpeed TX
9	StdA_SSTX+



High Active 2A



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Sheet		35 of 109	
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[24] USB_CHARGER_EN >>>

[24] USB_CHAR_SEL >>>

[24] USB_CHAR_CT1 >>>

To Connector

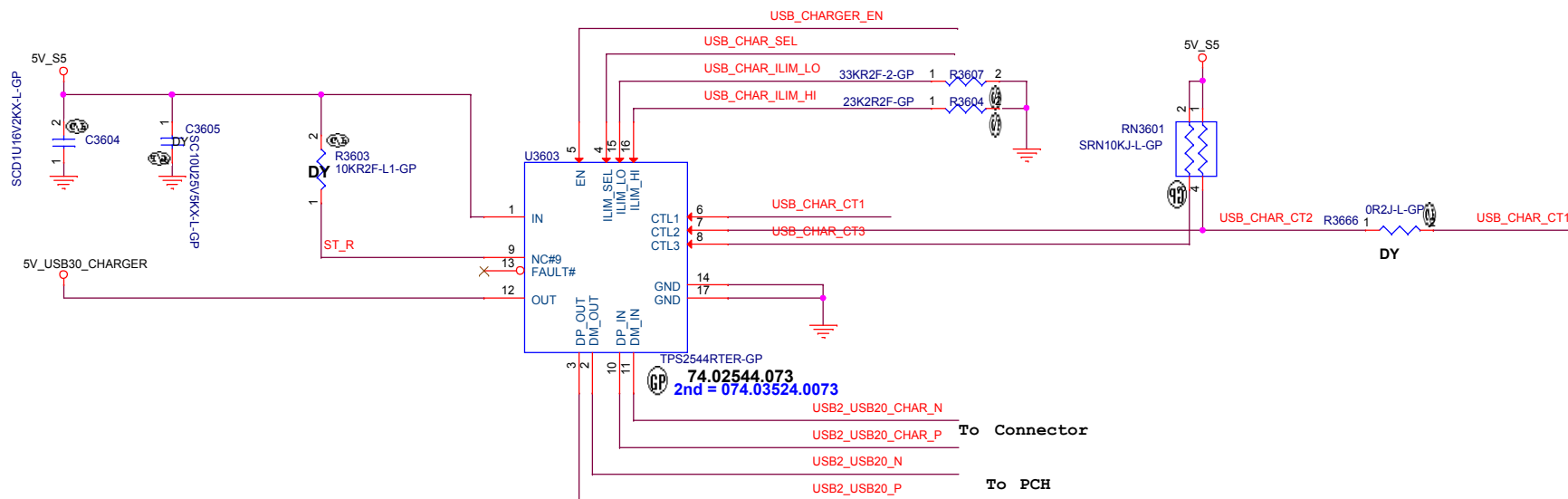
[35] USB2_USB20_CHAR_N <<<

[35] USB2_USB20_CHAR_P <<<

To PCH

[16] USB2_USB20_N <<<

[16] USB2_USB20_P <<<



CTL1	CTL2	CTL3	ILIM_SEL	Mode	Current Limit Setting	Comment
0	0	0	0	Discharge	NA	OUT held low
0	0	0	1	Discharge	NA	
0	0	1	0	DCP_Auto	ILIM_HI	Data Lines Disconnected
0	1	1	X			
0	1	0	0	SDP1	ILIM_LO	Data Lines connected
0	1	0	1		ILIM_HI	
1	0	0	0	DCP Forced Shorted	ILIM_LO	Device Forced to stay in DCP BC 1.2 charging mode
1	0	0	1		ILIM_HI	
1	0	1	0	DCP / Divider1	ILIM_LO	Device Forced to stay in DCP Divider 1 Charging Mode
1	0	1	1		ILIM_HI	
1	1	0	0	SDP1	ILIM_LO	Data Lines Connected
1	1	0	1	SDP1	ILIM_HI	
1	1	1	0	SDP2 ⁽¹⁾	ILIM_LO	
1	1	1	1	CDP ⁽¹⁾	ILIM_HI	Data Lines Connected

S5 (at low bateery and non support charger)

S3 and S5 state

S0 and S3 (at low bateery and non support charger)

S0 state

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USB CHARGER			
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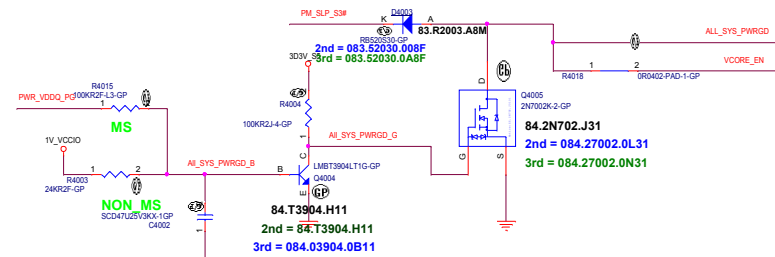
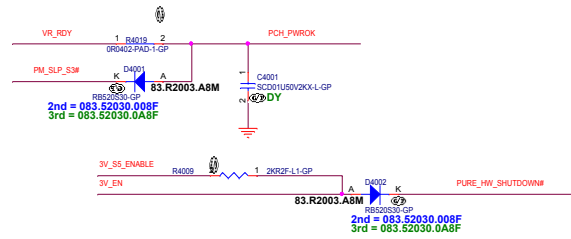
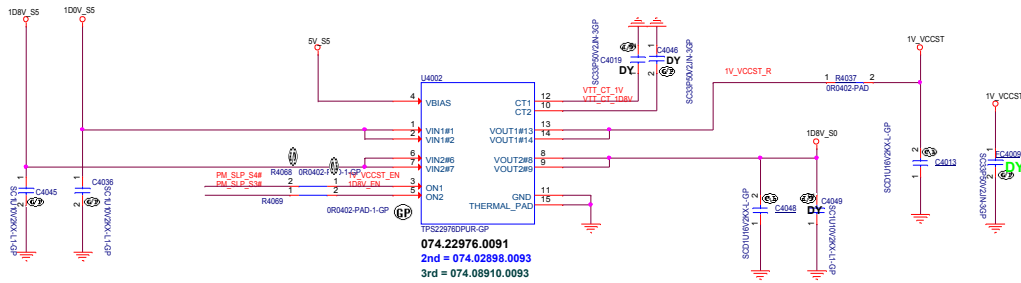
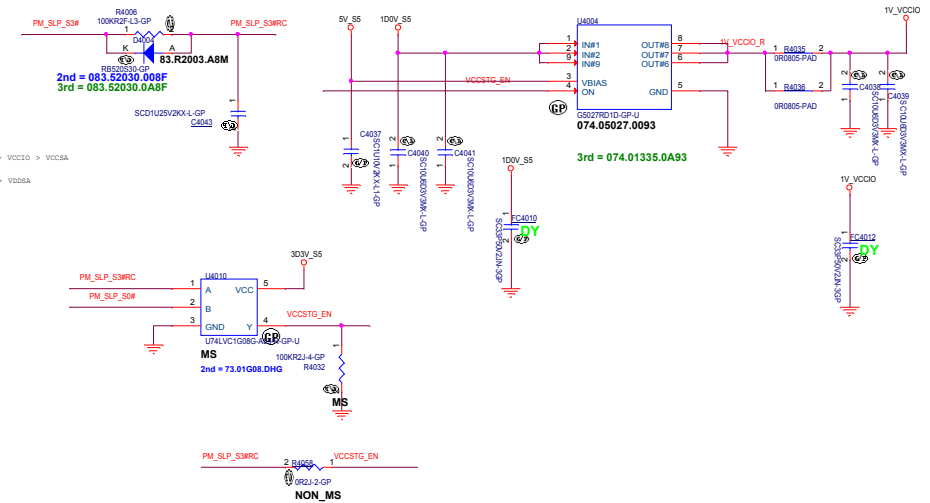
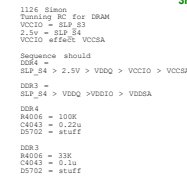
```

[26.46] VR_RDY >>> _____
[20.24.58] PM_SLP_S3# >>> _____
[20] PCH_PWRORK <<< _____
[24] 3V_S5_ENABLE >>> _____
[46] 3V_EN <<< _____

[24.26] PURE_HW_SHUTDOWN# >>> _____
[20.24] ALL_SVS_PWRGOD <<< _____
[46] VCORE_EN <<< _____
[20.24.51] PM_SLP_S4# >>> _____
[20.24.60.91] PM_SLP_S0# >>> _____

[51] PWR_VDDQ_PG >>> _____

```

[illegible]

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Title	Power Plane Enable & SEQUENCE
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緯創資通

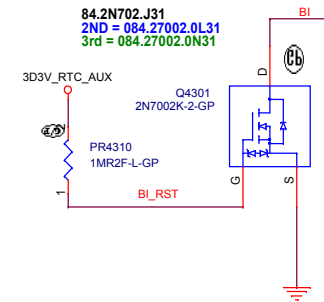
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DCIN JACK

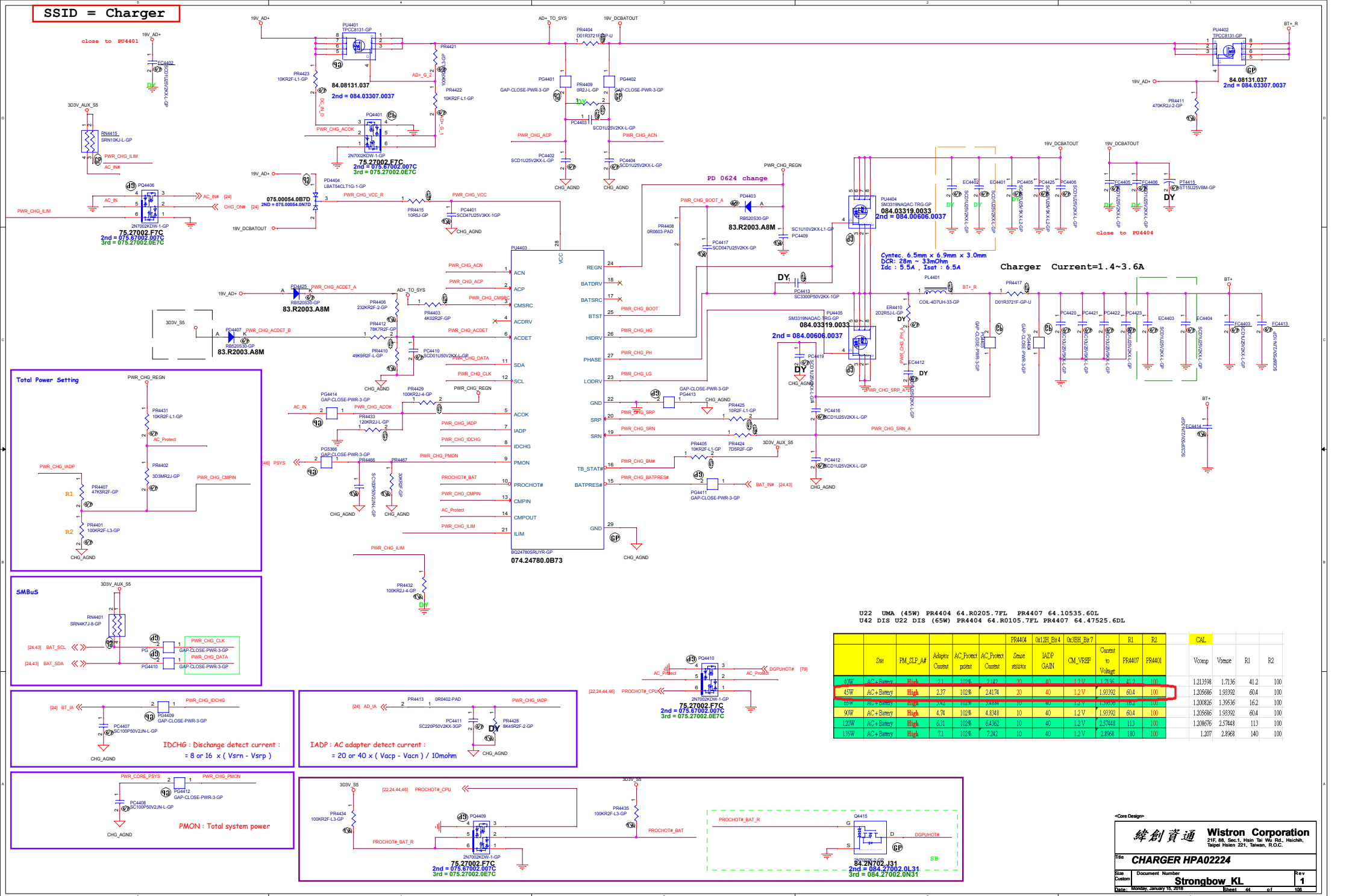
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BATTERY CONNECTOR

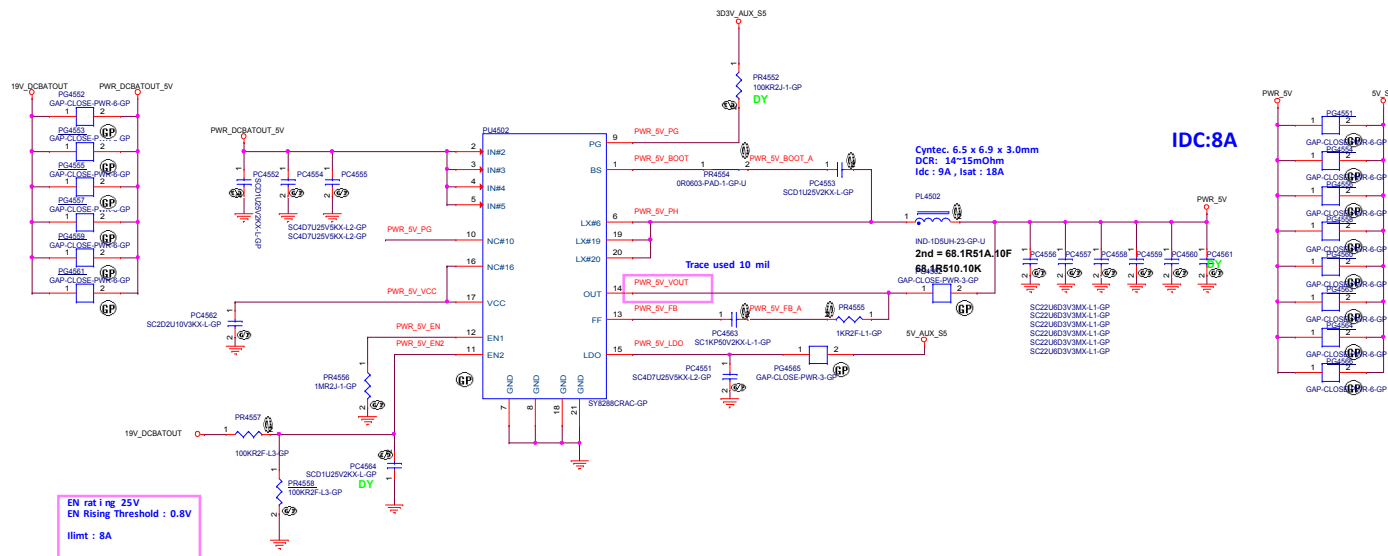


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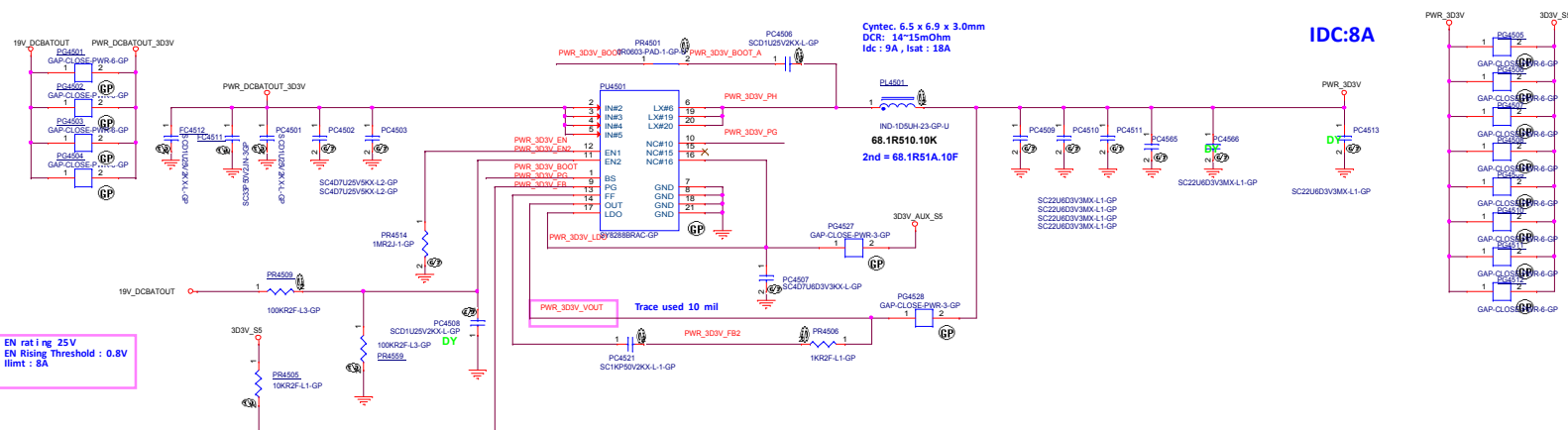
SSID = Charger



[24] 5V EN >>> 2 PR4517 1 PWR_5V_EN



40] 3V EN >>> 2 PR4515 1 PWR_3D3V_EN

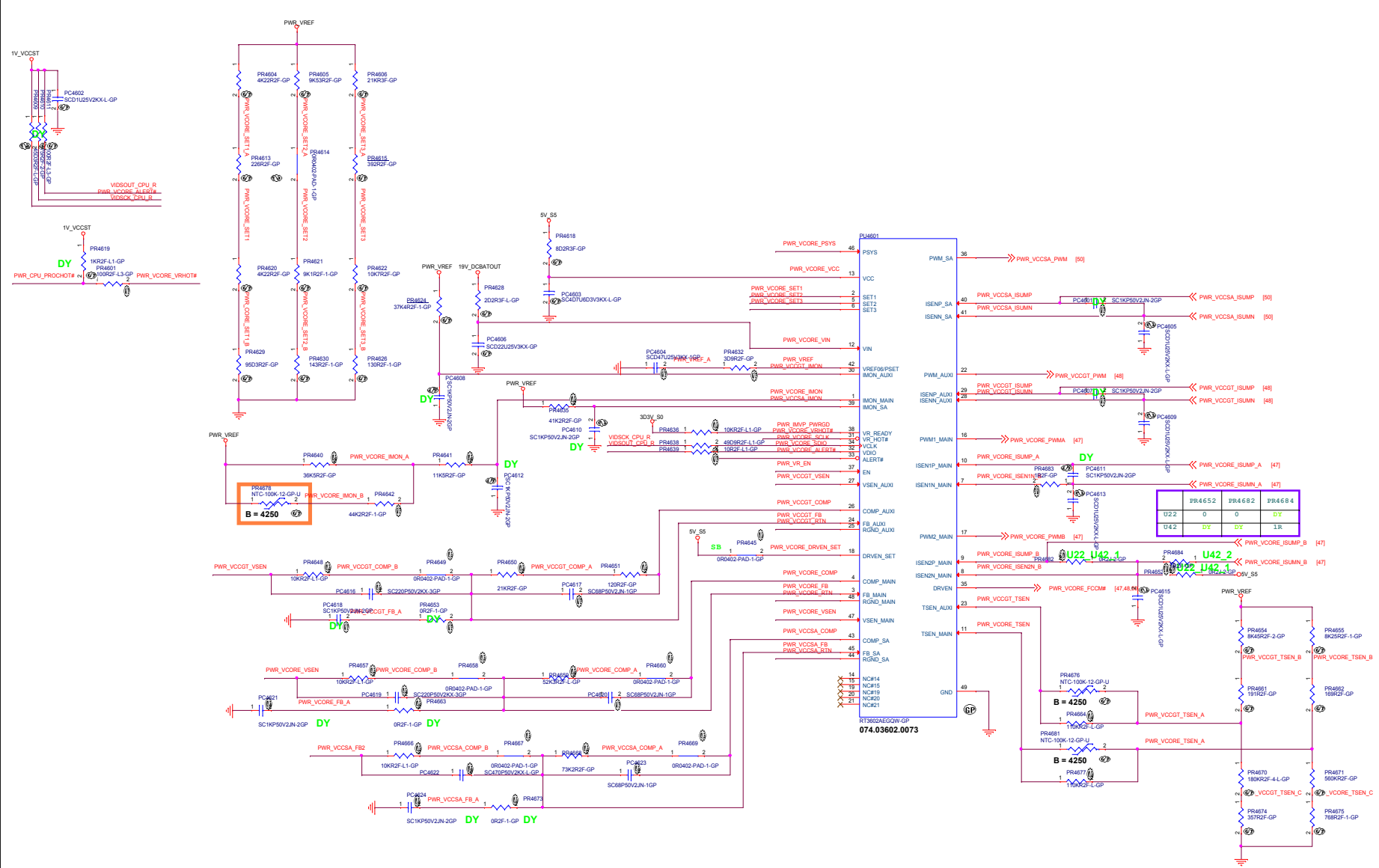
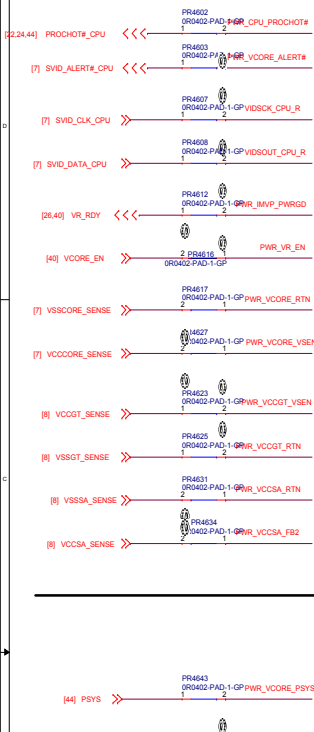


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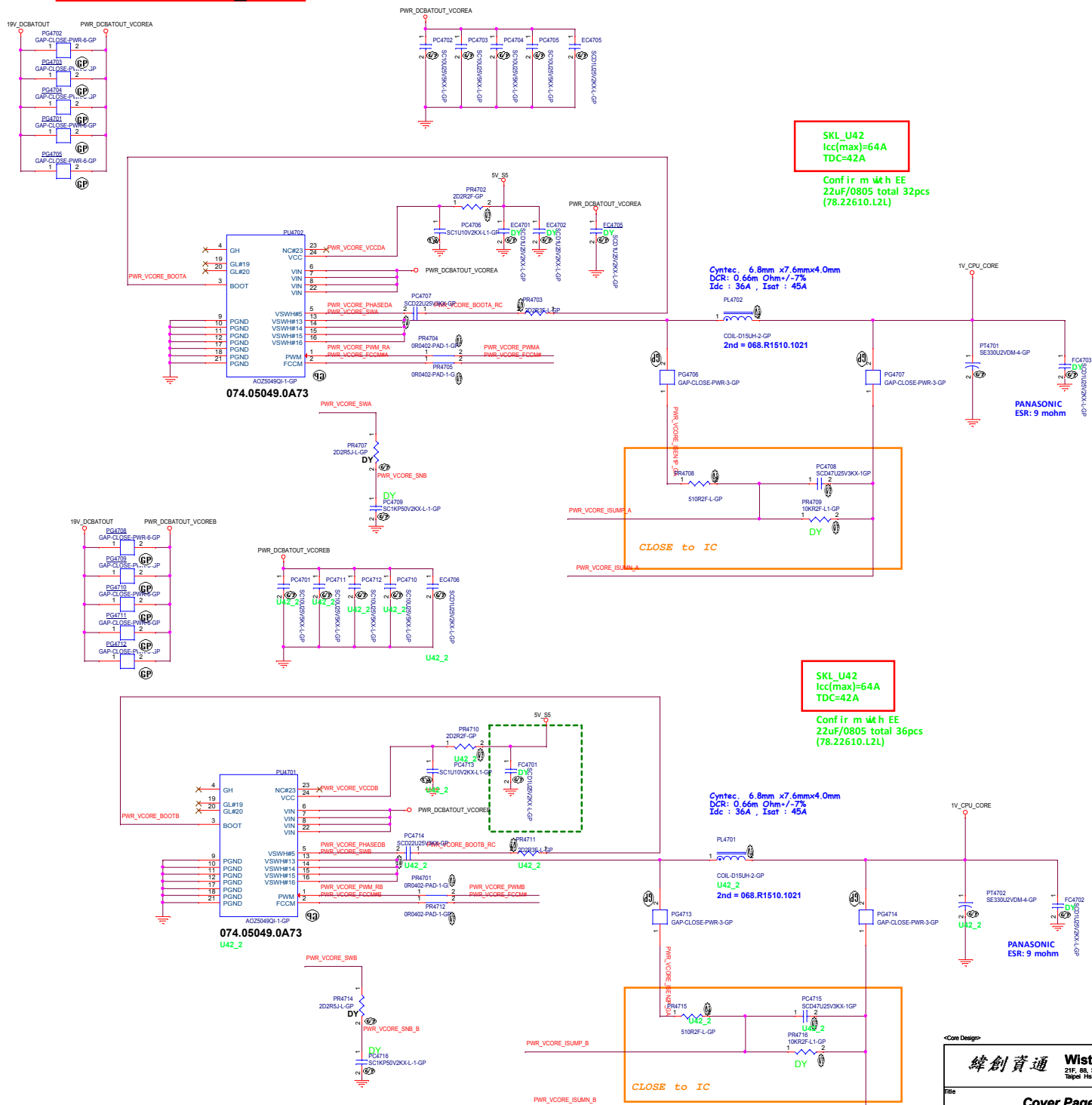
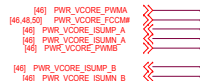
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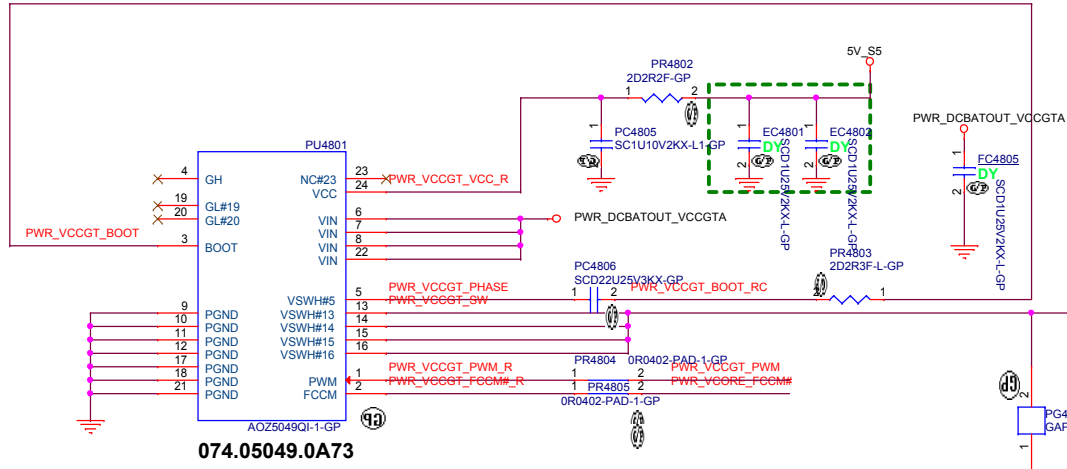
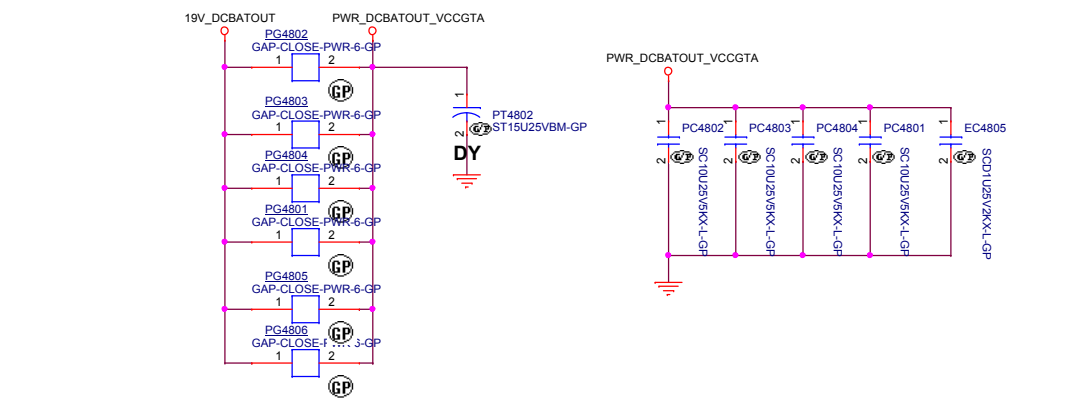


Main Func = CPU CORE



Main Func = CPU_CORE

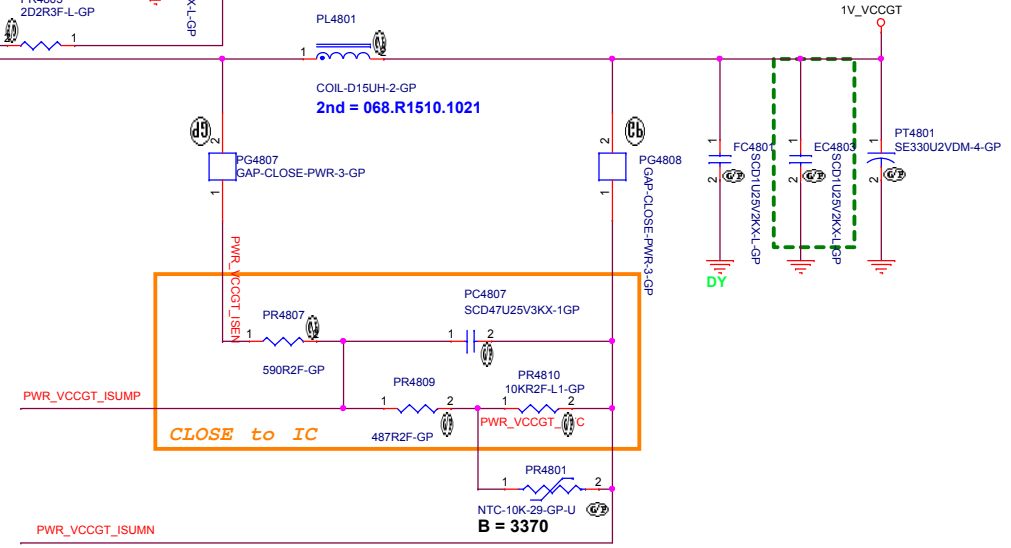
[46] PWR_VCCGT_PWM
[46.47.50] PWR_VCORE_FCCM#
[46] PWR_VCCGT_ISUMP
[46] PWR_VCCGT_ISUMN



SKL_U42
Icc(max)=28A
TDC=12A

Confir m with EE
22uF/0805 total 26pcs
(78.22610.L2L)

Cynotec 6.8mm x7.6mmx4.0mm
DCR: 0.66m Ohm+/-7%
Idc : 36A , Isat : 45A



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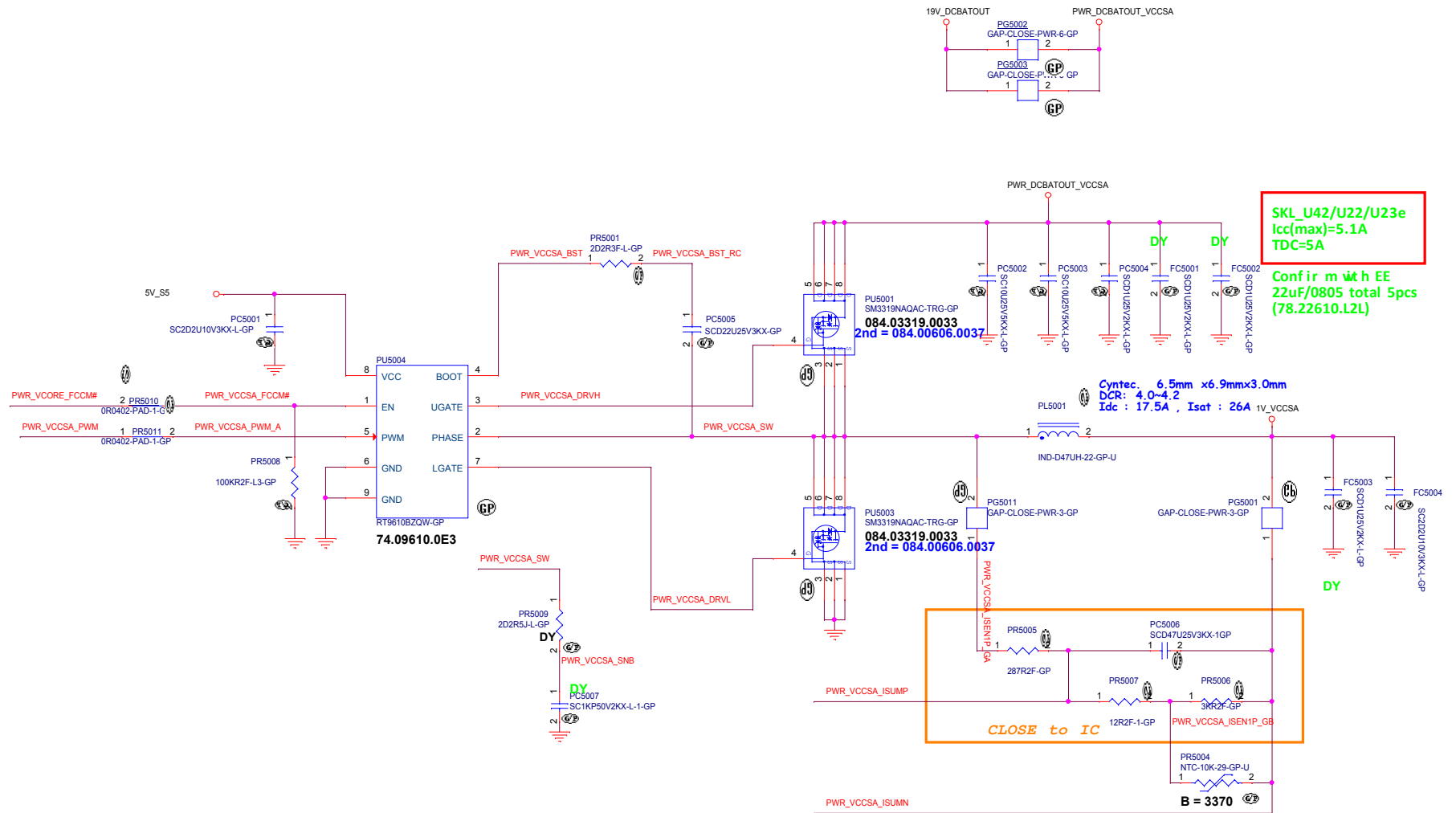
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Main Func = CPU_CORE
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[46,47,48] PWR_WCOORE_FCCM# >>>_____
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[46] PWR_VCCSA_ISUMP <<<_____
[46] PWR_VCCSA_ISUMN <<<_____
```



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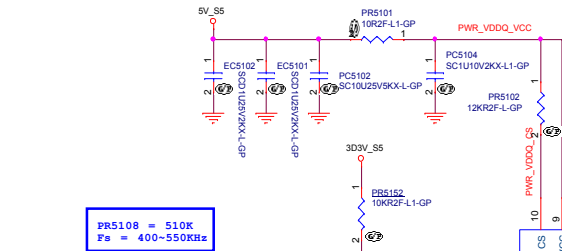
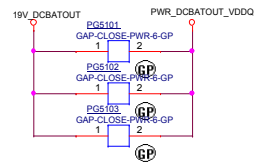
VDDQ ENABLE CONTROL

[H] VTT_CNTL_CPU >>>

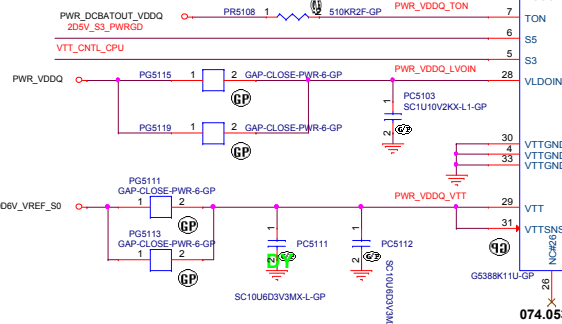
2D5V ENABLE CONTROL

[20,24,40] PM_SLP_S4# >>>

[40] PWR_VDDQ_PG >>>

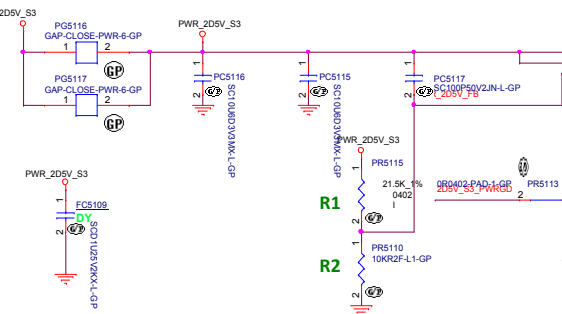


PR5108 = 510K
Fs = 400~550KHz

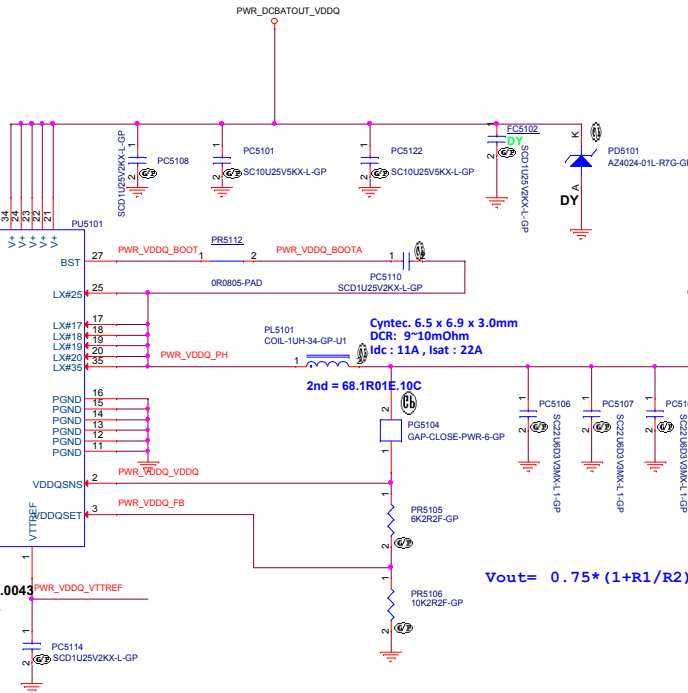


V2D5_S5
MAX=1A

$Pd = (3.3 - 2.5) * 1 = 0.8W$



$Vout = 0.8 * (1 + R1/R2) = 2.52V$



TDC : 8.0A

Cyntec. 6.5 x 6.9 x 3.0mm
DCR: 9*10mOhm
Idc : 11A, Isat : 22A

2nd = 68.1R01E.10C

$Vout = 0.75 * (1 + R1/R2) = 1.2$

2D5V_PWR_GOOD
PWR_2D5V_PG

[53] 1D8V_S5_PWRGD >>



$$V_{out} = 0.75 * (1 + R1/R2) = 1.0V$$

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RT8237 1D0V S5

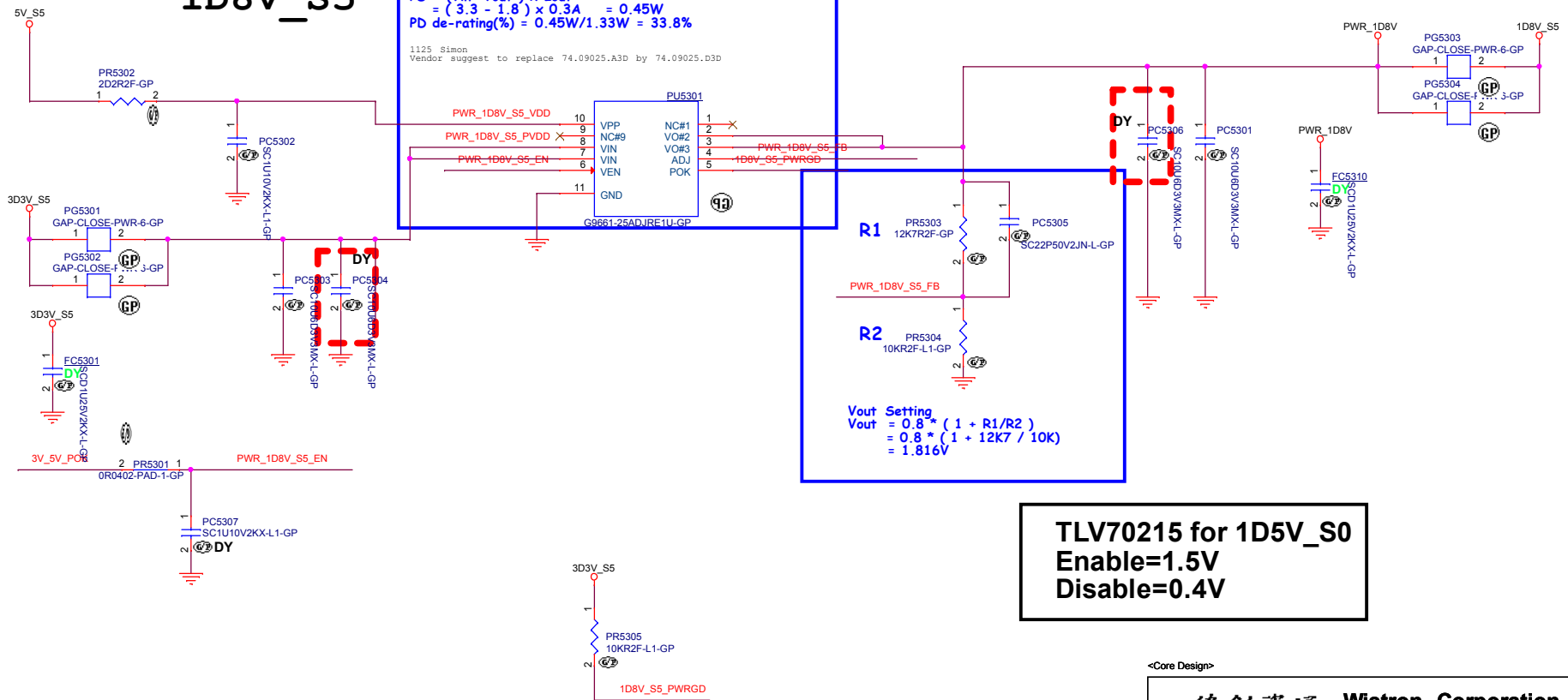
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1D8V_S5

$$\begin{aligned} PD &= (V_{in} - V_{out}) \times I_{out} \\ &= (3.3 - 1.8) \times 0.3A = 0.45W \\ PD \text{ de-rating}(\%) &= 0.45W / 1.33W = 33.8\% \end{aligned}$$

```
1125 Simon
Vendor suggest to replace 74.09025.A3D by 74.09025.D3D
```



TLV70215 for 1D5V_S0
Enable=1.5V
Disable=0.4V

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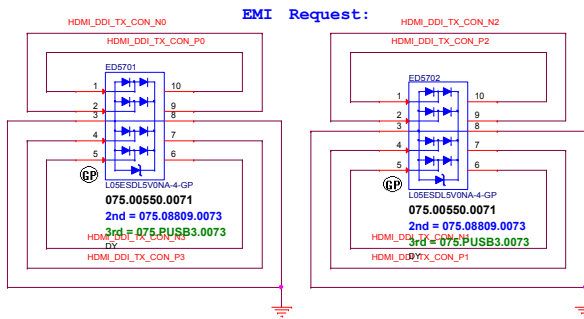
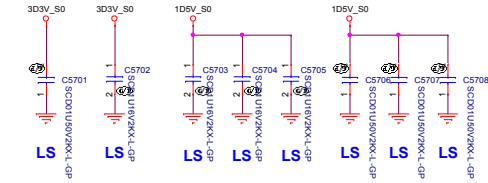
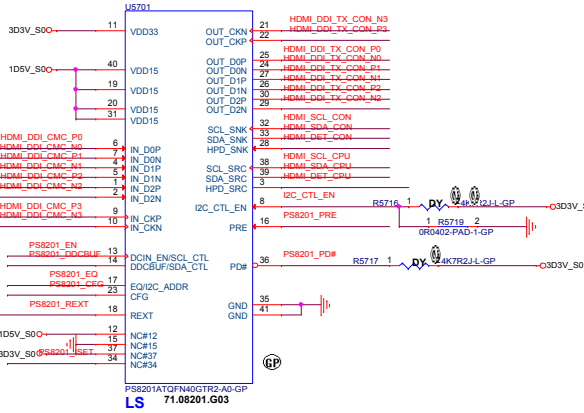
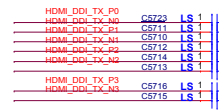
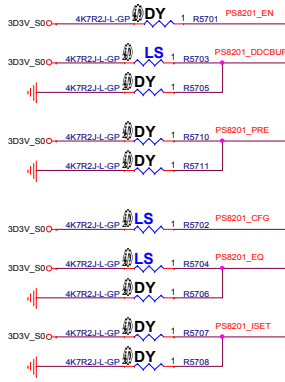
HDMI CONN

HDMI 1.4 & CONNECTOR

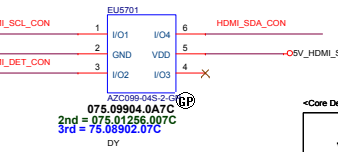
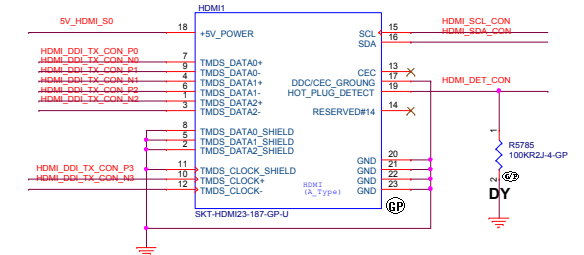
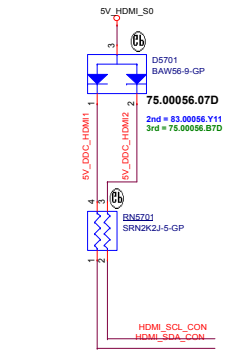
[3] HDMI_DDI_TX_P0
[3] HDMI_DDI_TX_N0
[3] HDMI_DDI_TX_P1
[3] HDMI_DDI_TX_N1
[3] HDMI_DDI_TX_P2
[3] HDMI_DDI_TX_N2
[3] HDMI_DDI_TX_P3
[3] HDMI_DDI_TX_N3
[3,15] HDMI_SCL_CPU
[3,15] HDMI_SDA_CPU
[3] HDMI_DET_CPU <<<

[89] HDMI_DDI_TX_CON_N3
[89] HDMI_DDI_TX_CON_P3

[89] HDMI_DDI_TX_CON_P0
[89] HDMI_DDI_TX_CON_N0
[89] HDMI_DDI_TX_CON_P1
[89] HDMI_DDI_TX_CON_N1
[89] HDMI_DDI_TX_CON_P2
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[89] HDMI_SCL_CON
[89] HDMI_SDA_CON
[89] HDMI_DET_CON <<<



EMI Request:



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HDMI Level Shifter/Connector	
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SSID = SATA



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[illegible]**HDD**

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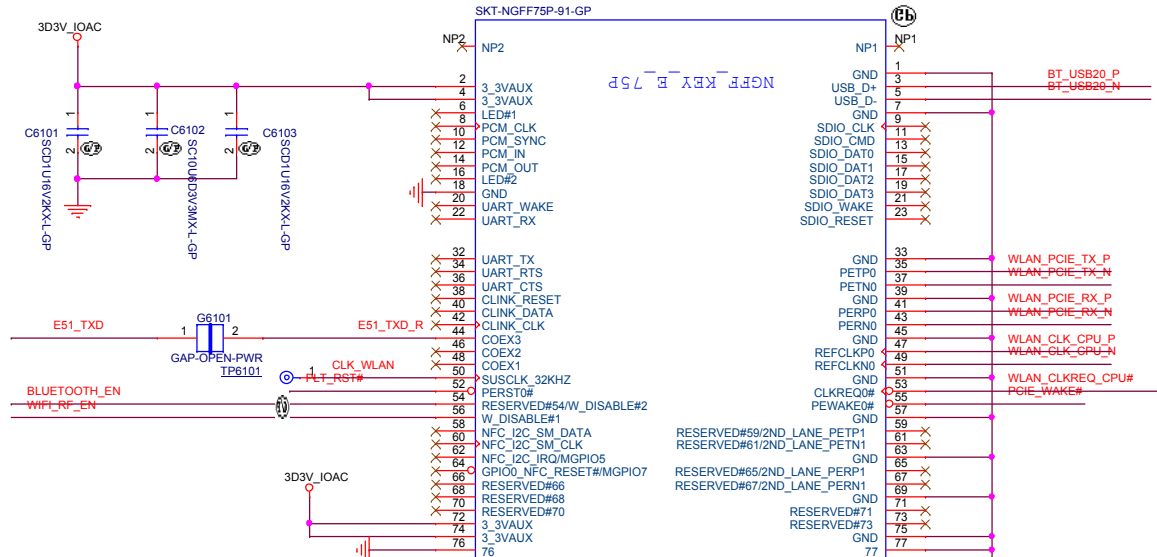
SSID = Wireless

Mini Card Connector(802.11a/b/g/n)

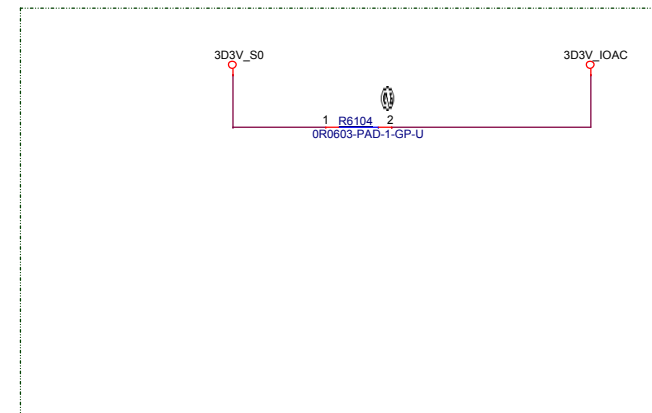
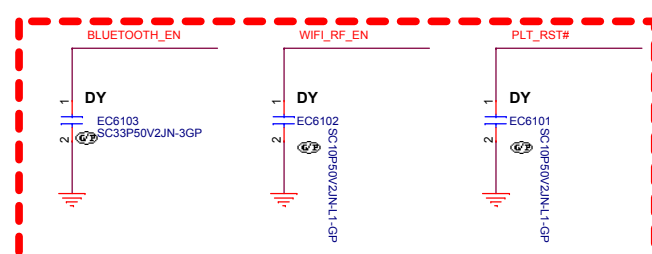
[24,61,68] E51_TXD >>>
[16,89] BT_USB20_P <<<
[16,89] BT_USB20_N <<<
[24,61,68] E51_TXD >>>
[24,89] BLUETOOTH_EN >>>
[24,89] WIFI_RF_EN <<<
[20,24,63,68,79,89,91] PLT_RST# >>>

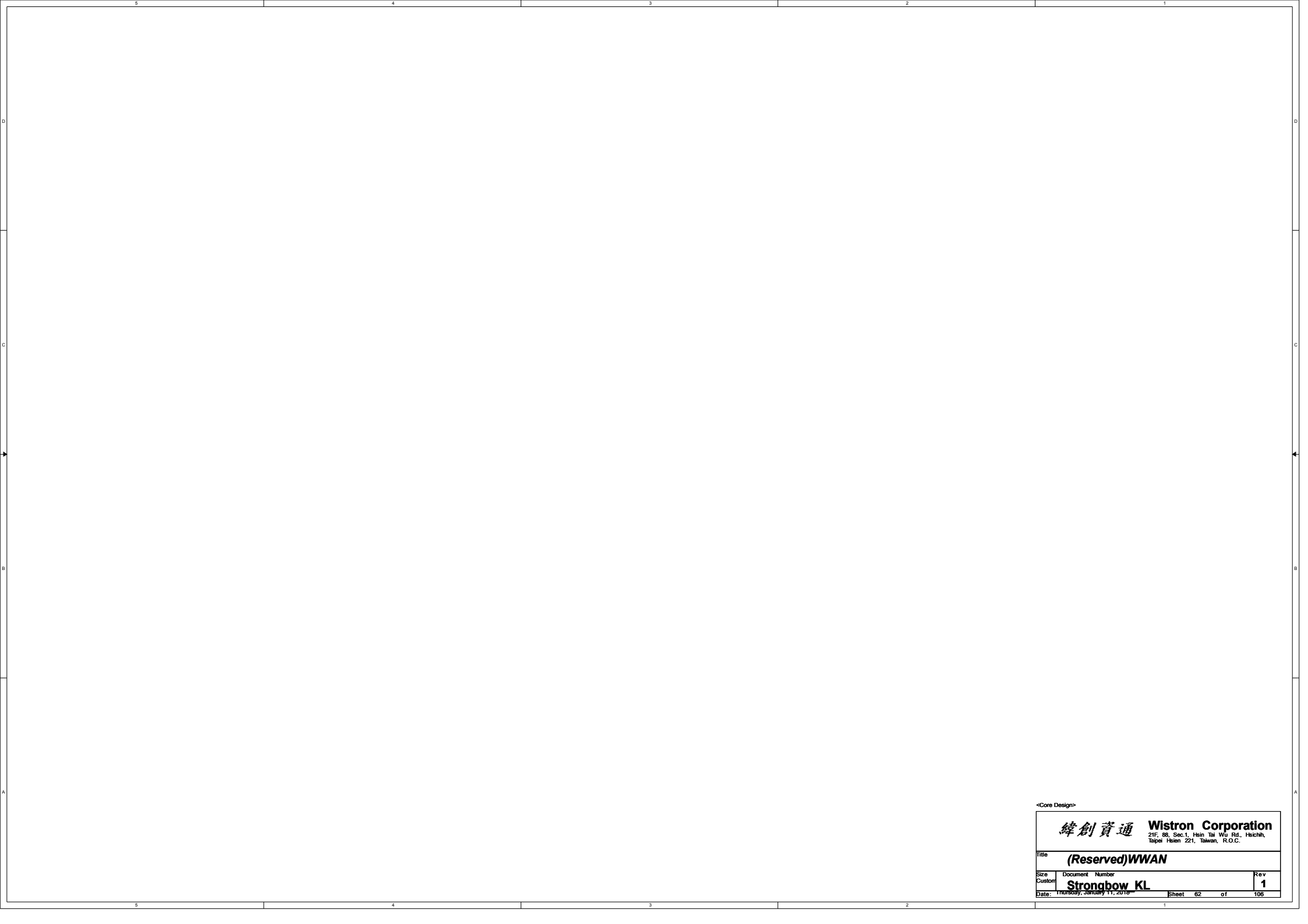
[16,89] WLAN_PCIE_TX_P >>>
[16,89] WLAN_PCIE_TX_N >>>
[16,89] WLAN_PCIE_RX_P <<<
[16,89] WLAN_PCIE_RX_N <<<
[17,89] WLAN_CLK_CPU_P >>>
[17,89] WLAN_CLK_CPU_N >>>

[20,63,89] PCIE_WAKE# <<<
[17,89] WLAN_CLKREQ_CPU# <<<



WLAN1
062.10003.0611
2nd = 062.10003.0C11
3rd = 062.10003.0E31
4th = 062.10003.0C61





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SSID = mSATA

Mini Card Connector(mSATA)

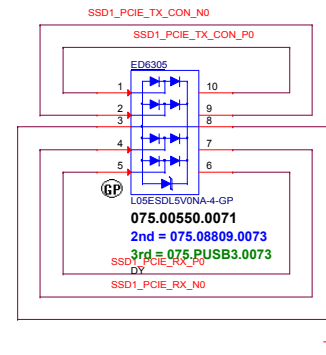
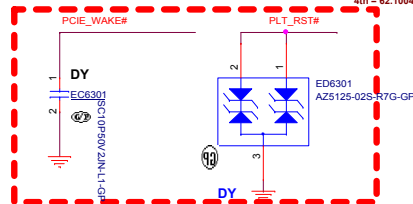
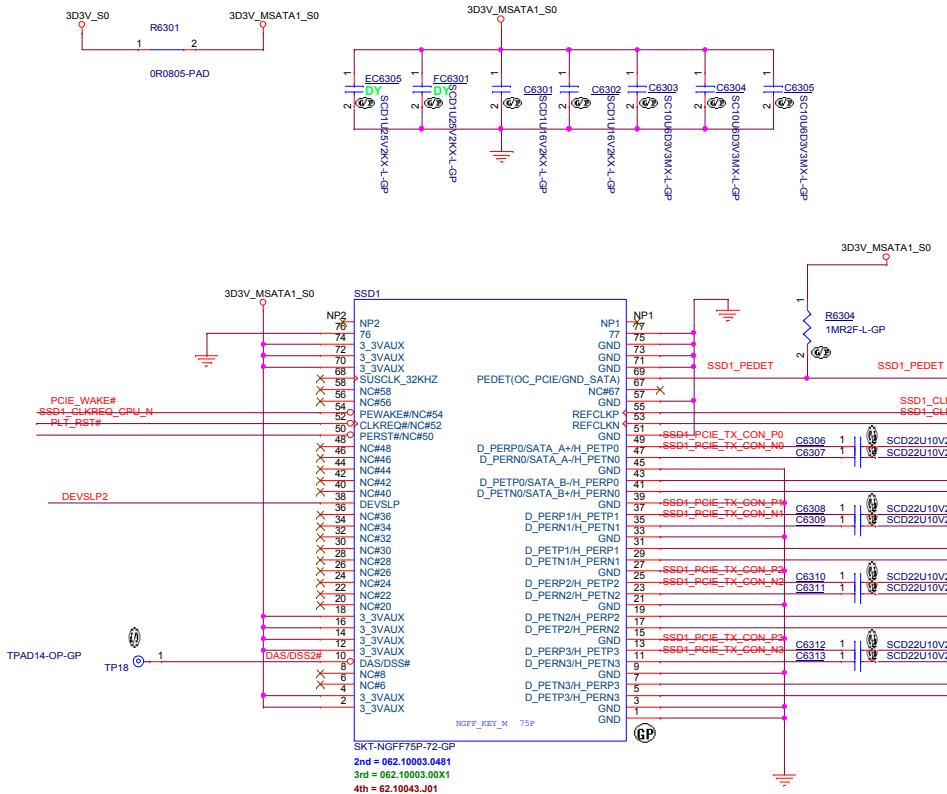
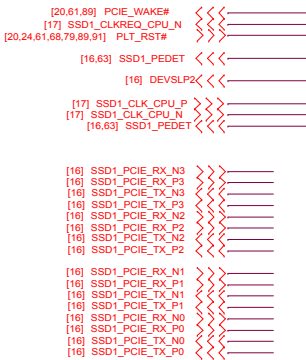


Figure 12-1. PCI Express® Link Configurations Supported by the Guidelines in this Chapter

PCH-LP Details		PCIe® Controller #1				PCIe® Controller #2				PCIe® Controller #3			
Flex I/O Lane #	PCIe Lane #	1	2	3	4	5	6	7	8	9	10	11	12
Base-U	14d	RP1											
	24d	RP5	RP3	RP5	RP5	RP5	RP5	RP5	RP5	RP5	RP5	RP5	RP5
	14d+24d	RP1	RP2	RP1	RP5	RP5	RP5	RP5	RP5	RP5	RP5	RP5	RP5
	24d+34d	RP4	RP3	RP1	RP5	RP5	RP5	RP5	RP5	RP5	RP5	RP5	RP5
Premium-U	14d	RP1											
	24d	RP1	RP5	RP5	RP5	RP5	RP5	RP5	RP5	RP5	RP5	RP5	RP5
	14d+24d	RP1	RP3	RP1	RP5	RP5	RP5	RP5	RP5	RP5	RP5	RP5	RP5
	24d+34d	RP4	RP3	RP1	RP5	RP5	RP5	RP5	RP5	RP5	RP5	RP5	RP5
Premium-Y	14d	RP1											
	24d	RP1	RP3	RP1	RP5	RP5	RP5	RP5	RP5	RP5	RP5	RP5	RP5
	14d+24d	RP1	RP3	RP1	RP5	RP5	RP5	RP5	RP5	RP5	RP5	RP5	RP5
	24d+34d	RP4	RP3	RP1	RP5	RP5	RP5	RP5	RP5	RP5	RP5	RP5	RP5

Condition	PCI Express® Gen 2 Only	PCI Express® Gen 3 Only	SATA Only	PCI Express® Gen 2 / SATA	PCI Express® Gen 3 / SATA
Processor Tx	100 nF	220 nF	10 nF	100 nF	220 nF
Processor Rx	None	None	10 nF ²	None	None ³

Notes:

- Design Constraint: For PCIe only application, refer to the PCIe guidelines for details.
- Design Constraint: For SATA only application, both Tx and Rx channels need to have 10 nF capacitors on the motherboard. This option supports all SATA devices. However, the 10 nF capacitor on Rx can be removed if DC coupled ODDs / devices are NOT used.
- Design Constraint: For PCIe® Gen 2 / SATA multiplexed configuration, motherboard Tx requires a 100 nF AC capacitor and NO AC capacitor is required for motherboard Rx channel. **This option DOES NOT support DC coupled ODDs / Devices.**
- Design Constraint: For PCIe® Gen 3 / SATA multiplexed configuration, motherboard Tx requires a 220 nF AC capacitor and NO AC capacitor is required for motherboard Rx channel. **This option DOES NOT support DC coupled ODDs / Devices.**
- Design Constraints, Required: Refer to chapter 3, "General Differential Signals Design Guidelines" along with the additional guidelines in this section for all design optimization guidelines.
- Design Constraint: For PCIe® lane that needs to support either **PCIe® Gen2 devices** or **PCIe® Gen3 devices**, follow the PCIe® Gen 3 / SATA multiplexed configuration where the motherboard Tx requires a 220 nF AC capacitor and NO AC capacitor is required for motherboard Rx channel. **This option DOES NOT support DC coupled ODDs / Devices.**

Pin define from PCH and socket side.

	High (1)	Low (0)
PCH GPIO	SATA	PCIe
M.2 CONFIG_1	PCIe**	SATA

** Native: Internal Pull-Up (15k-40k) when function.

Table 27. Socket 2 Module Configuration


State #	Module Configuration Decodes			Module Type and Main Host Interface ¹	Port Configuration ²
	CONFIG_0 (Pin 21)	CONFIG_1 (Pin 69)	CONFIG_2 (Pin 75)	CONFIG_3 (Pin 1)	
0	GND	GND	GND	GND	SSD - SATA
1	GND	NC	GND	GND	SSD - PCIe

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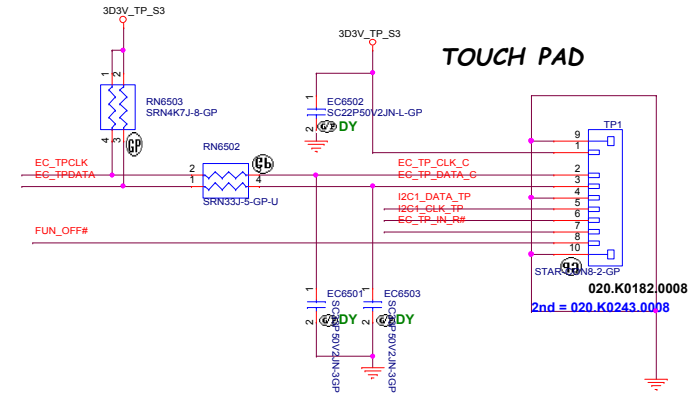
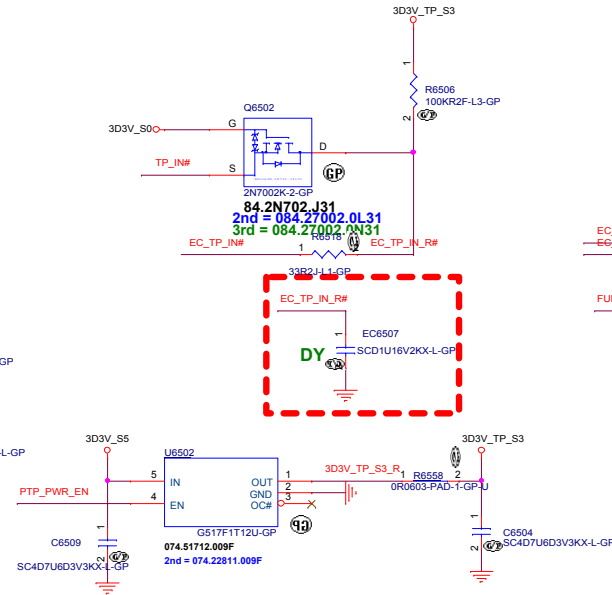
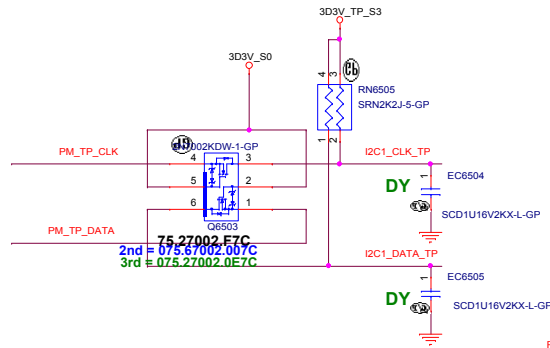
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D				D
C				C
B				B
A				A
5	4	3	2	1

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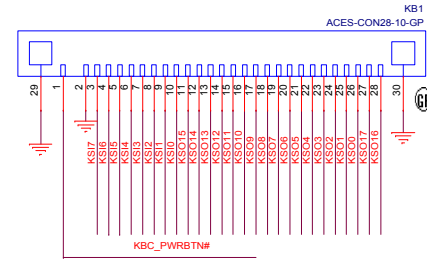
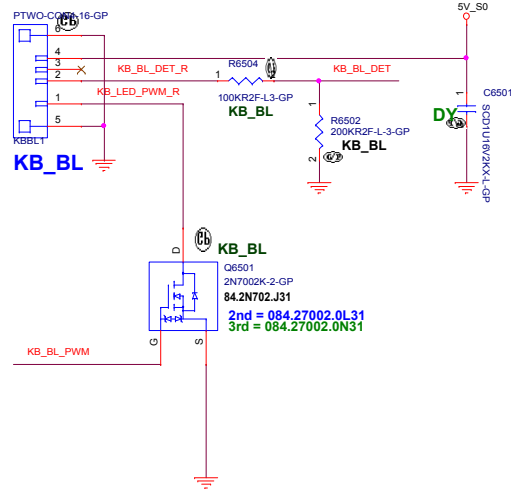
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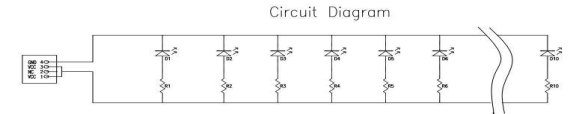
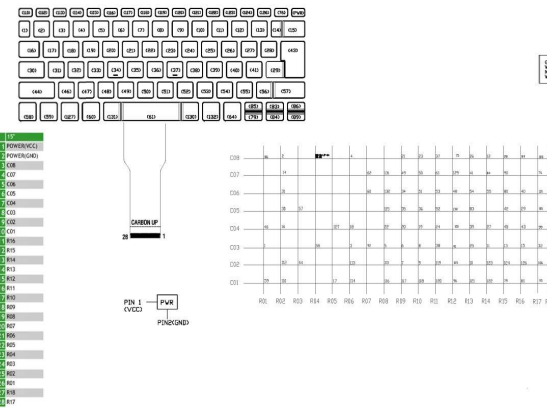
[24.89] KSI[0..7] >>> 
[24.89] KSO[0..17] <<< 
[24] EC_TPCLK >>> 
[24] EC_TPDATA >>> 
[24.89] FUN_OFF# >>> 
[89] EC_TP_CLK_C >>> 
[89] EC_TP_DATA_C >>> 
[89] I2C1_DATA_TP >>> 
[89] I2C1_CLK_TP >>> 
[24] PTP_PWR_EN >>> 
[22] TP_IN# <<< 
[24.89] EC_TP_IN# <<< 
[24.89] EC_TP_IN_R# <<< 
[6] PM_TP_CLK <<< 
[6] PM_TP_DATA <<< 
[24] KB_BL_PWM >>> 
[24] KB_BL_DET <<< 
[89] KB_BL_DET_R# <<< 
[89] KB_LED_PWM# <<< 
[24.64.89] KBC_PWRBTN# <<< 



Internal KeyBoard Connector



020.K0173.0028
2nd = 020.K0266.0028



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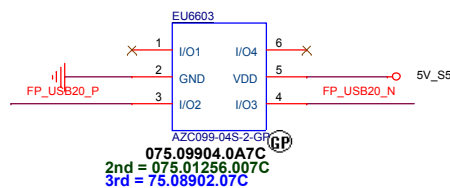
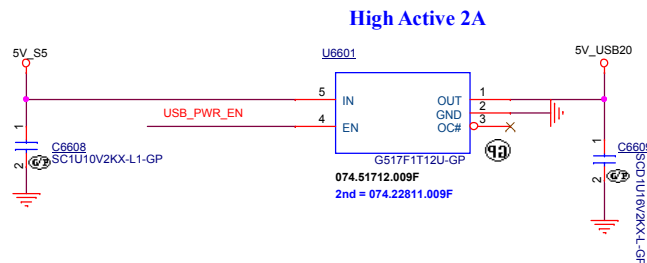
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Key Board/Touch Pad

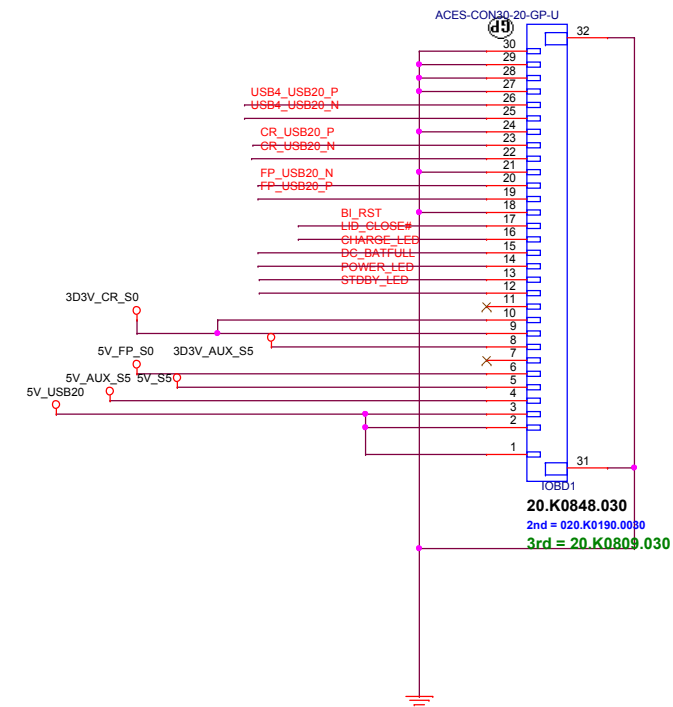
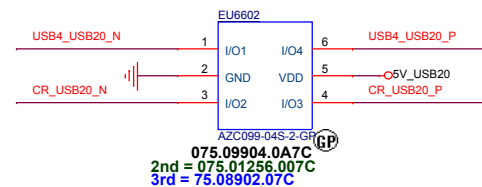
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SSID = User.Interface



Close connector



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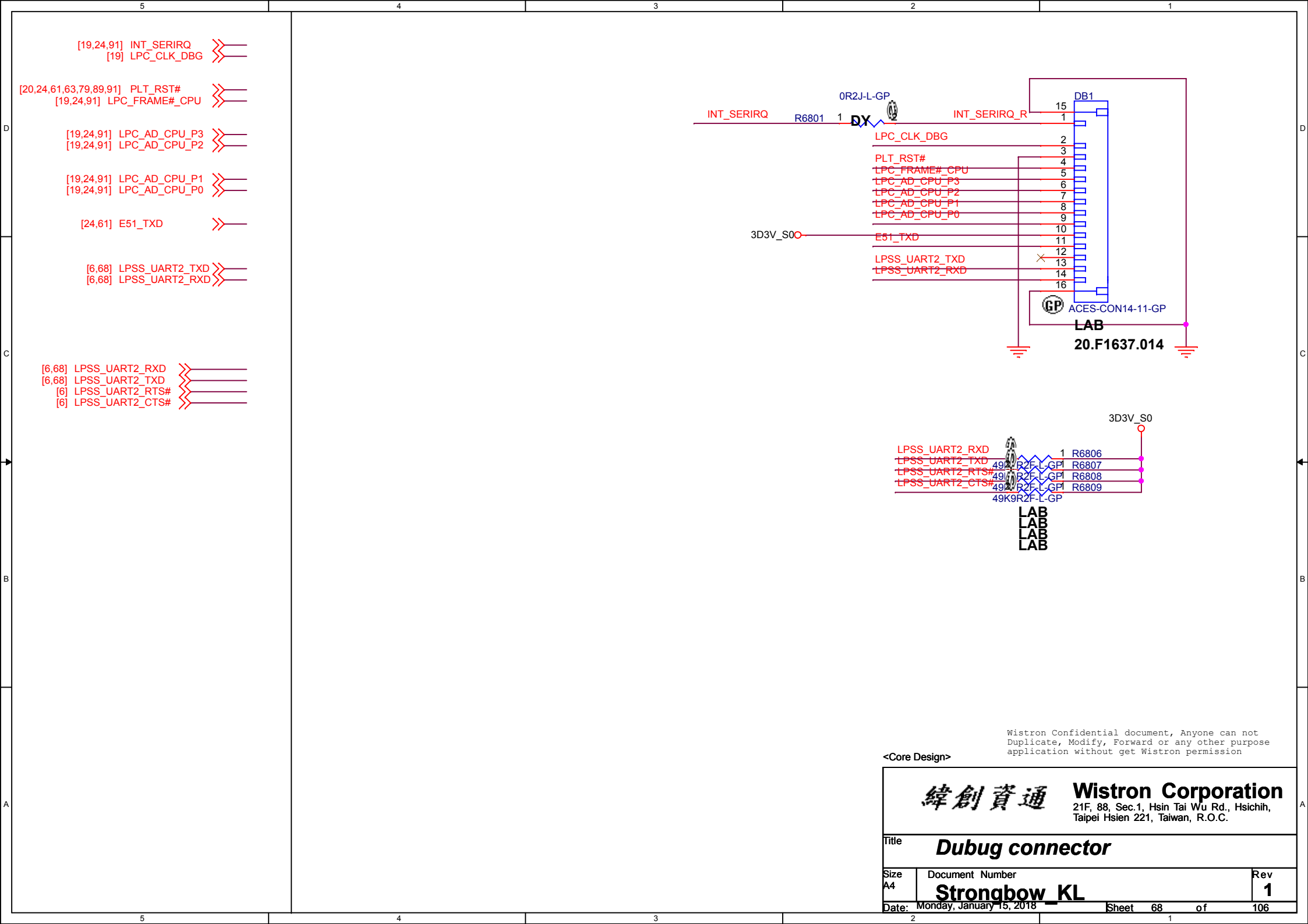
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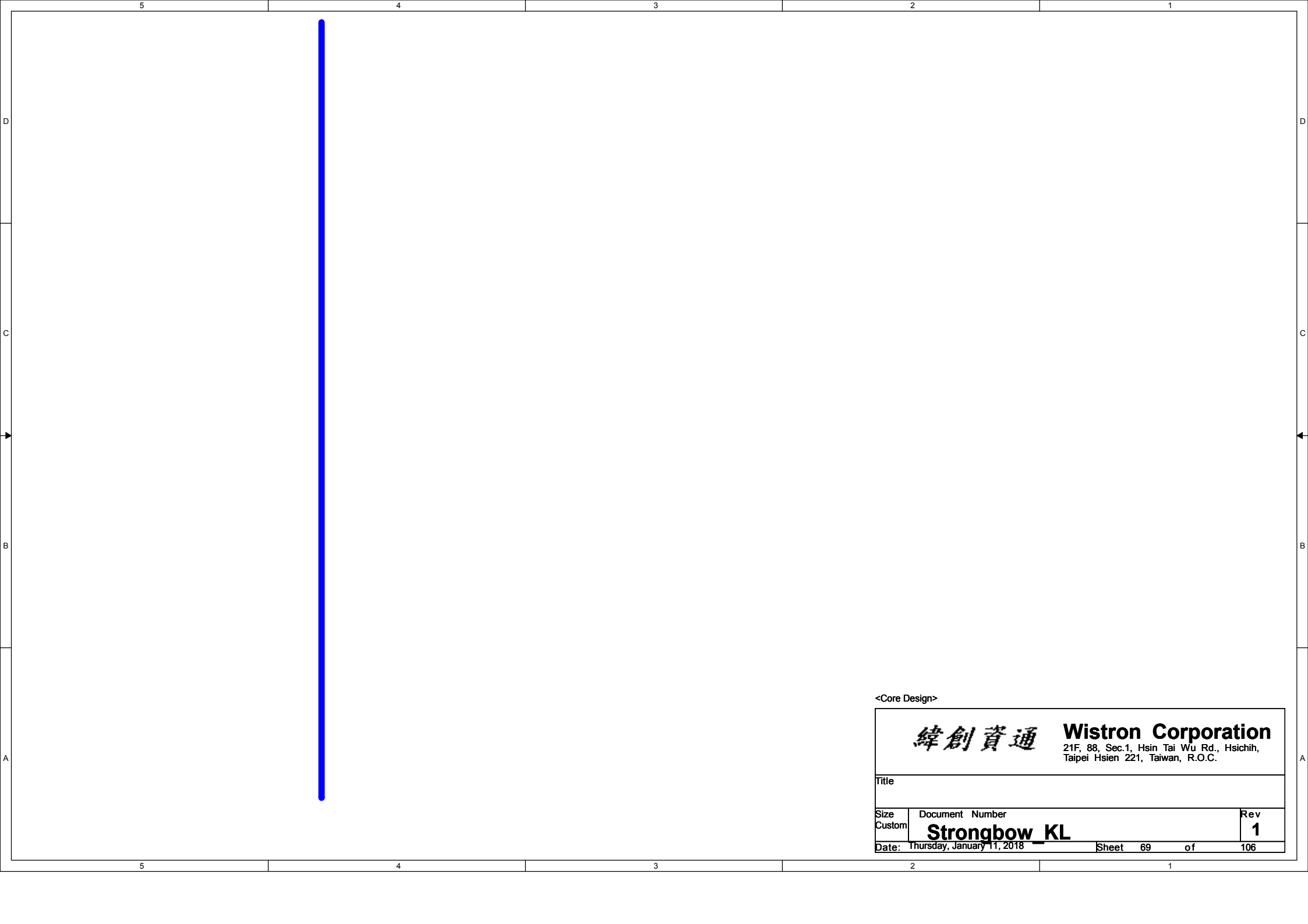
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SSID = User.Interface

G Sensor

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Thunderbolt (4/5)

Size

A4

Document Number

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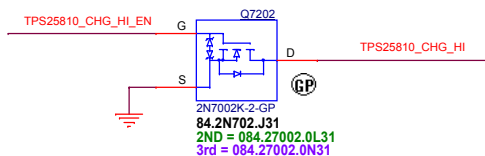
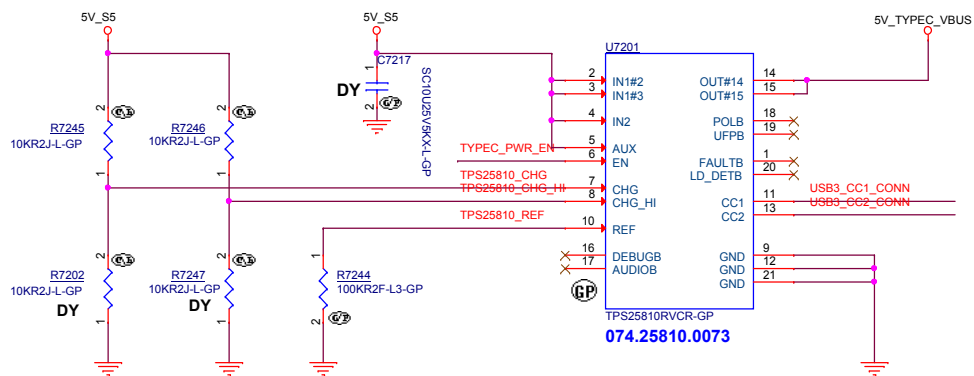
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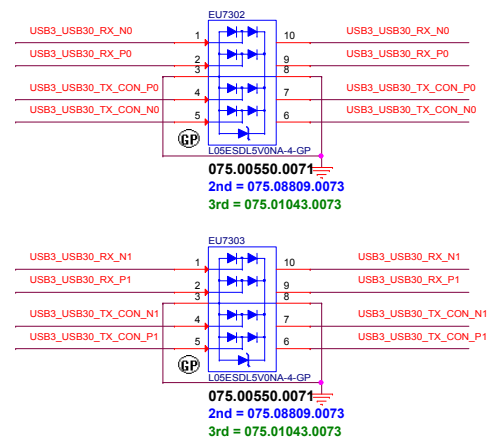
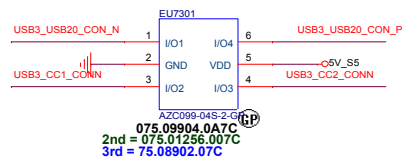
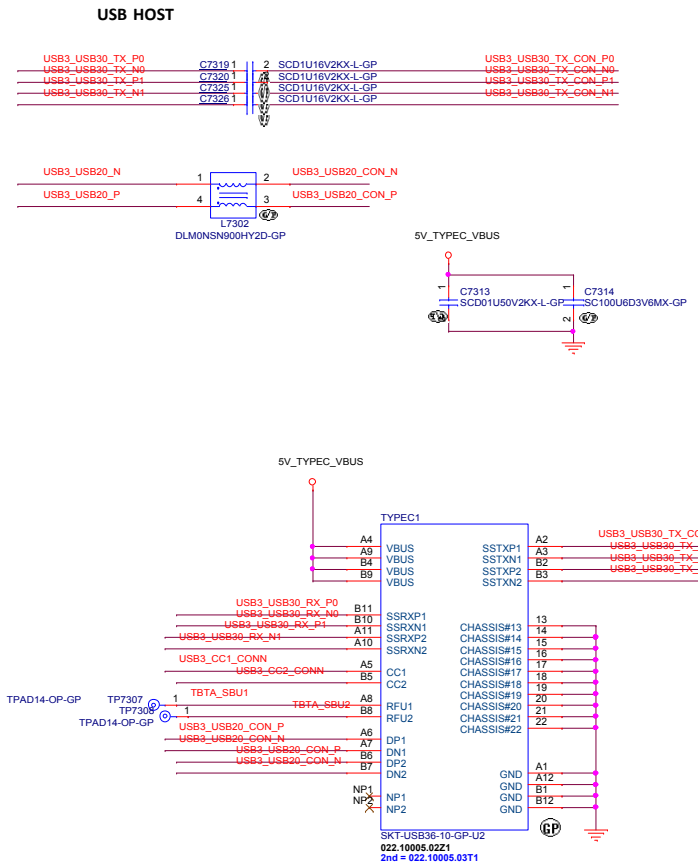
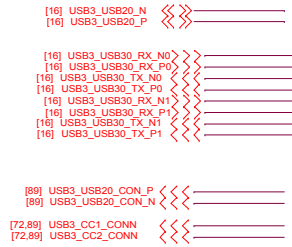
Date: Thursday, January 11, 2018

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[24] TPS25810_CHG_HI_EN >>> _____
[24] TYPEC_PWR_EN >>> _____
[73,89] USB3_CC1_CONN <<<< _____
[73,89] USB3_CC2_CONN <<<< _____



CHG	CHG_HI	CC Capability Broadcast	Current Limit	Load Detect Threshold
0	0	STD	1.67 A	NA
0	1	STD	1.67 A	NA
1	0	1.5 A	1.67 A	NA
1	1	3.0 A	3.34 A	1.77 A



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Title TYPE-C

Size Custom Document Number Rev 1

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5	4	3	2	1
D				
C				
B				
A				

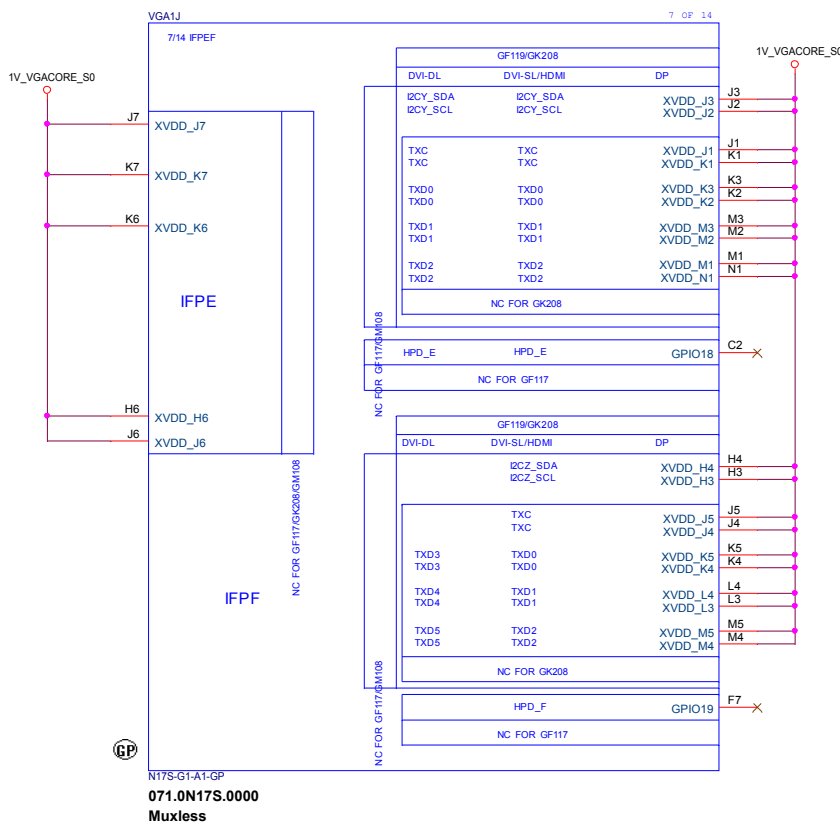
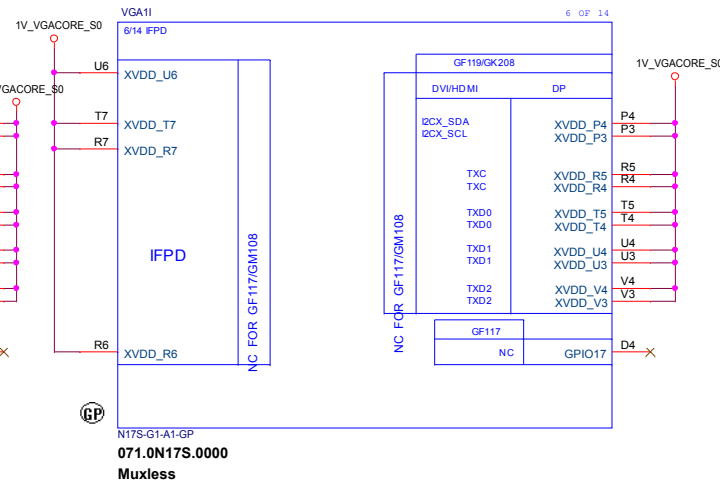
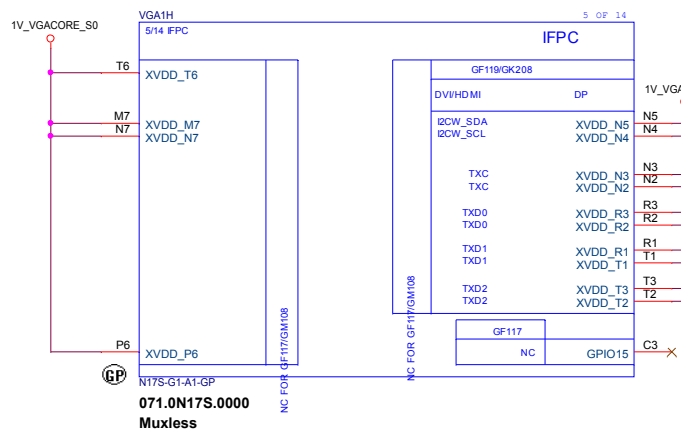
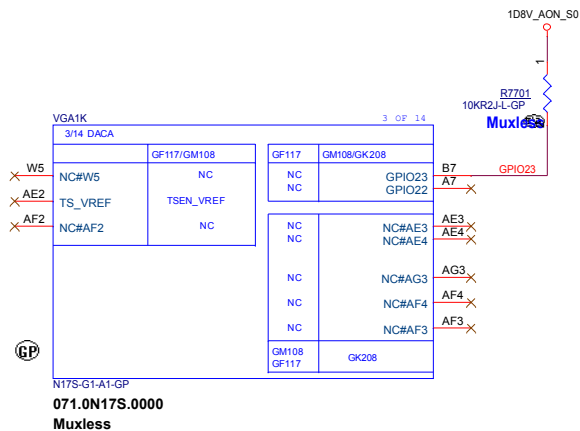
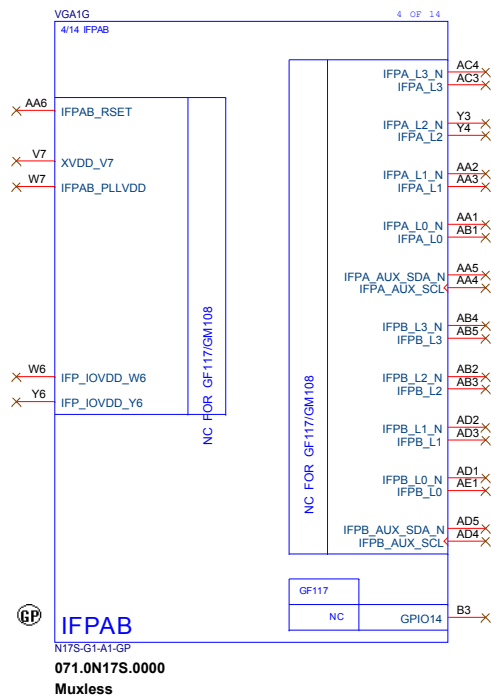
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Size	Document Number		Rev		
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GPU (VRAM I/F)		
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GPU (2/5) DIGITALOUT			
Size Custom	Document	Number	Rev
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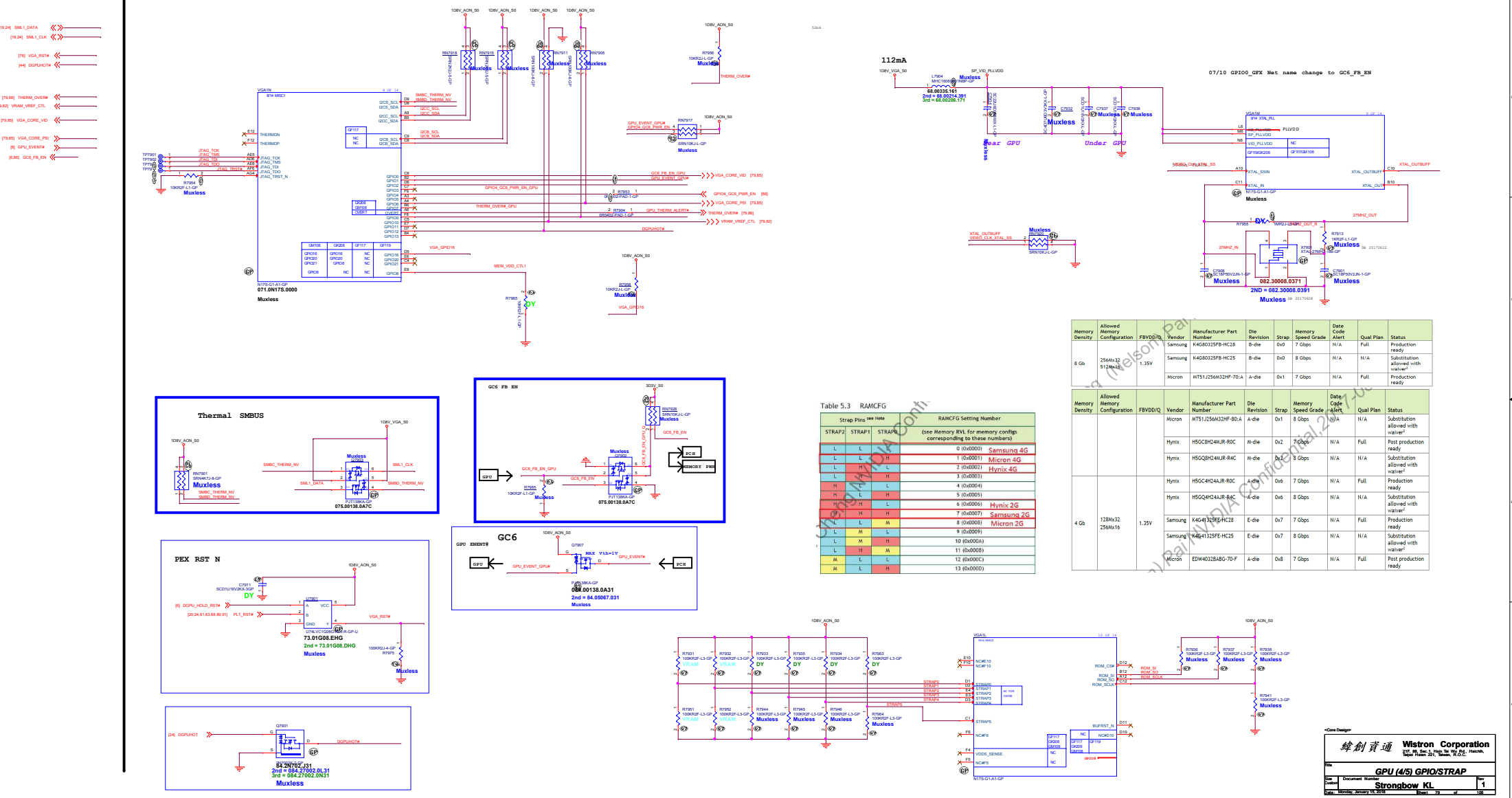
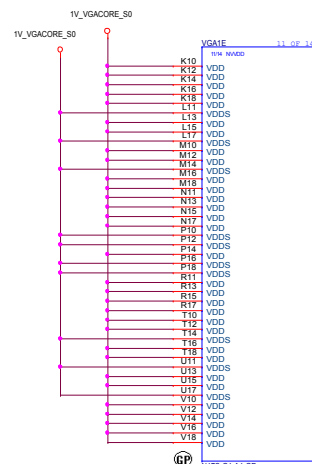


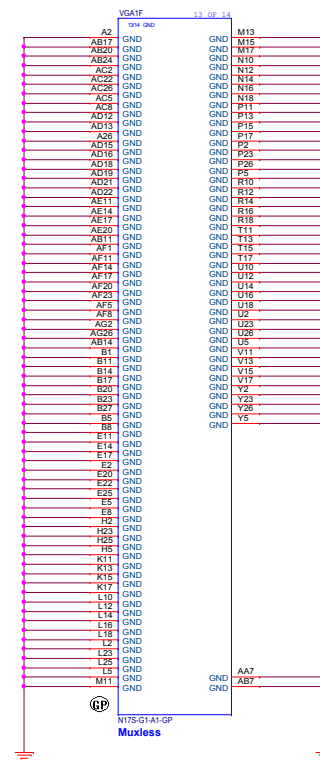
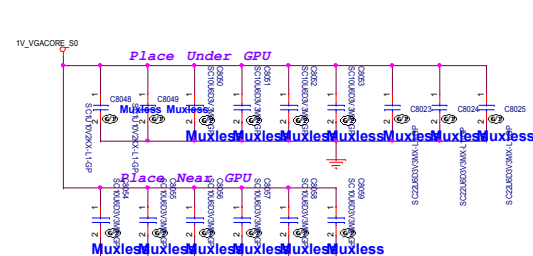
Table 5.3 RAMCFG

Strap Pins	see Note	RAMCFG Setting Number
STRAP2	STRAP1	(see Memory RVL for memory configs corresponding to these numbers)
L	L	0 (0x0000)
L	L	1 (0x0001) Samsung 4G
L	L	2 (0x0002) Micron 4G
L	H	3 (0x0003) Hynix 4G
H	L	4 (0x0004)
H	L	5 (0x0005)
H	H	6 (0x0006) Hynix 2G
H	H	7 (0x0007) Samsung 2G
L	L	8 (0x0008) Micron 2G
L	M	9 (0x0009)
L	M	10 (0x000A)
M	L	11 (0x000B)
M	L	12 (0x000C)
M	L	13 (0x000D)

Memory Density	Allowed Memory Configuration	FBVDD/Q	Vendor	Manufacturer Part Number	Die Revision	Strap	Memory Speed Grade	Date Code Alert	Qual Plan	Status
8 Gb	256Mb32 512Mb16	1.35V	Samsung	K4G8032FB-HC28	B-die	Dx0	7 Gbps	N/A	Full	Production ready
			Samsung	K4G8032FB-HC25	B-die	Dx0	8 Gbps	N/A	N/A	Substitution allowed with waiver
			Micron	MTS1J256M32HF-70-A	A-die	Dx1	7 Gbps	N/A	Full	Production ready
4 Gb	128Mb32 256Mb16	1.35V	Micron	MTS1J256M32HF-80-A	A-die	Dx1	8 Gbps	N/A	N/A	Substitution allowed with waiver
			Hynix	H5GC8H24UR-R0C	M-die	Dx2	7 Gbps	N/A	Full	Post production ready
			Hynix	H5GQ8H24UR-R4C	M-die	Dx2	8 Gbps	N/A	N/A	Substitution allowed with waiver
			Hynix	H5GC4H24UR-R0C	A-die	Dx6	7 Gbps	N/A	Full	Production ready
			Hynix	H5GQ4H24UR-R4C	A-die	Dx6	8 Gbps	N/A	N/A	Substitution allowed with waiver
			Samsung	K4G4132FE-HC28	E-die	Dx7	7 Gbps	N/A	Full	Production ready
			Samsung	K4G4132FE-HC25	E-die	Dx7	8 Gbps	N/A	N/A	Substitution allowed with waiver
			Micron	EDW4032BAG-70-F	A-die	Dx8	7 Gbps	N/A	Full	Post production ready



Power ^{Muxless} *current=26A*



Power current=60mA

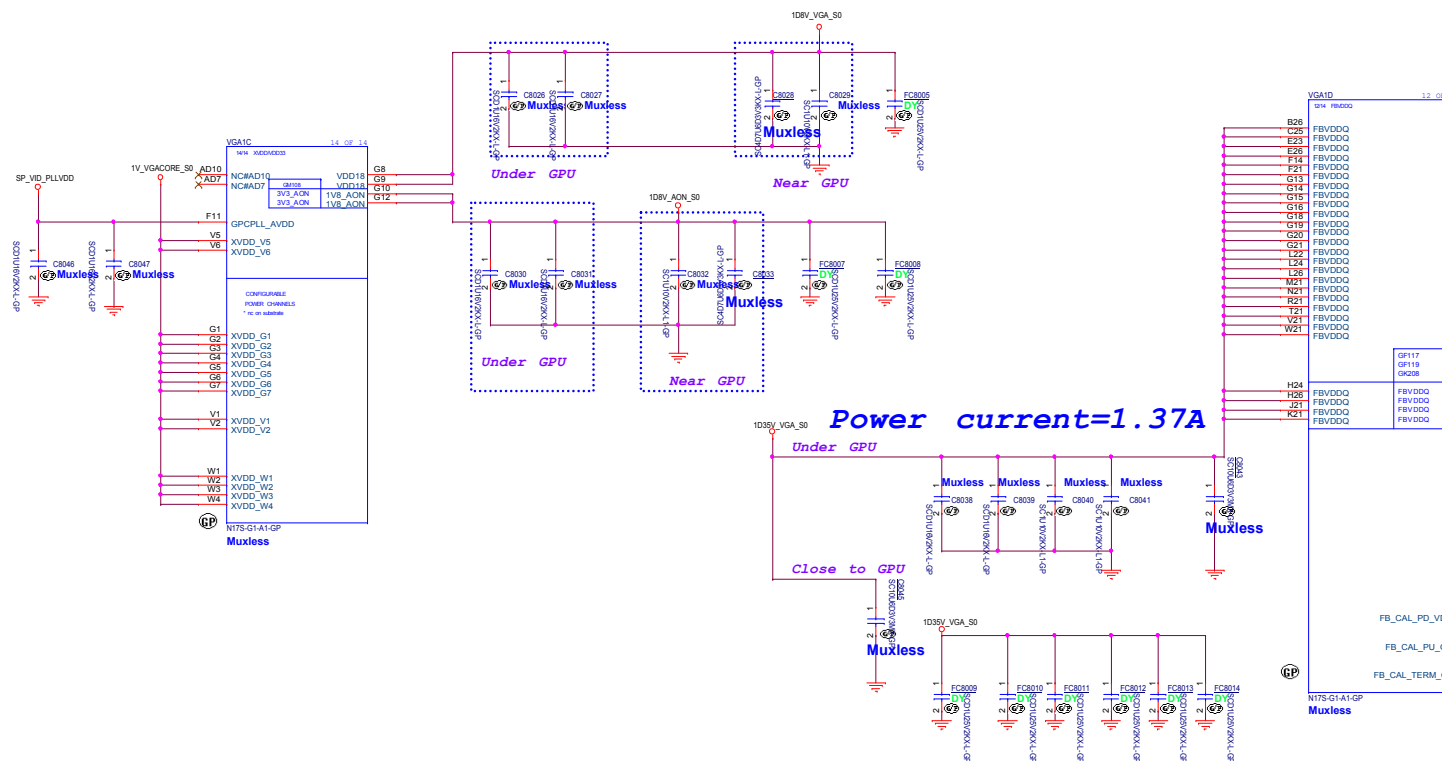


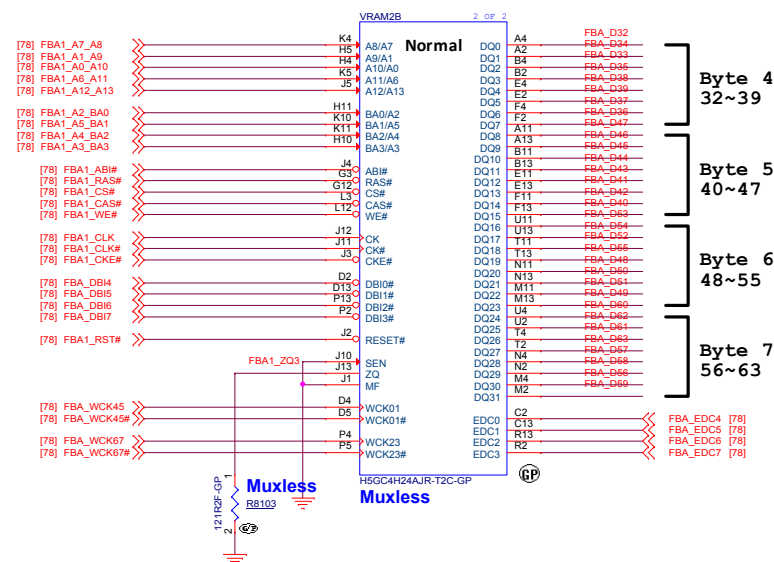
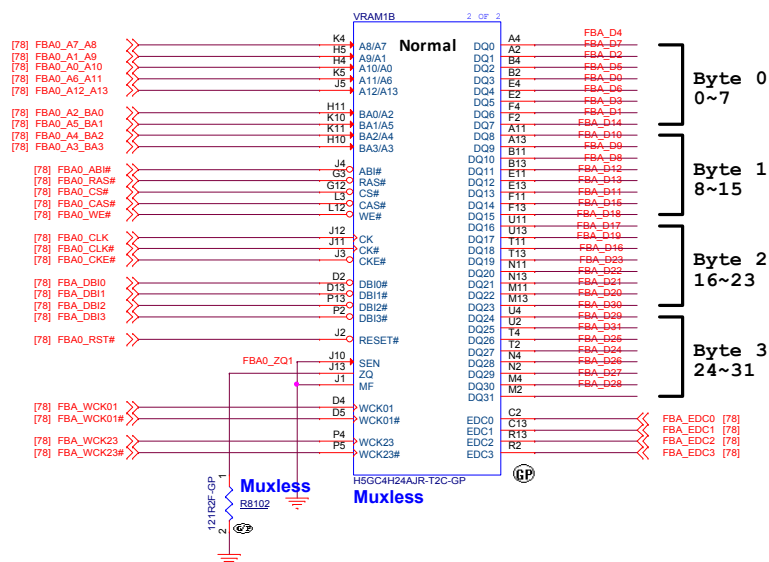
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GDDR5 VIDEO MEMORY

072.05424.0A0U

072.44132.000U

072.04032.000N

	HYNIX 4GBITS (128Mx32)	SAMSUNG 4GBITS (128Mx32)	Micron 4GBITS (128Mx32)
VRAM1 VRAM2	H5GC4H24AJR-T2C	K4G41325FC-HC03	EDW4032BABG-60-F-D



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VRAM CHANNEL-A			
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VRAM CHANNEL-B			
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C																								
B																								
A																								

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MEMORY TERMINATION

Size

A4

Document Number

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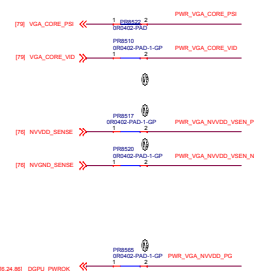
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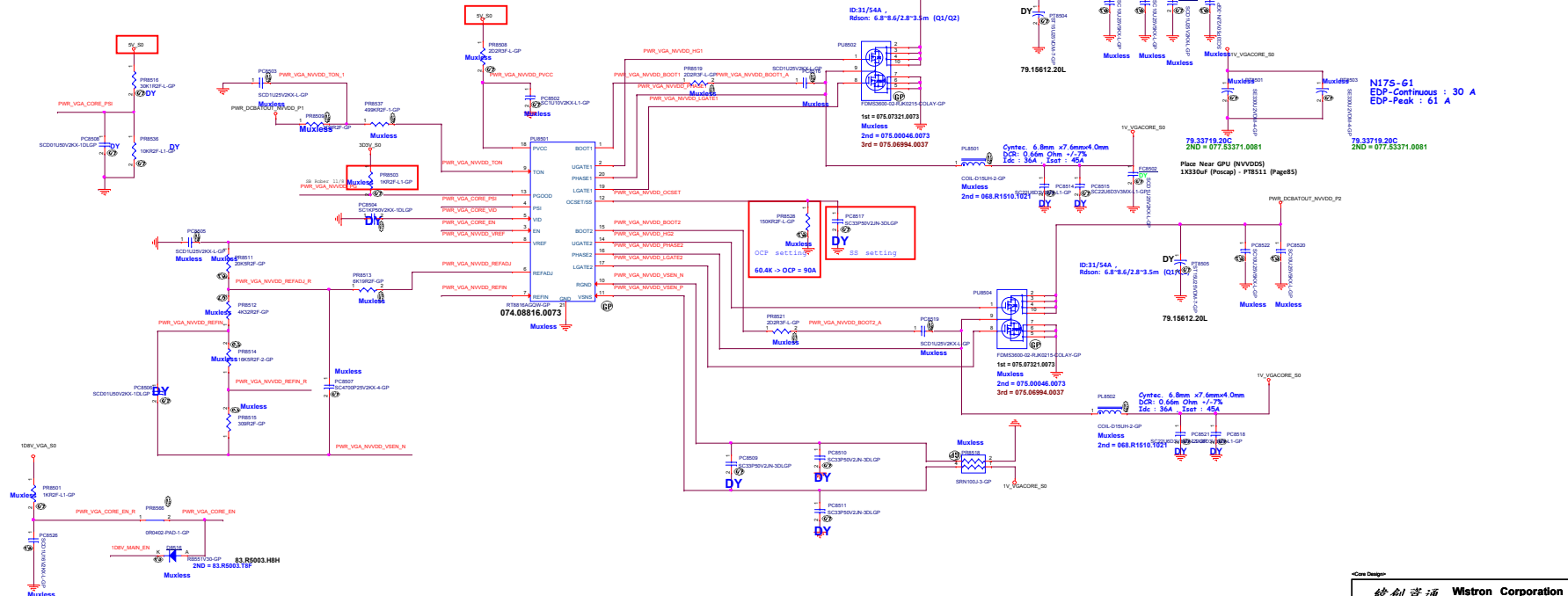
Size A4	Document Number Strongbow_KL	Rev 1
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RT8816A For NVVDD

N175-G1
 EDP-Continuous : 30 A
 EDP-Peak : 61 A



>>> PWR_VGA_CORE_PSB [79:88]
 >>> PWR_VGA_CORE_VSD [87]
 >>> TDRV_MAIN_EN [87]



SSID = PWR.Plane.Regulator_1p0v

SSID = PWR.Plane.Regulator_1p35v

IC	AOZ2262 (10A)	AOZ2261 (8A)	AOZ2260 (6A)
COM	074.02262.0043	074.02261.0A73	074.02260.0043
Check	68.1R01A.20B IDC : 10A	68.1R01A.20B IDC : 10A	68.1R01A.20B IDC : 10A
Output CAP	22uF/6.3V * 5pcs DY*1	22uF/6.3V * 4pcs DY*1	22uF/6.3V * 4pcs DY*1

AOZ2262 for 1D35V

TDC : 8.6A
Peak : 10.3A

Cyntec 6.5mm x 6.9mm x 3.0mm
DCR: 3mV/On/On
Idc : 11 A , Isst : 22A

SYW232 for 1D8V_AON

VGA_CORE&1D05V_VGA_S0 Discharge Circuit
3D3V_S5 to 1D8V_AON_S0

Cyntec 2.5 x 2.0 x 1.2mm
DCR: 37-43 mOhm
Idc : 2.6A , Isst : 2.7A

SYW232 for 1D05V
Enable=1.5V
Disable=0.4V

SYW232 for 1D8V_MAIN

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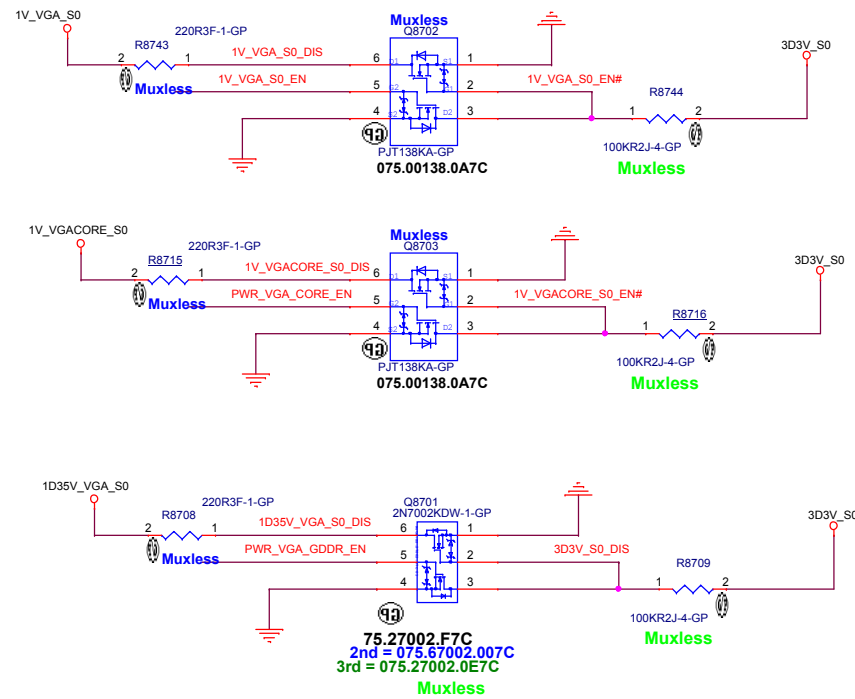
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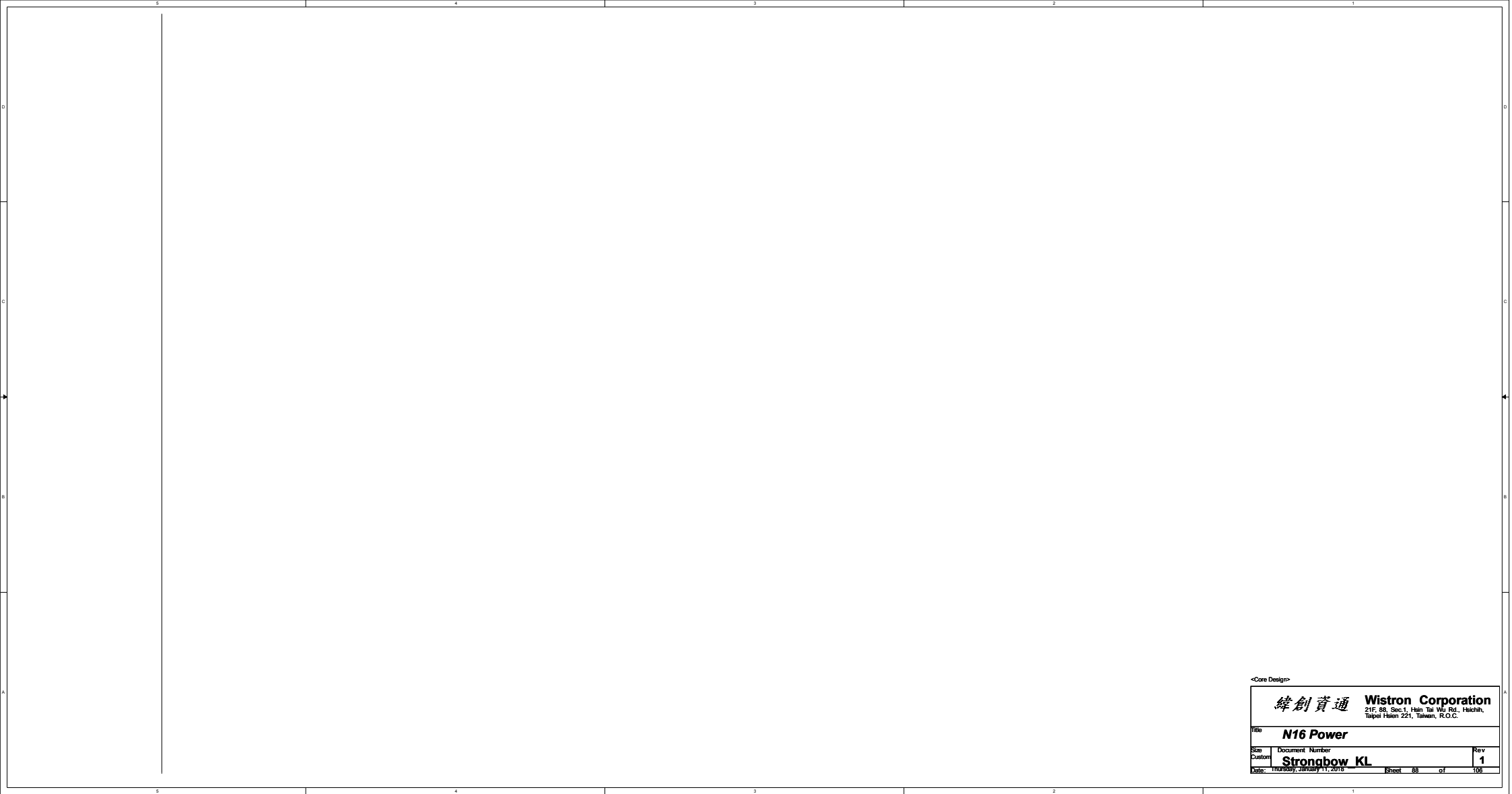
[86] 1V_VGA_S0_EN <<<

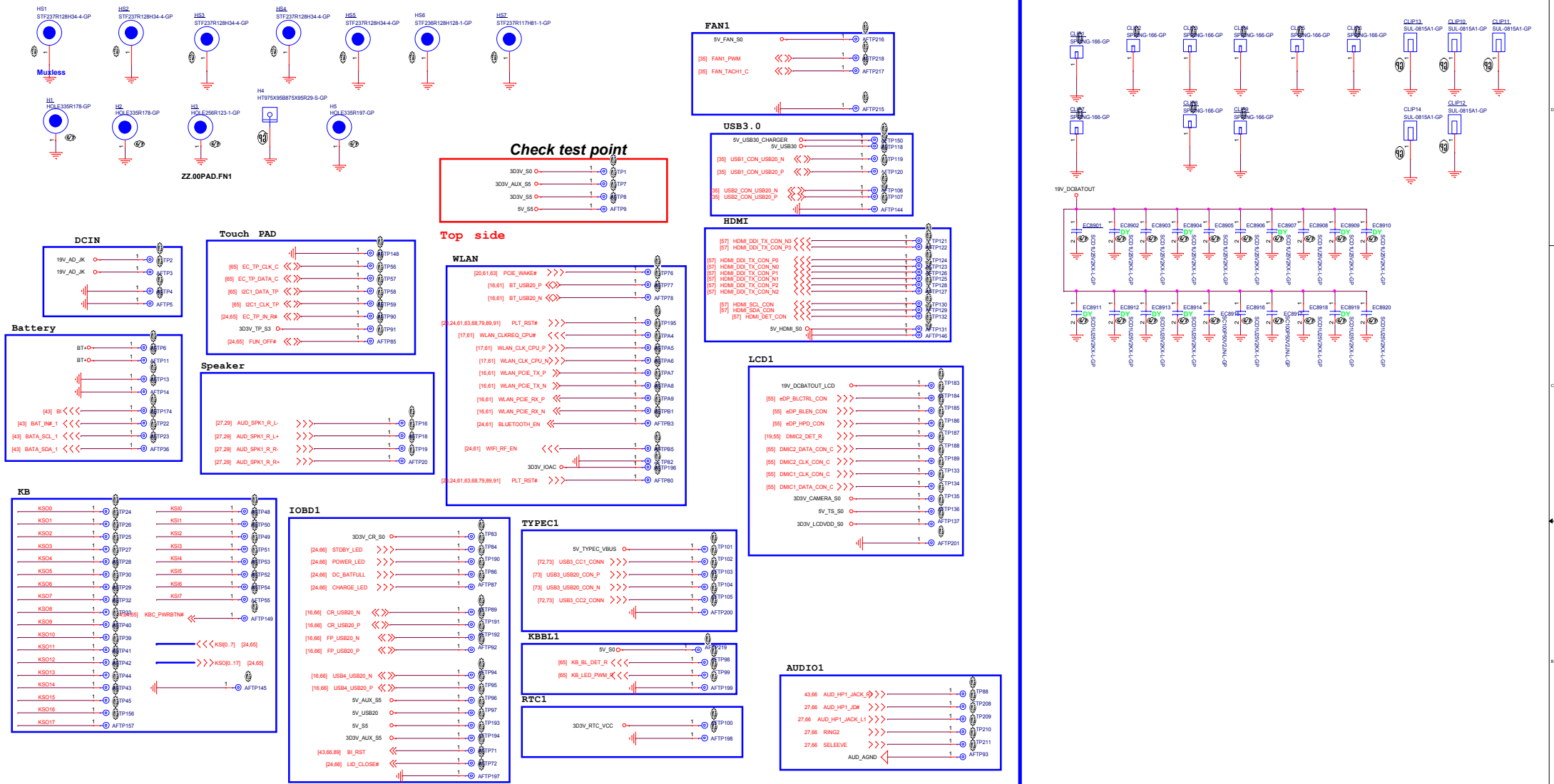
[85] PWR_VGA_CORE_EN >>>

[86] PWR_VGA_GDDR_EN >>>



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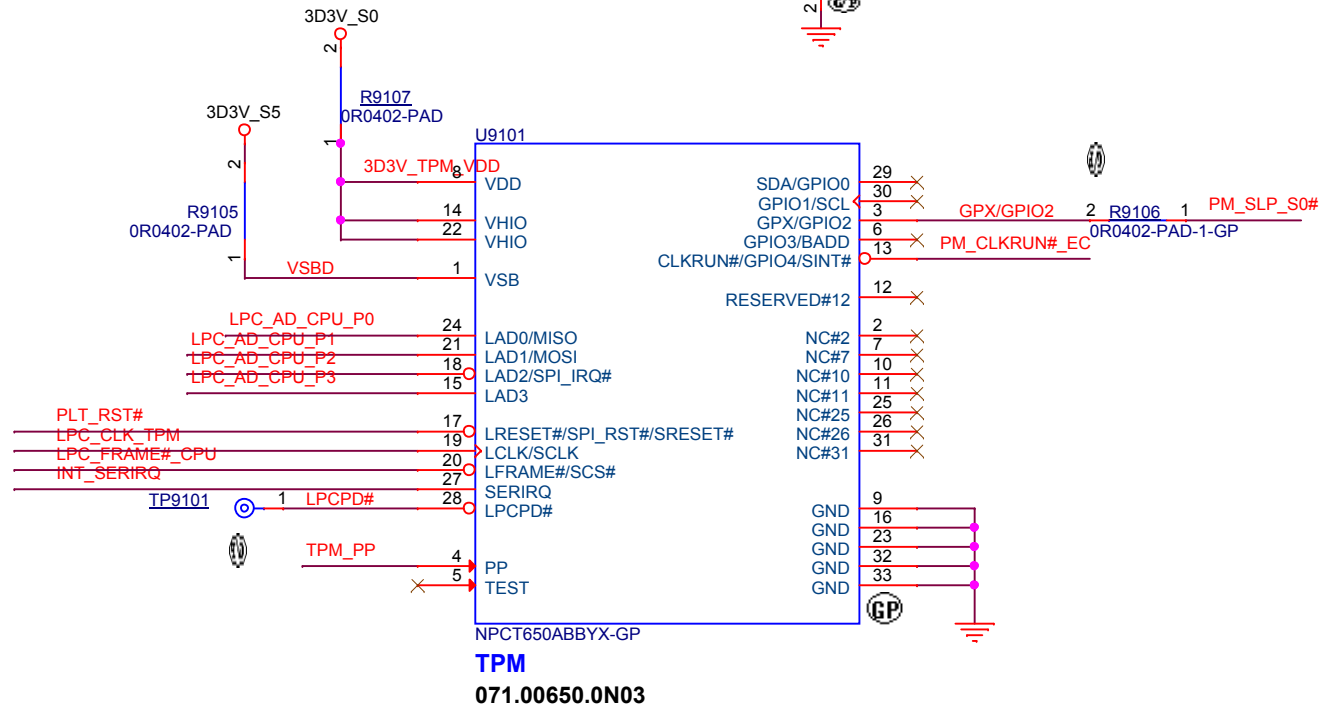
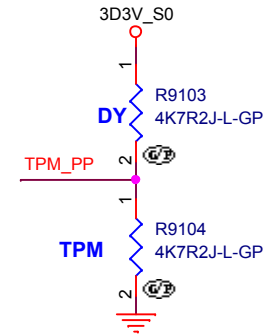
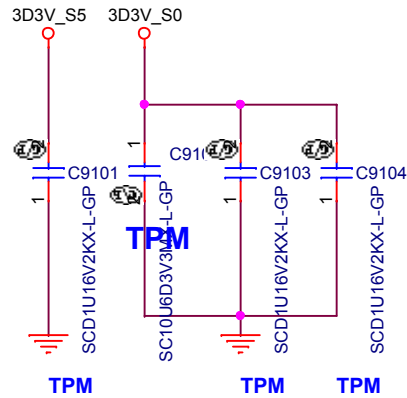
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[19,24,68] LPC_AD_CPU_P0
[19,24,68] LPC_AD_CPU_P1
[19,24,68] LPC_AD_CPU_P2
[19,24,68] LPC_AD_CPU_P3
[19] LPC_CLK_TPM
[19,24,68] LPC_FRAME#_CPU
[20,24,61,63,68,79,89] PLT_RST#
[19,24,68] INT_SERIRQ
[19,24] PM_CLKRUN#_EC
[20,24,40,60] PM_SLP_S0#



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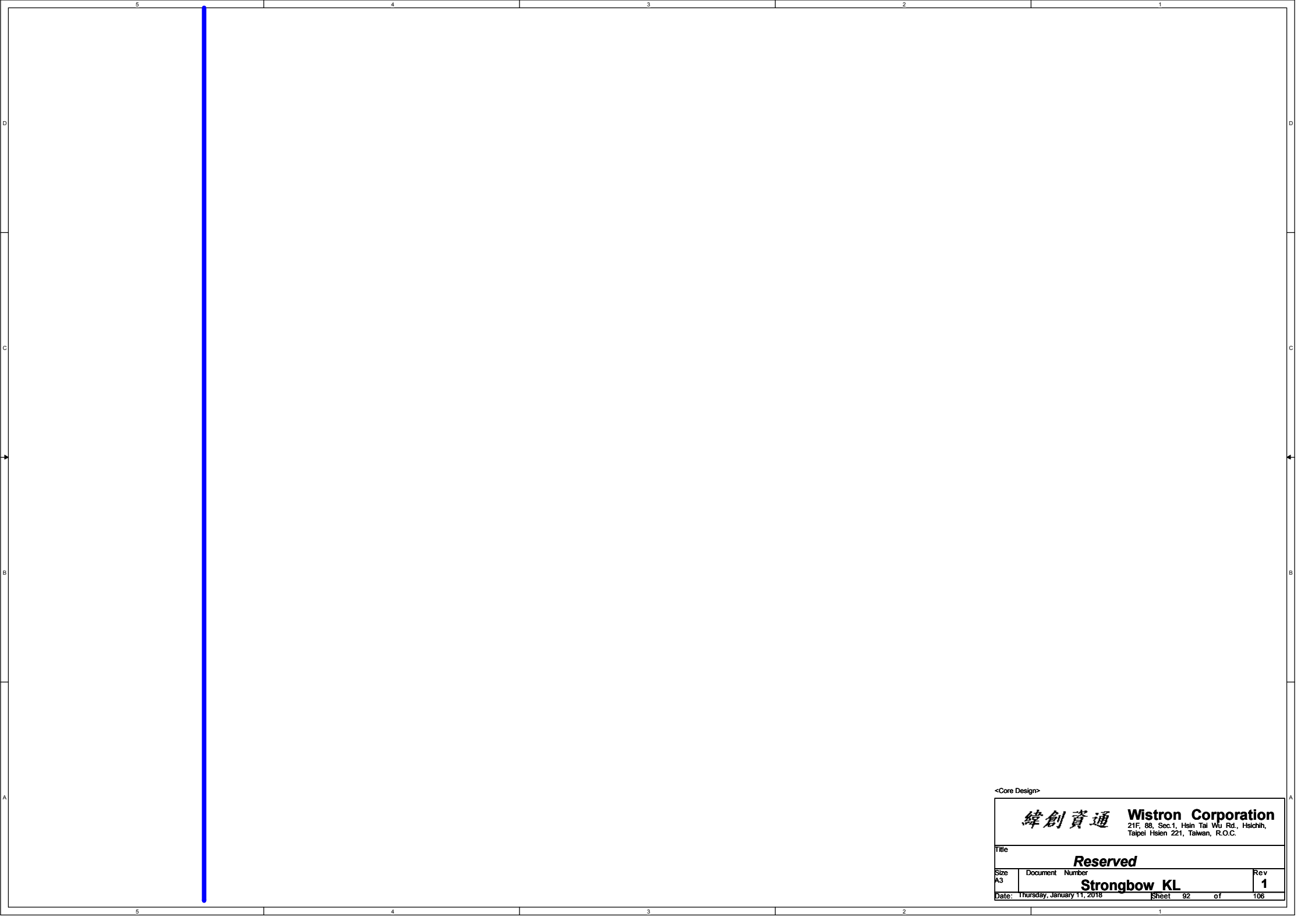
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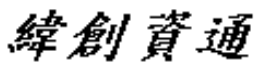
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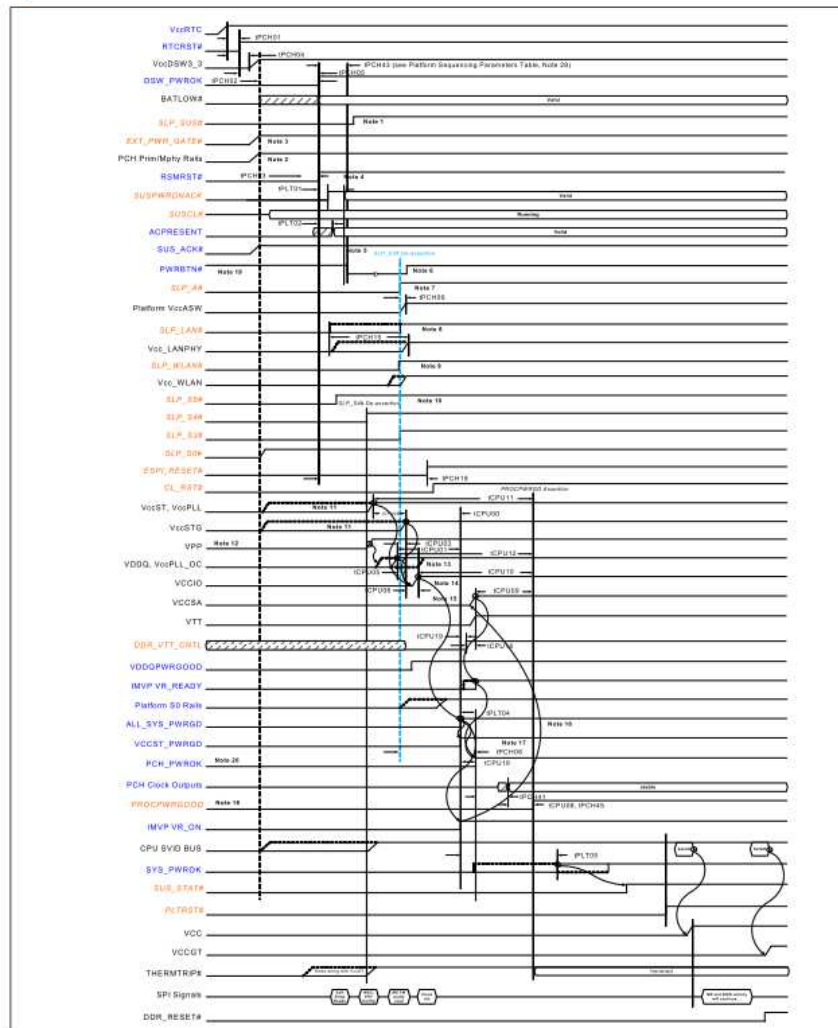
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Figure 41-5. KBL R U Timing Diagram for G3 to S0/M0 [Non-Deep Sx Platform] (Sheet 1 of 2)



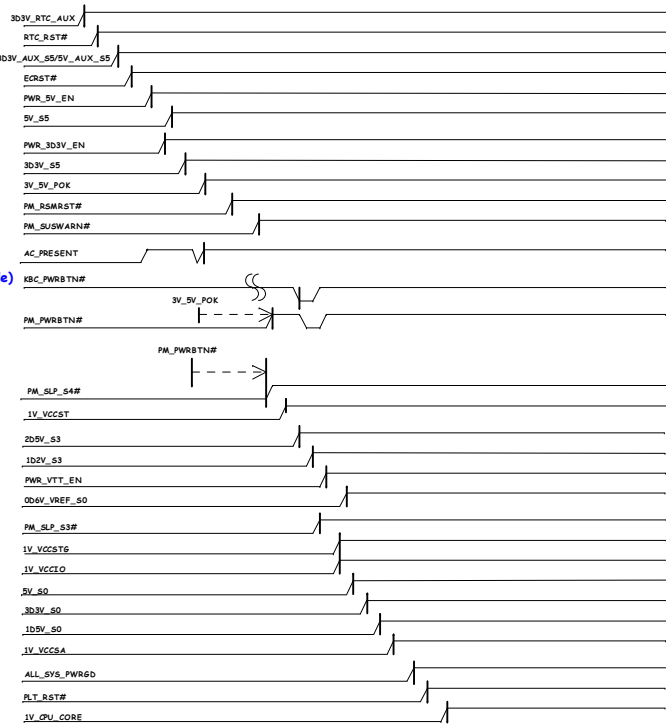
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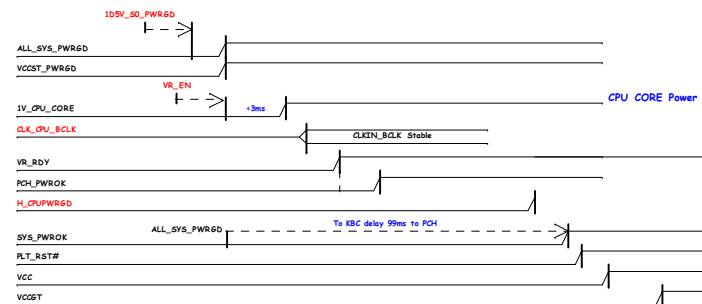
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Intel-Power Up Sequence

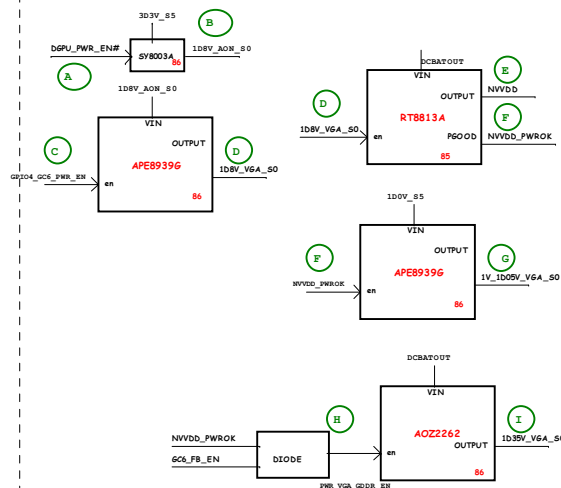
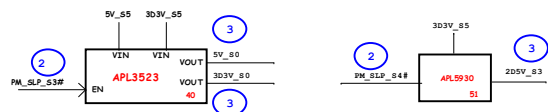
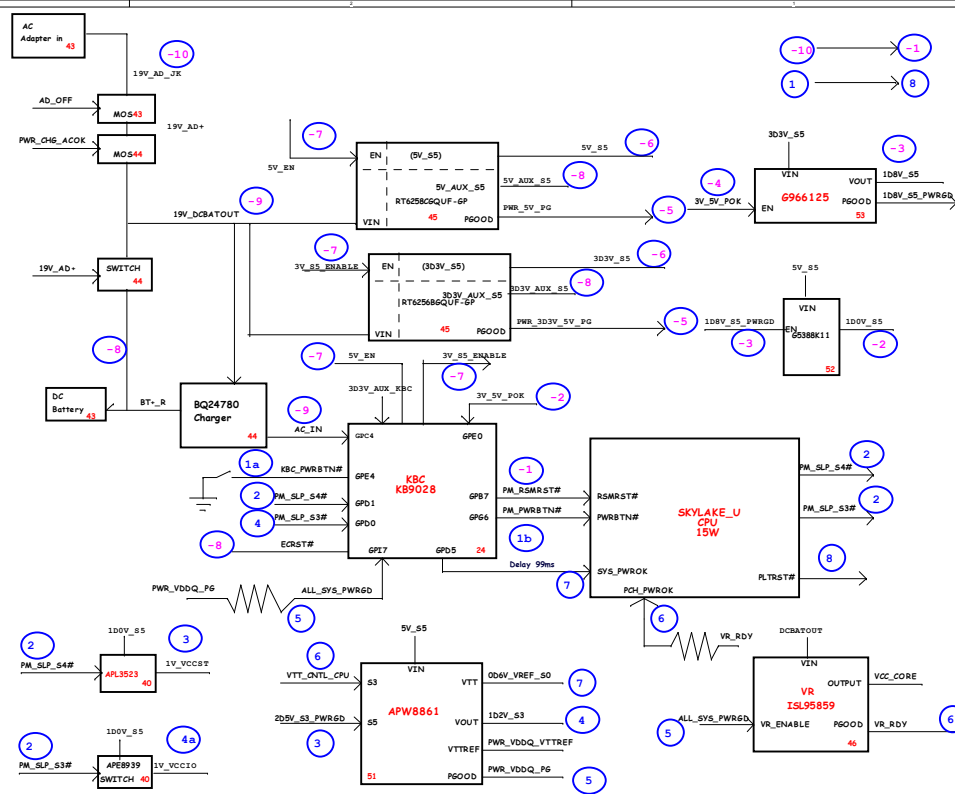
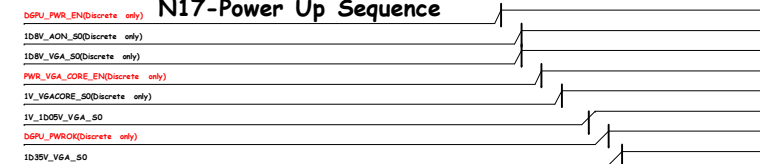
(AC mode)

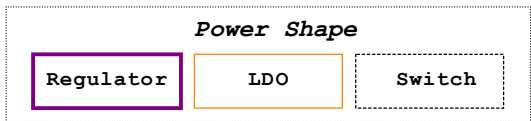
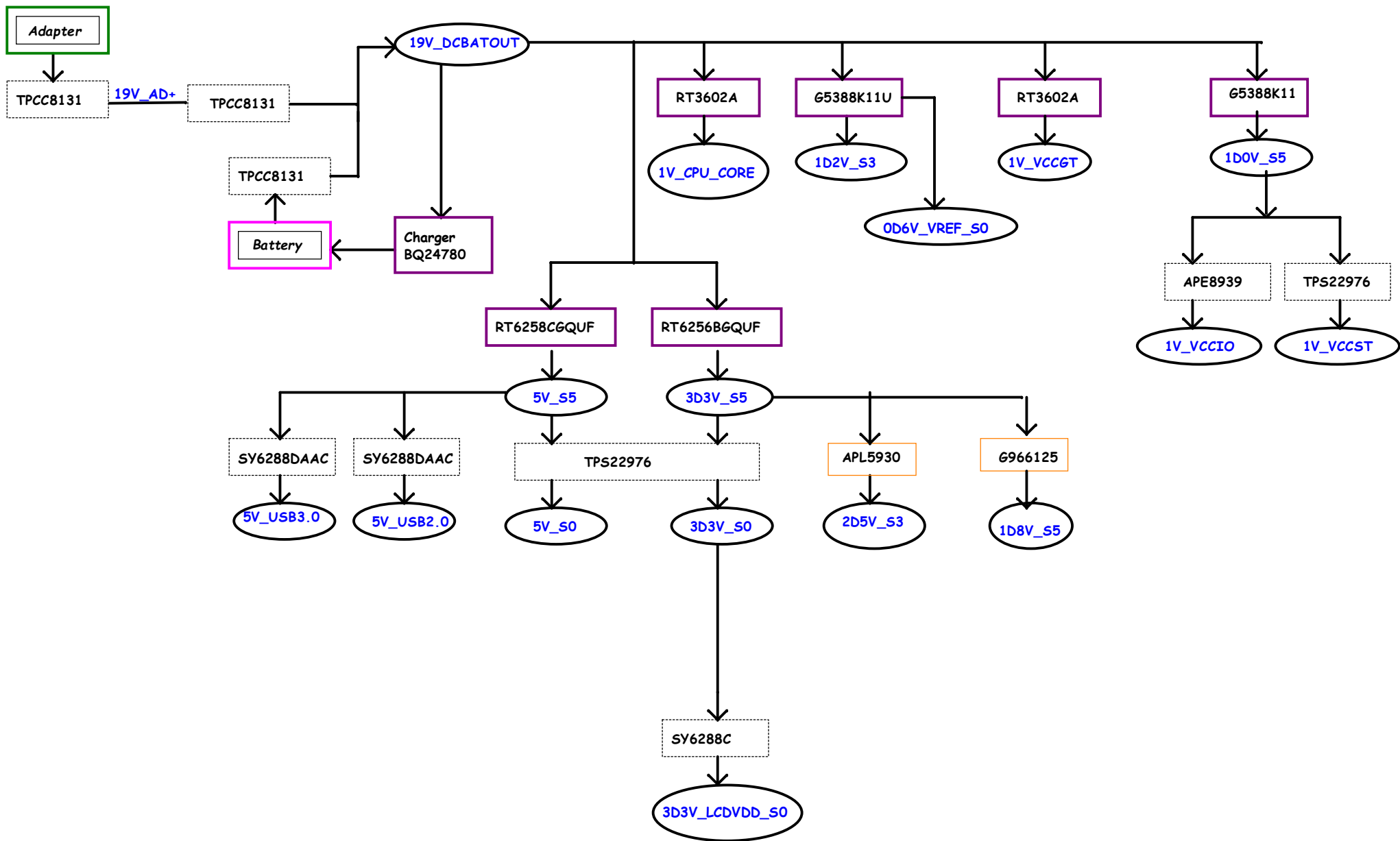


(AC mode) (DC mode)

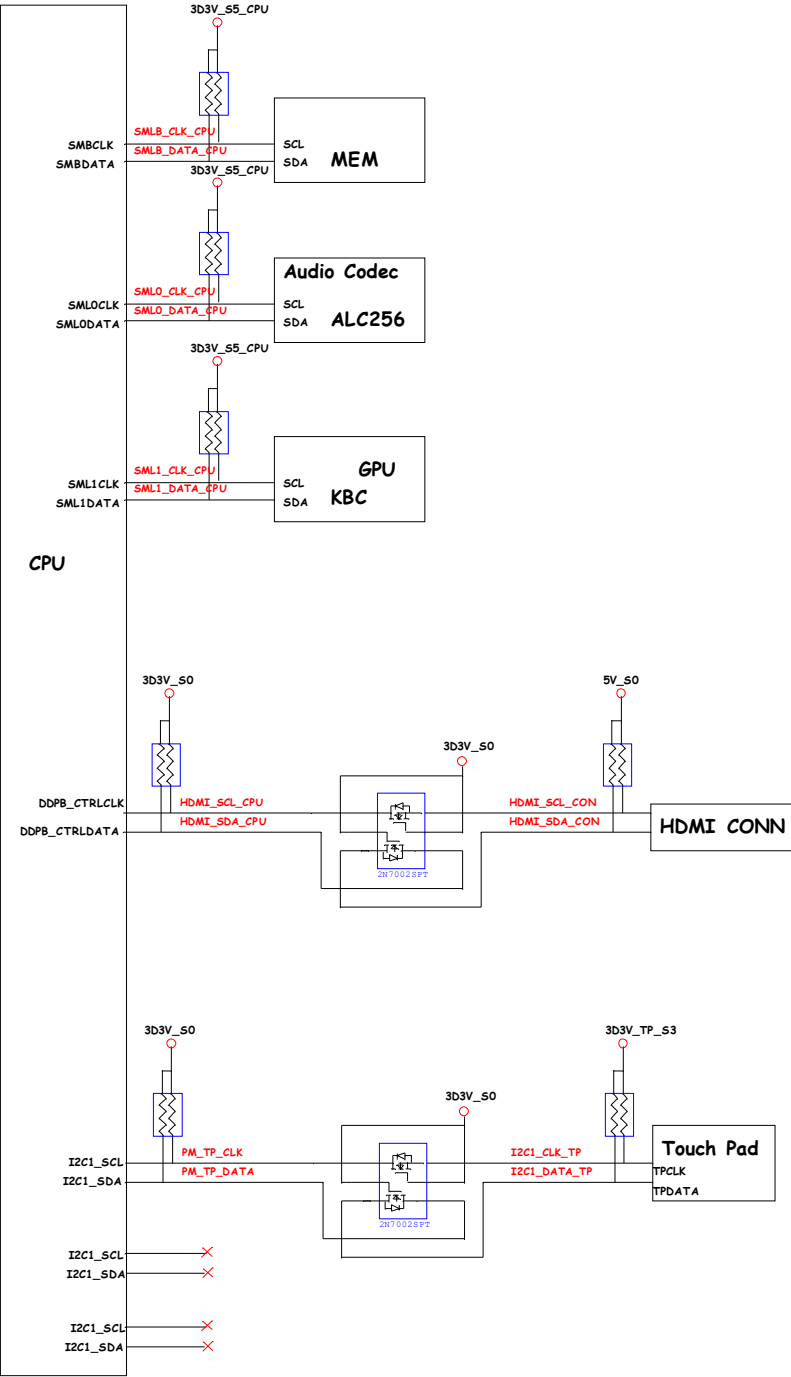


N17-Power Up Sequence

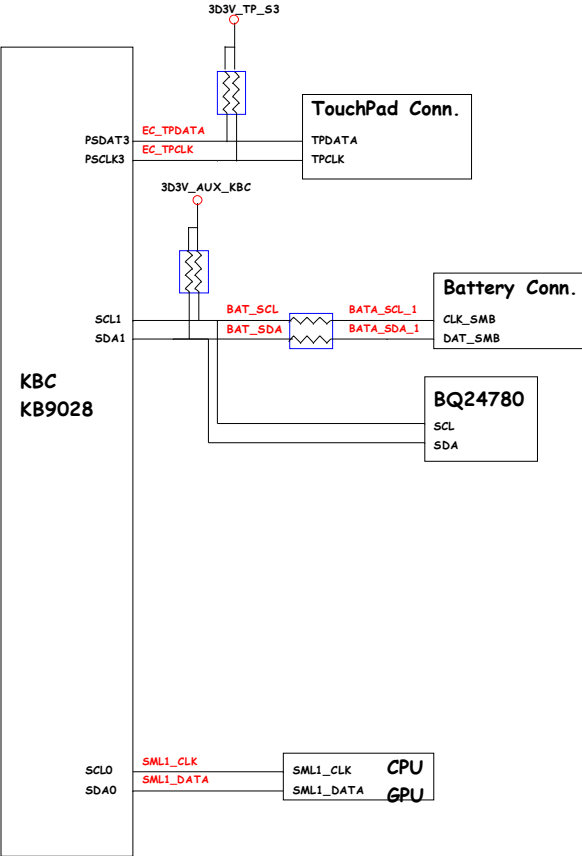




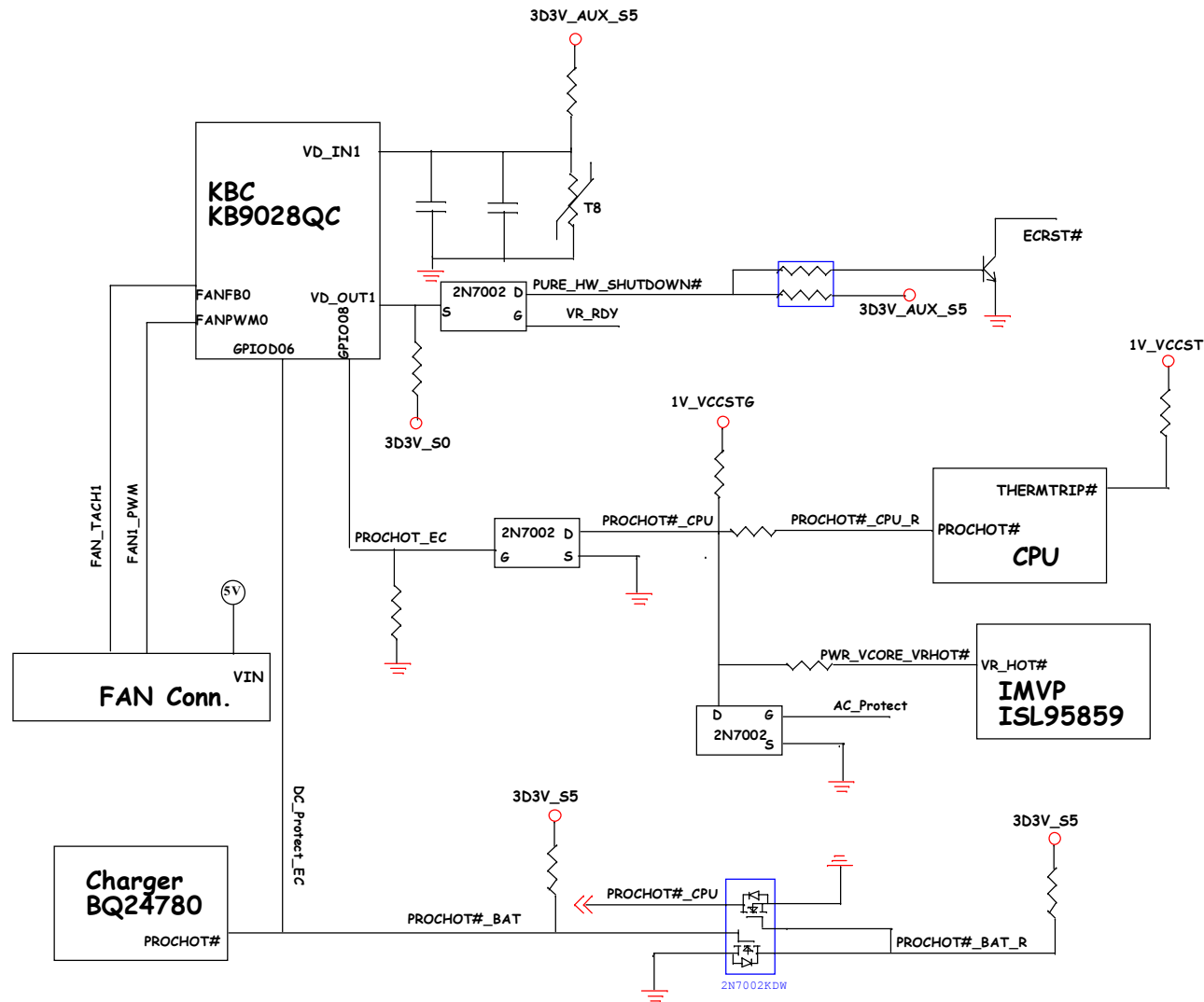
PCH SMBus/I2C Block Diagram



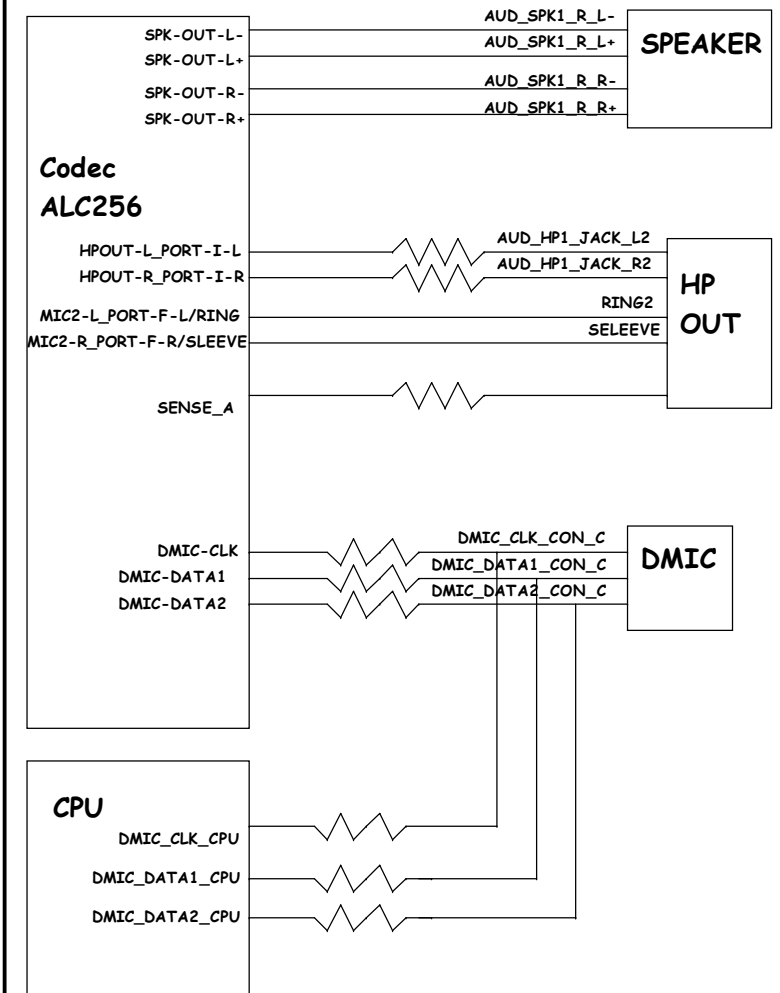
KBC SMBus/I2C Block Diagram



Thermal Block Diagram



Audio Block Diagram



CLOCK BLOCK DIAGRAM

